

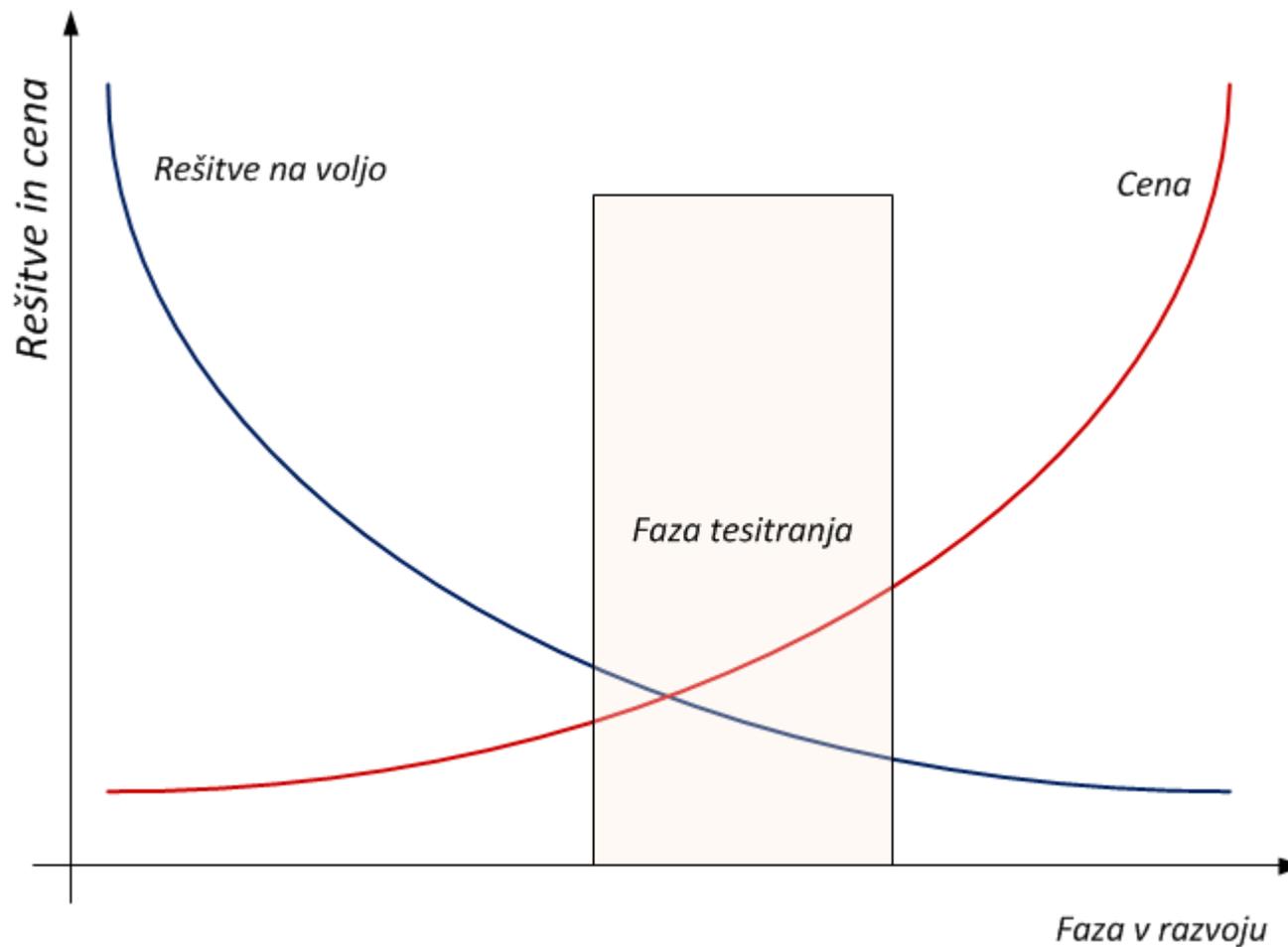
Seminar in delavnica

Načrtovanje elektronike za EMC

Elektromagnetna združljivost (EMC) 2

M. Jankovec

Doseganje EMC



Zakaj EMC?



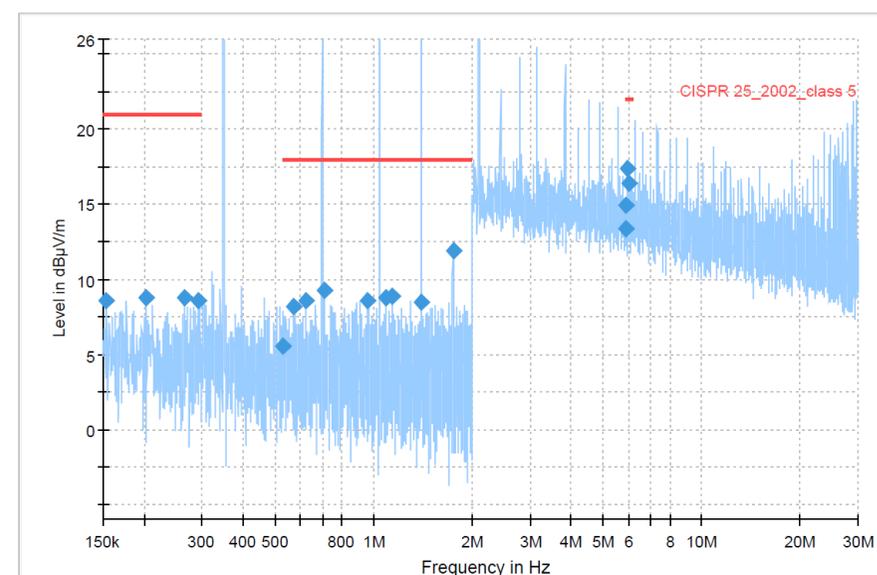
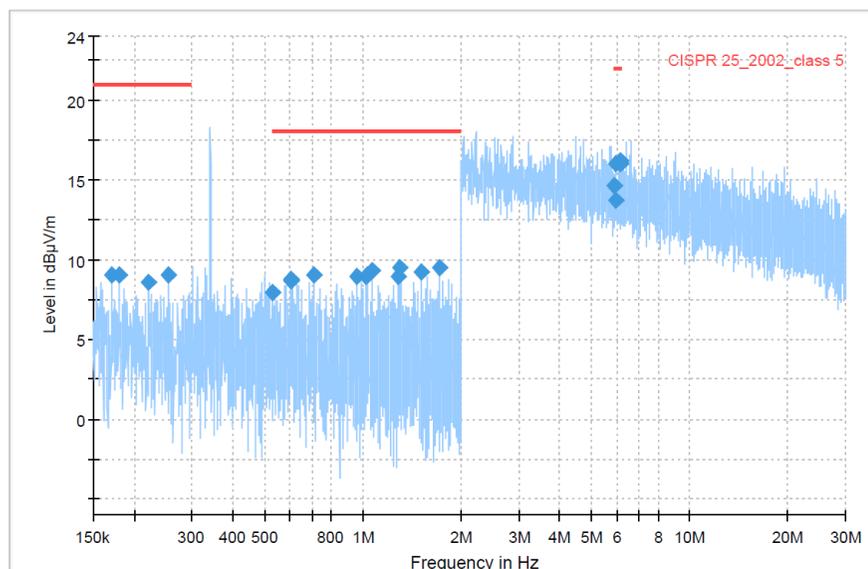
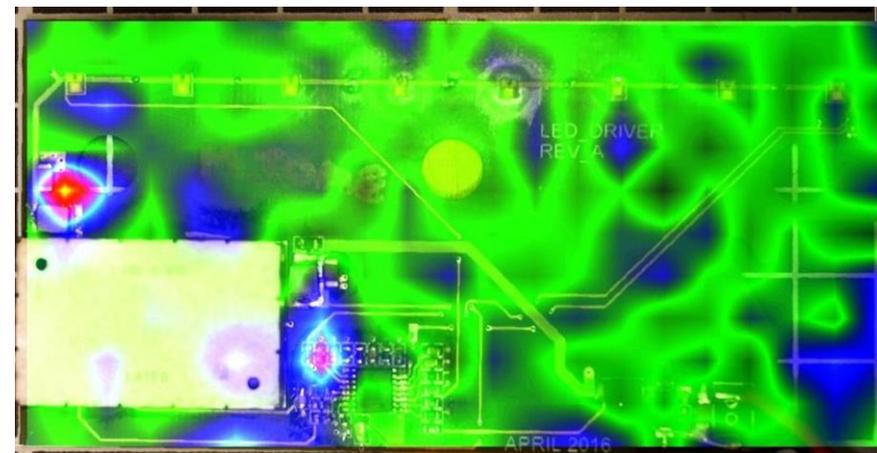
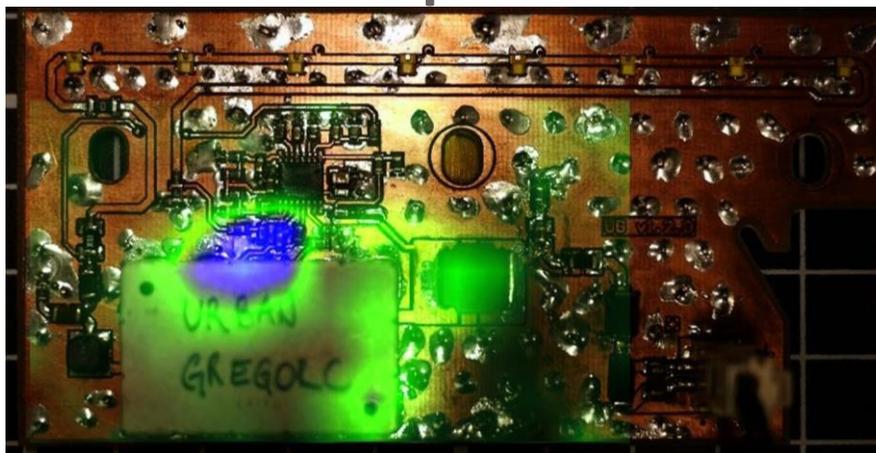
http://www.compliance-club.com/archive/old_archive/Bananaskins.htm

Resnica

"Some of the worst printed circuit boards we've seen were designed by engineers who were trying to comply with a list of EMC design rules.,,"

Todd Hubing

Resnica v praksi



Osnovna delitev EMC področja

Motnja/
emisija

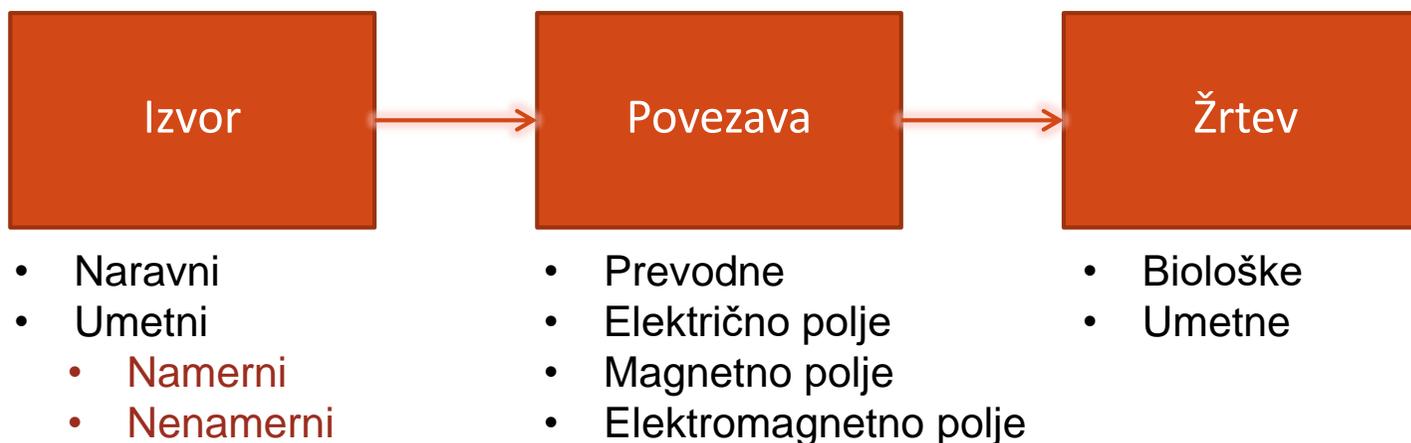
- Prevodna (Conducted)
- Sevalna (Radiated)

Odpornost/
imunost

- Prevodna (Conducted)
- Sevalna (Radiated)

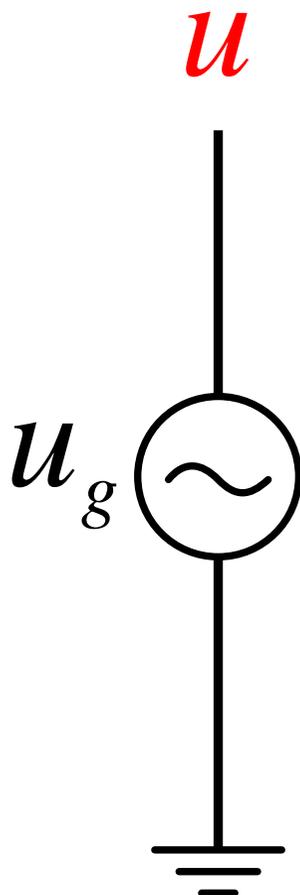
Model EMC

- Model, s katerim se prikaže elektromagnetne motnje, ima tri osnovne gradnike:
 - **izvor** sevanja (motenj),
 - **sprejemnik**,
 - **povezava** med izvorom in sprejemnikom.

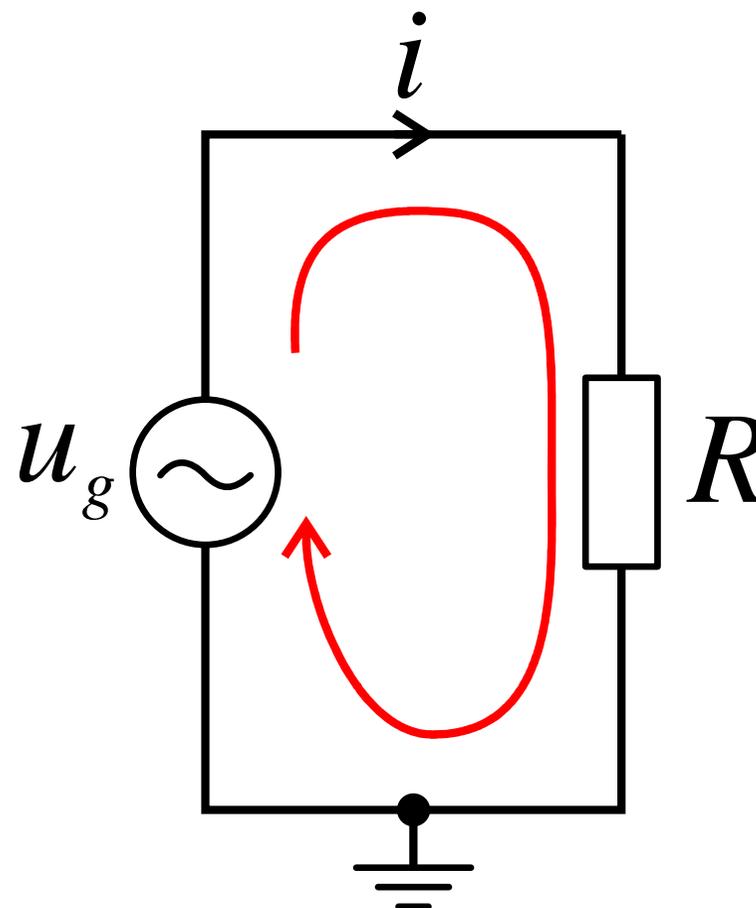


Izvori motenj

VF potenciali

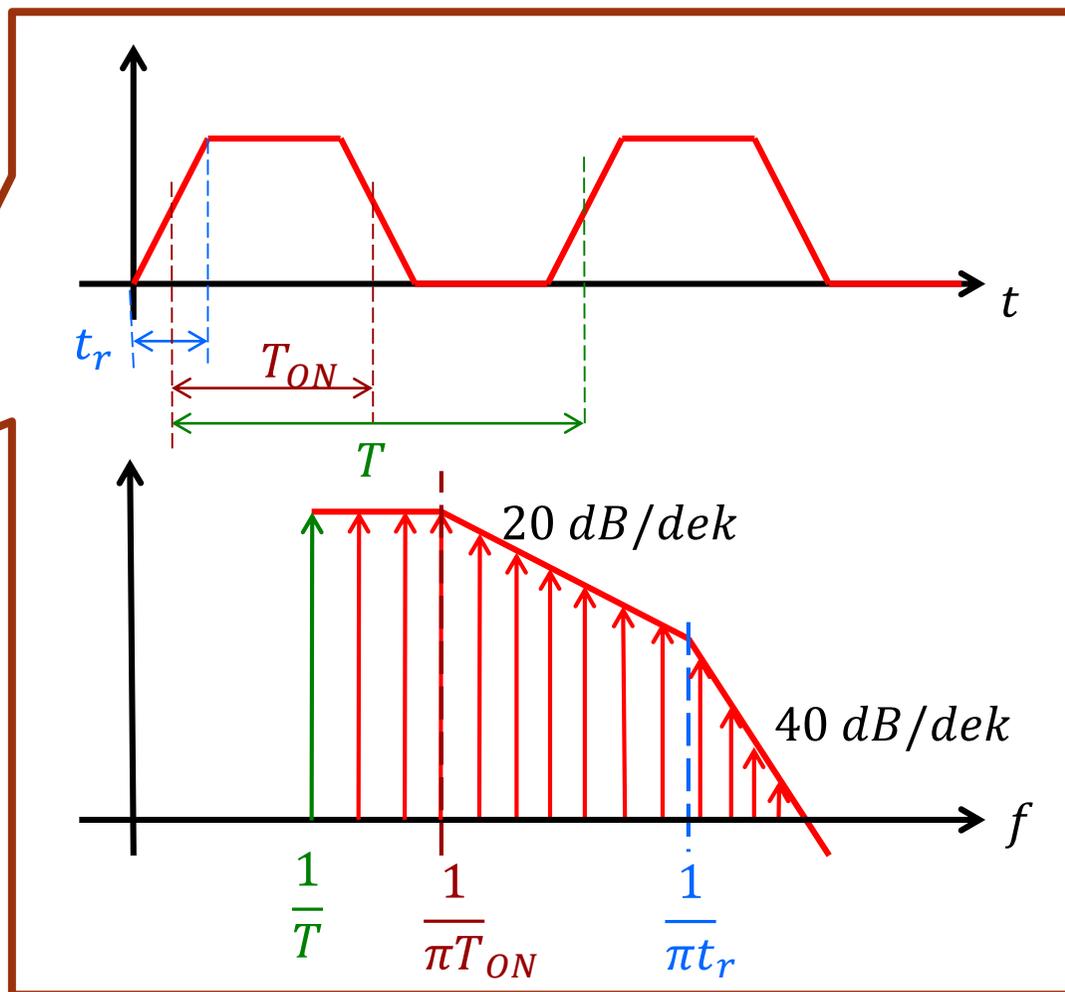


VF tokovne zanke

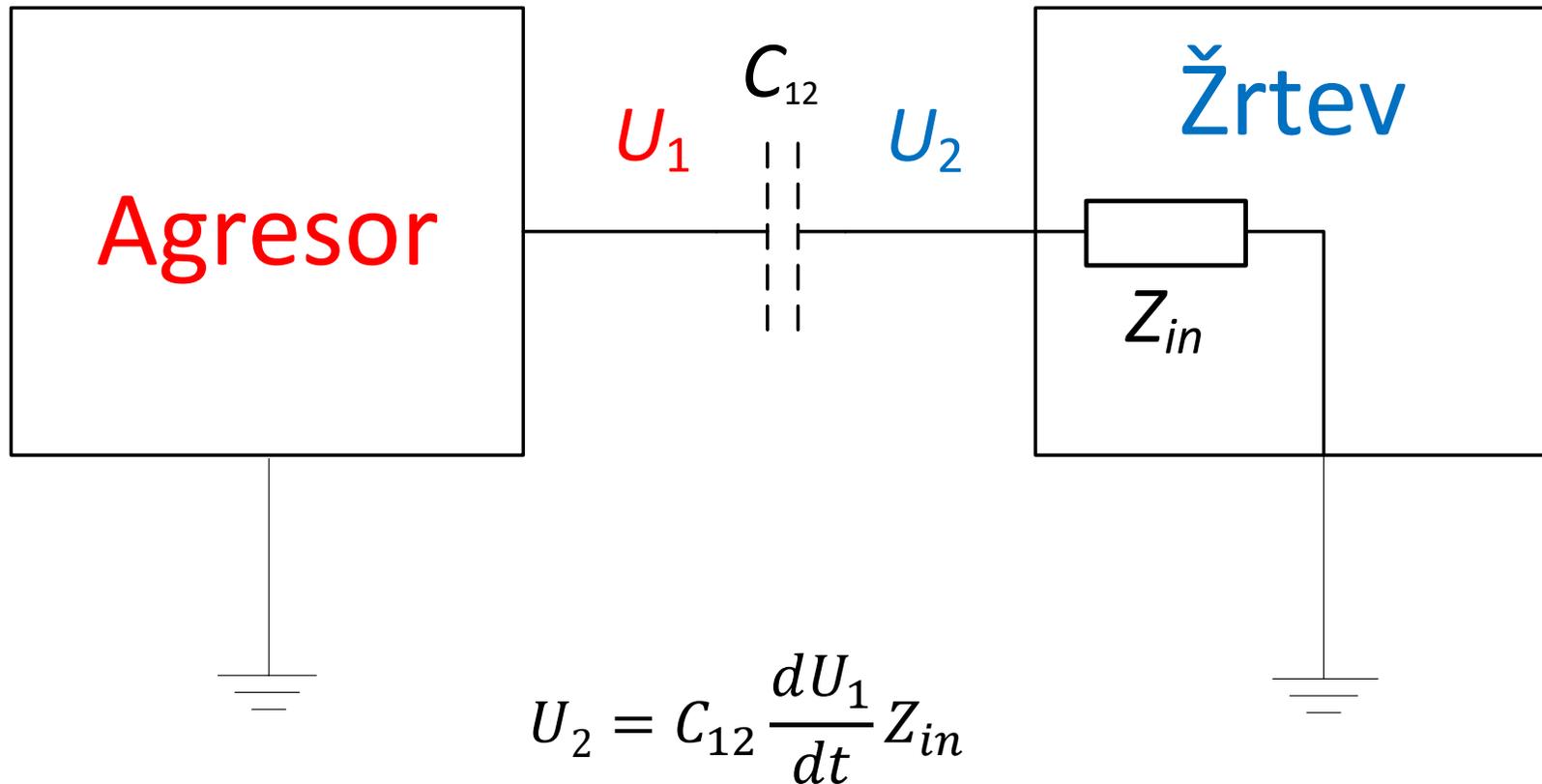


Izvori motenj

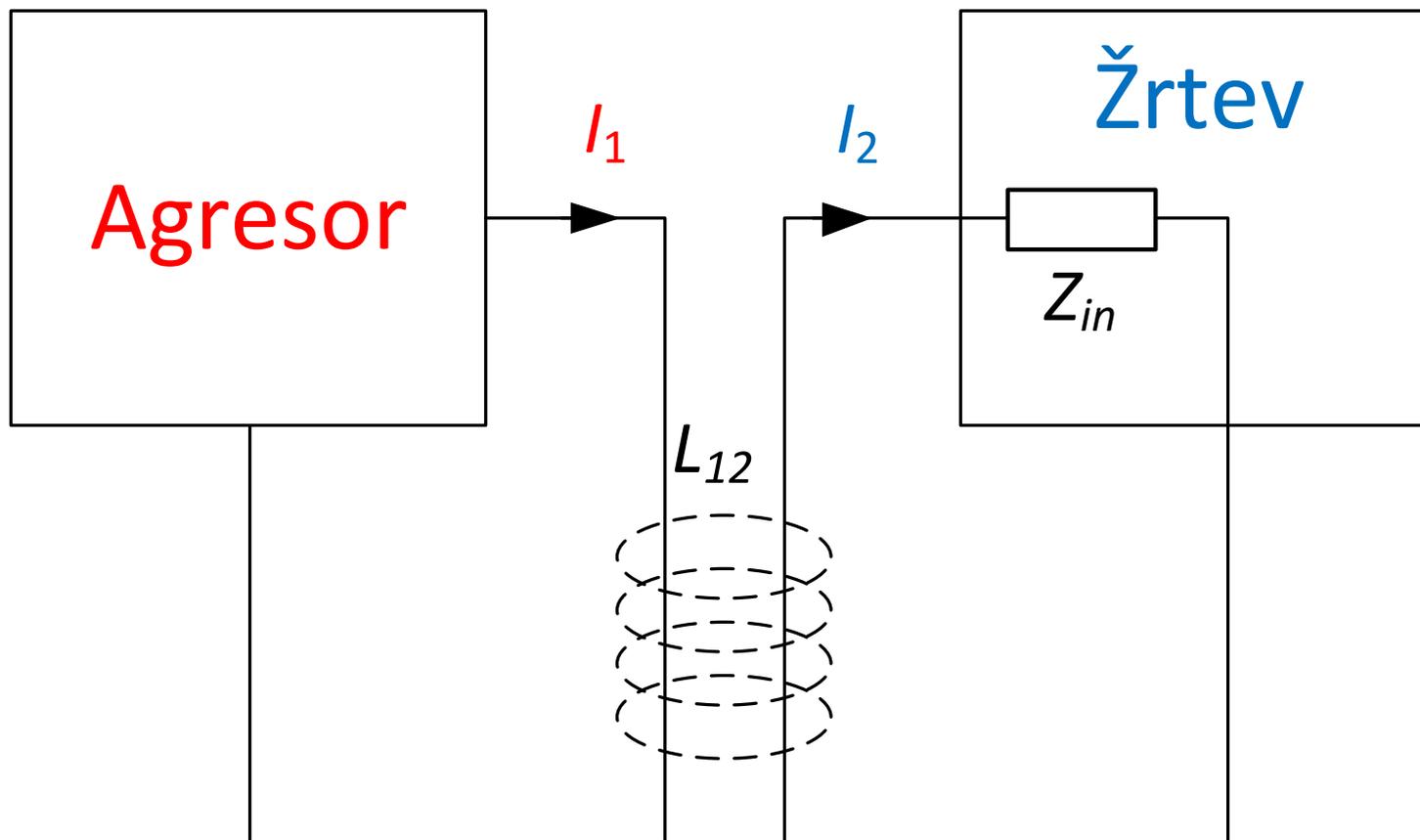
- Vprašanja:
 - Kje teče tok?
 - Kje so napetostna nihanja?
 - Kakšna je frekvenčna vsebina toka, napetosti?



Kapacitivni prenos motenj (prek E polja)

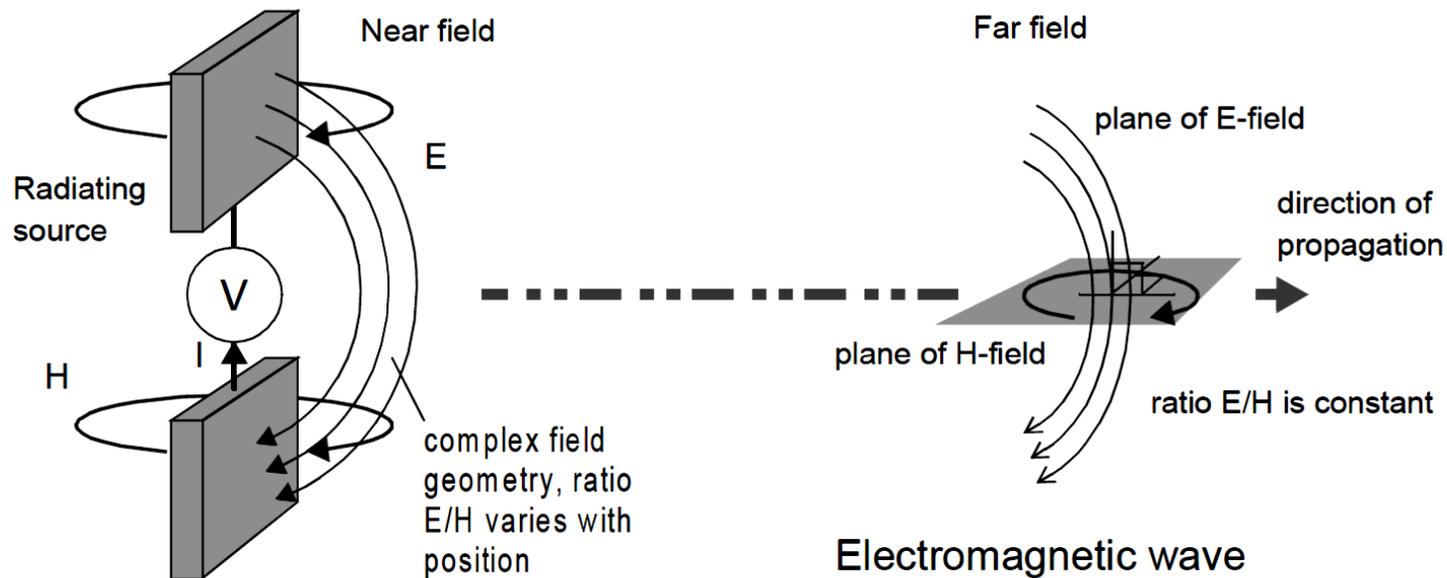
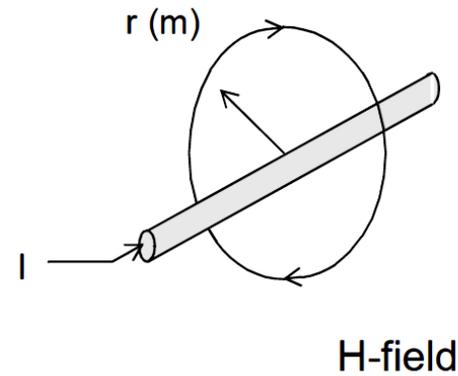
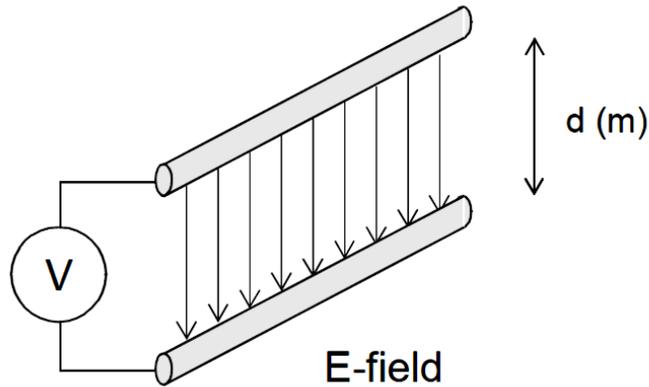


Induktivni prenos motenj (prek H polja)

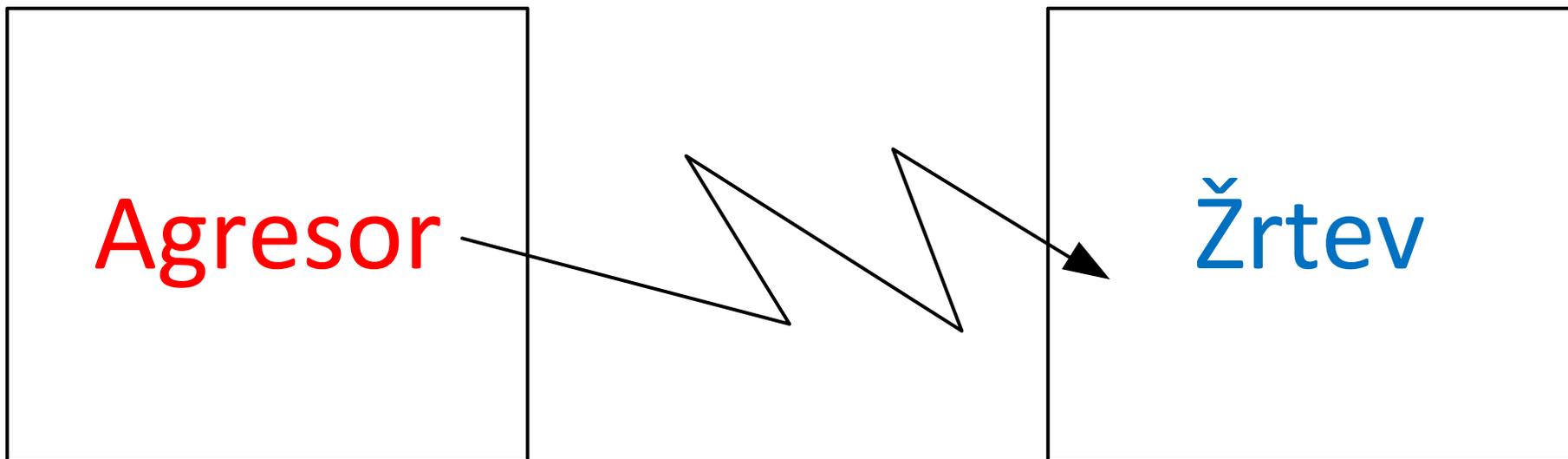


$$I_2 = -L_{12} \frac{dI_1}{dt} \frac{1}{Z_{in}}$$

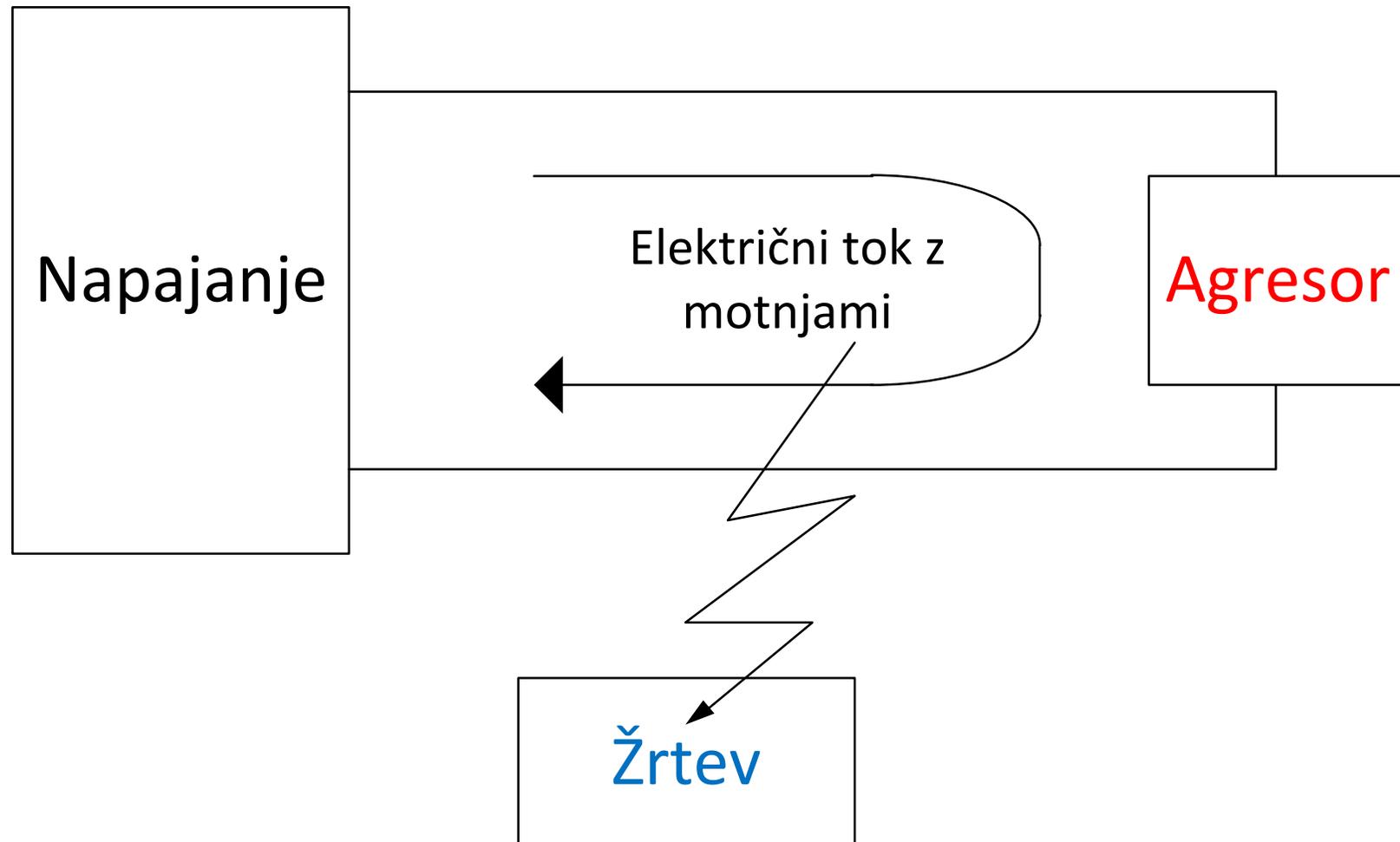
Prenos močnje preko EM polja



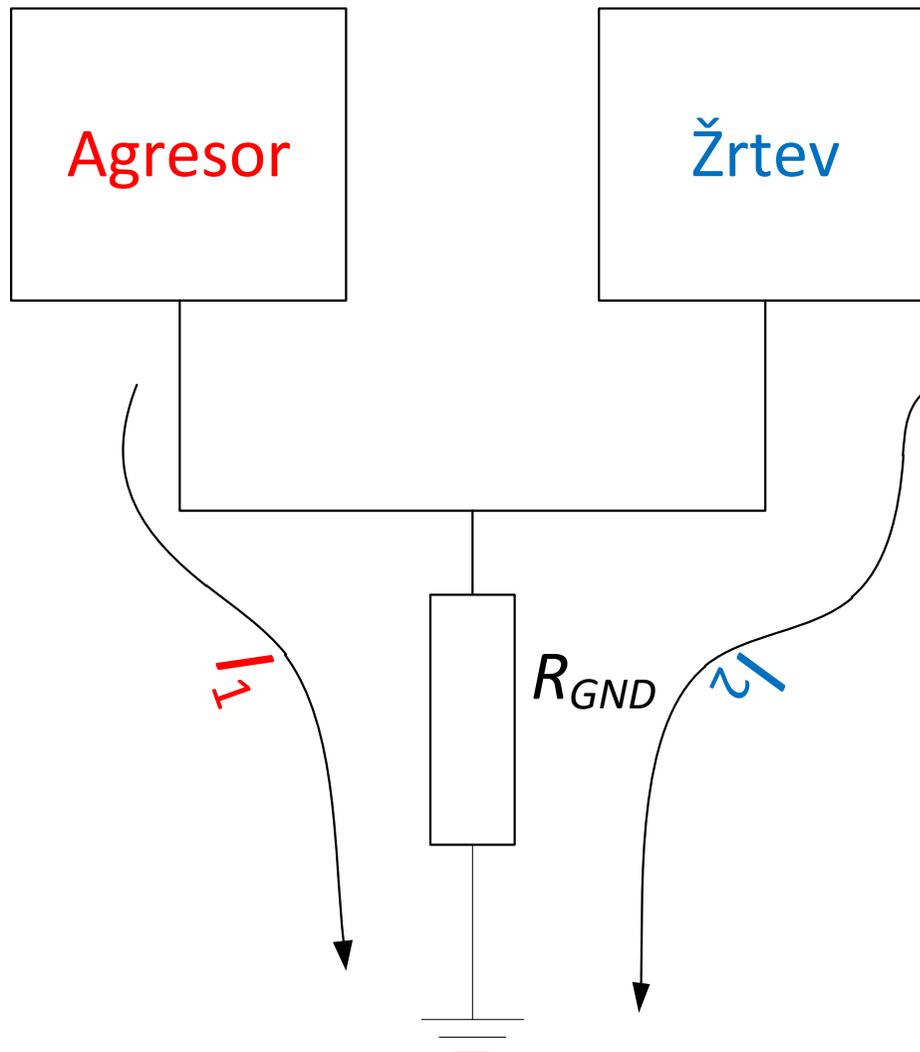
Prenos motnje preko EM polja



Prevodno-sevalni prenos motenj



Prevodni prenos motenj preko skupne mase

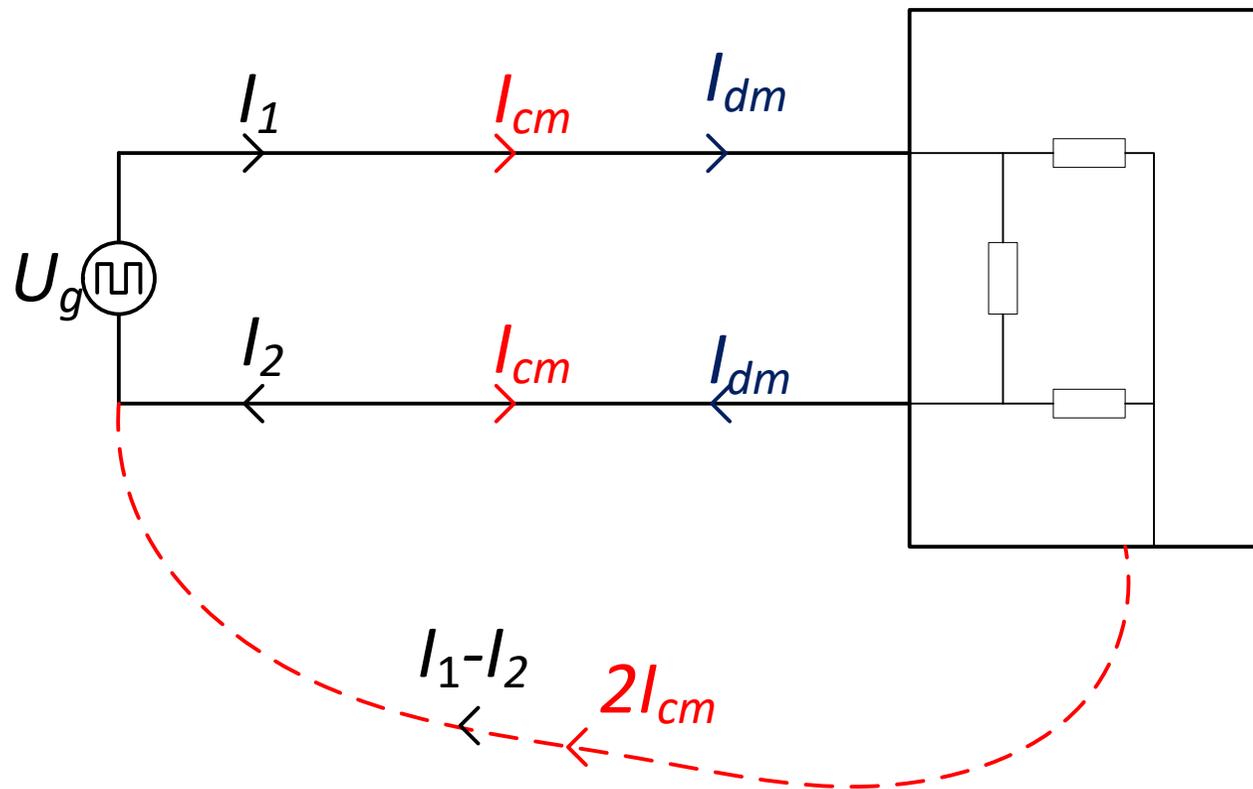


+

$$U_{GND} = R_{GND} * (I_1 + I_2)$$

-

Diferencialni in sofazni signali



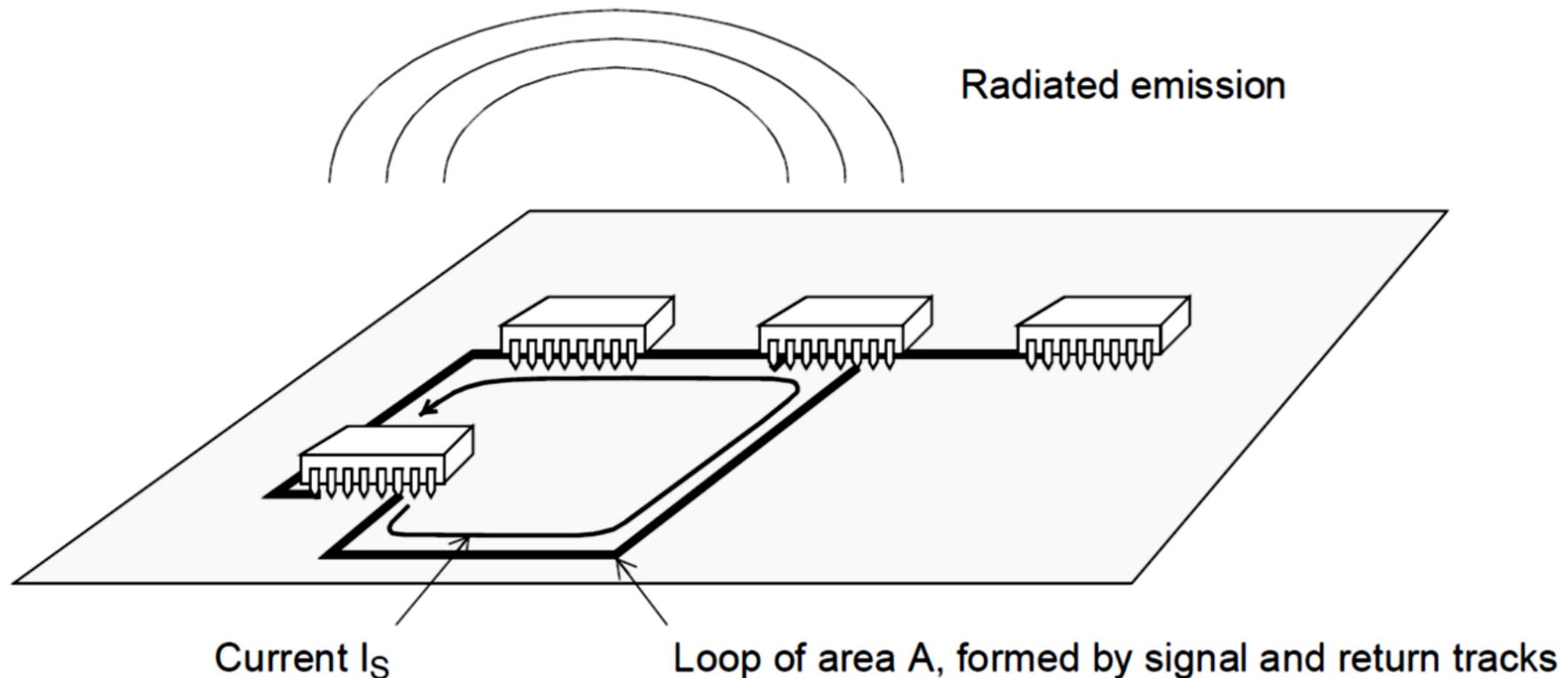
$$I_1 = I_{dm} + I_{cm}$$

$$I_2 = I_{dm} - I_{cm}$$

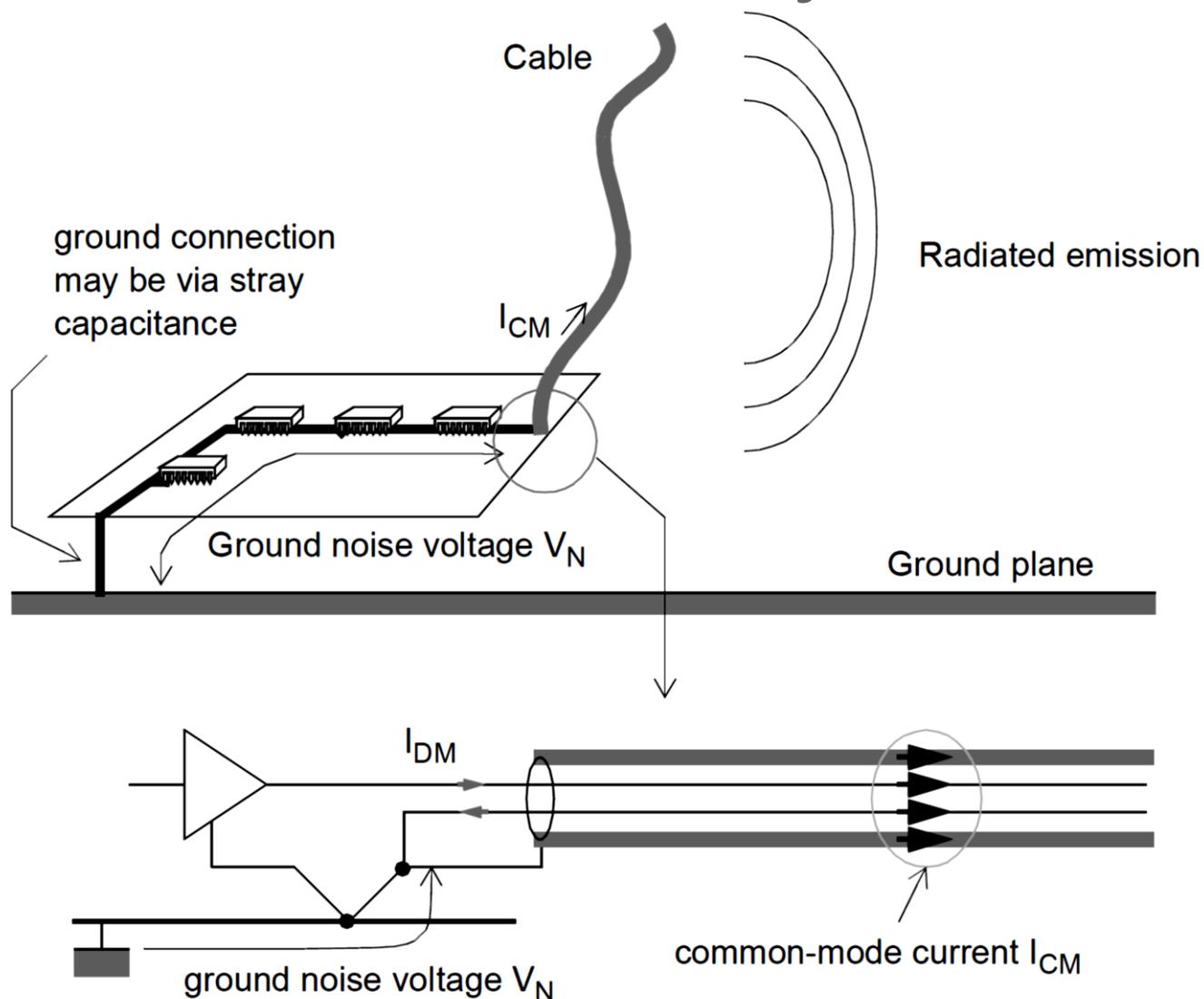
$$I_{dm} = \frac{I_1 + I_2}{2}$$

$$I_{cm} = \frac{I_1 - I_2}{2}$$

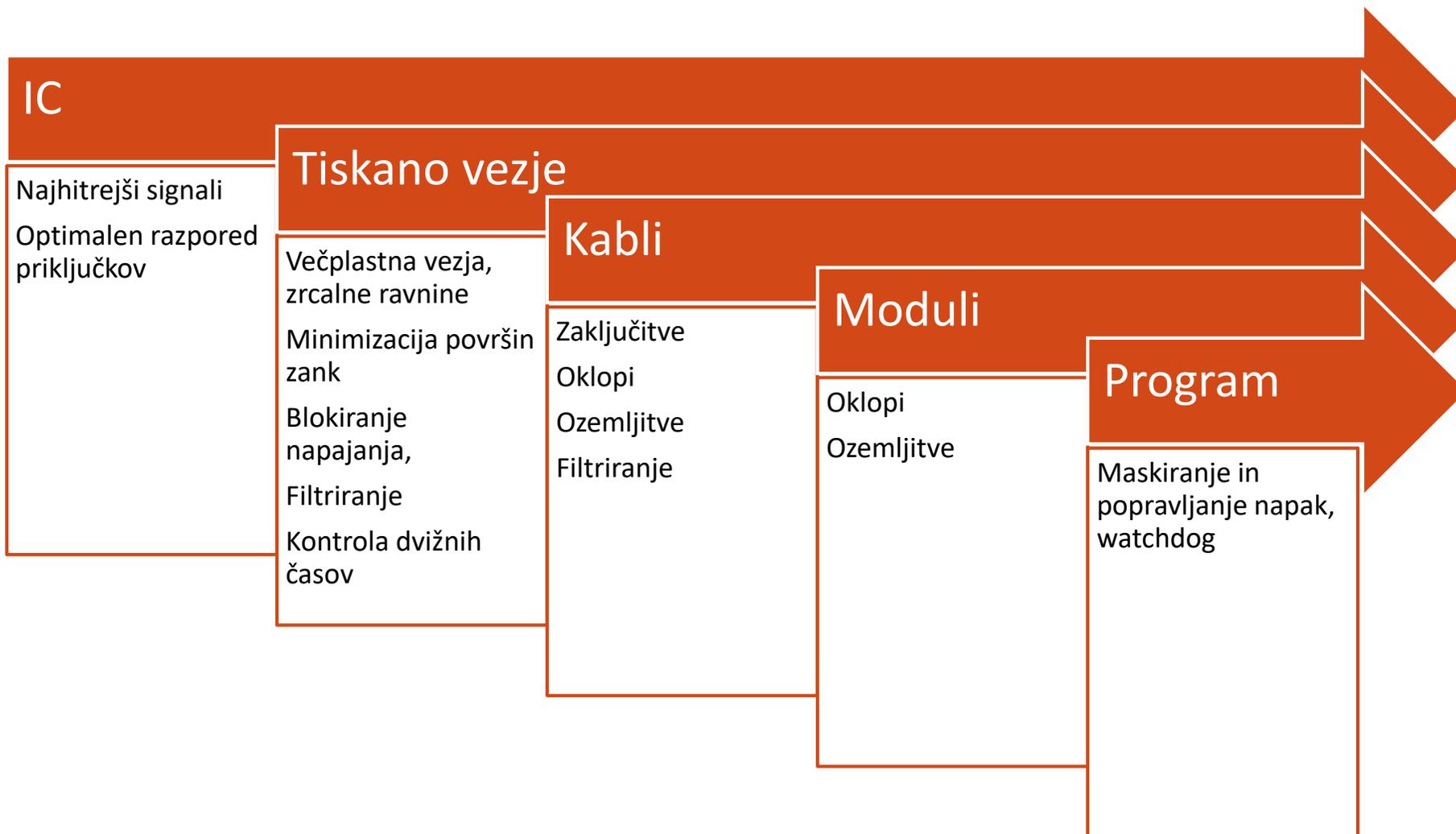
Primer vira diferencialne motnje na TIV



Primer vira sofazne motnje na TIV



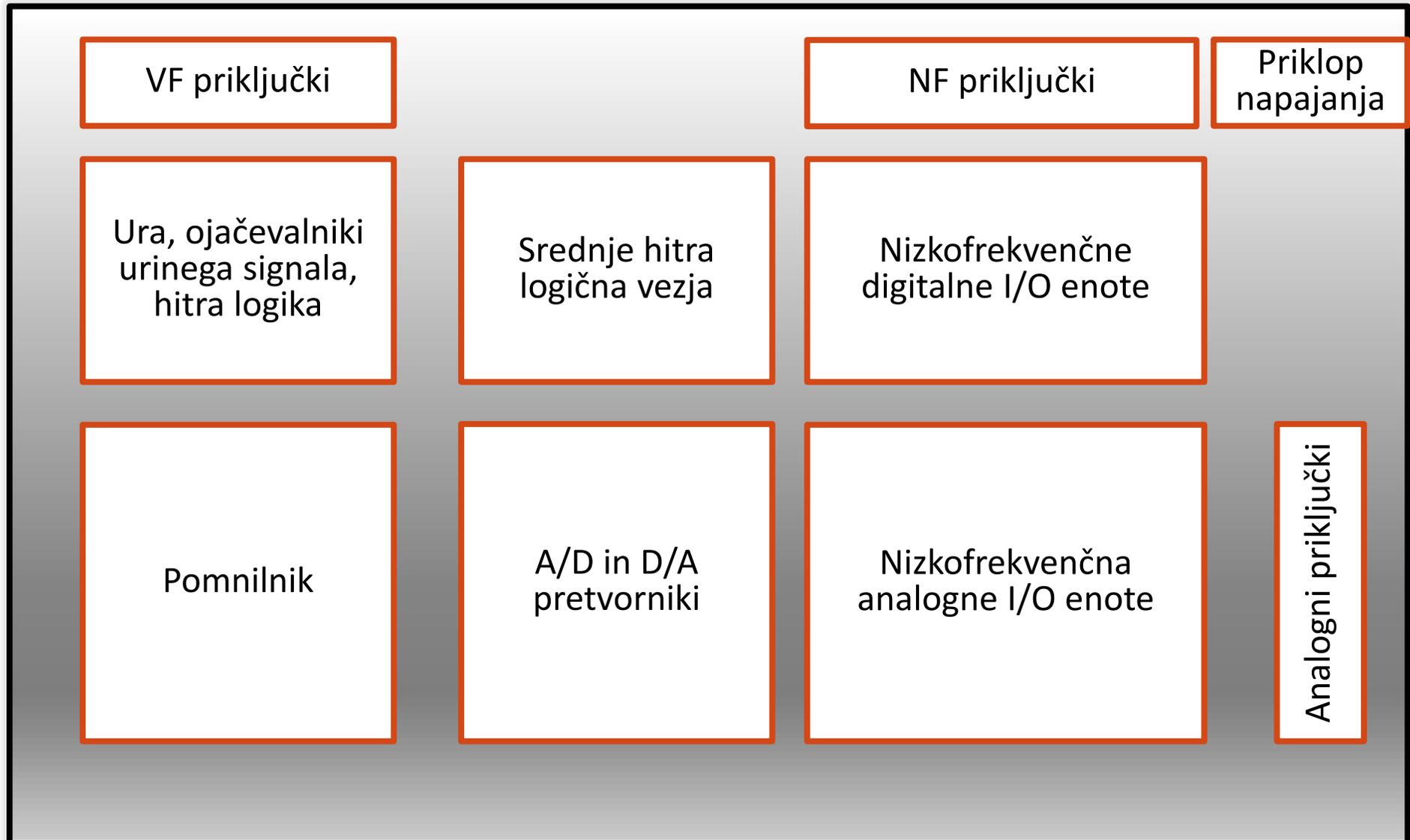
Nivoji zaščite EMI



Načrtovanje tiskanega vezja



Postavitev



Priporočila za postavitve priključkov

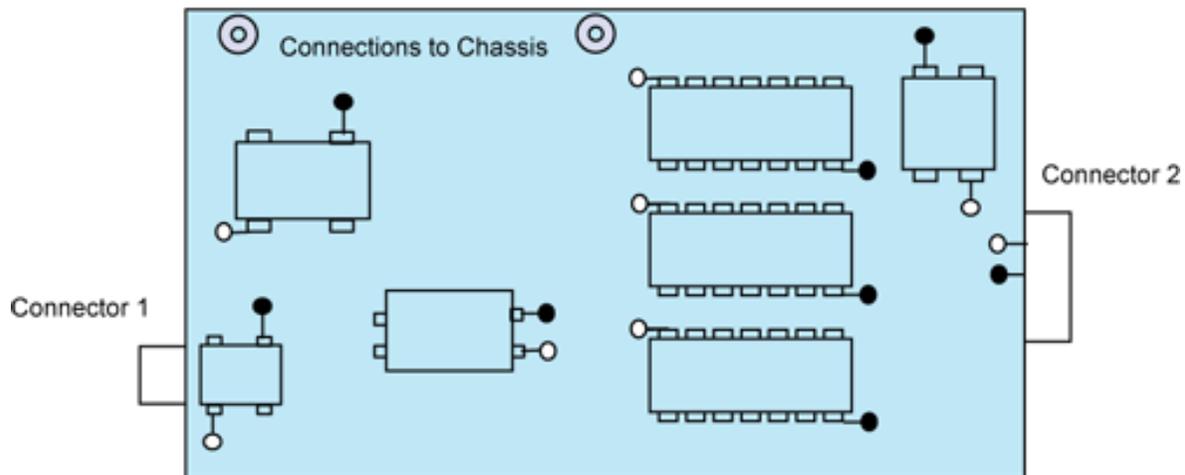
- Vsa komunikacija iz istega čipa naj poteka preko enega skupnega priključka
 - Sofazni tokovi so mnogo lažje obvladljivi v vodnikih, ki so del istega priključka in kabla.
- Čip, katerega komunikacija je povezana na priključek, naj bo čim bližje tega priključka
 - S tem ohranimo povezave na TIV kratke. Če je linija daljša, potem je bolj verjetno, da se nanjo sklapljajo motnje iz TIV.

Priporočila za postavitve priključkov

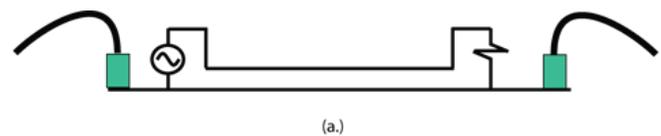
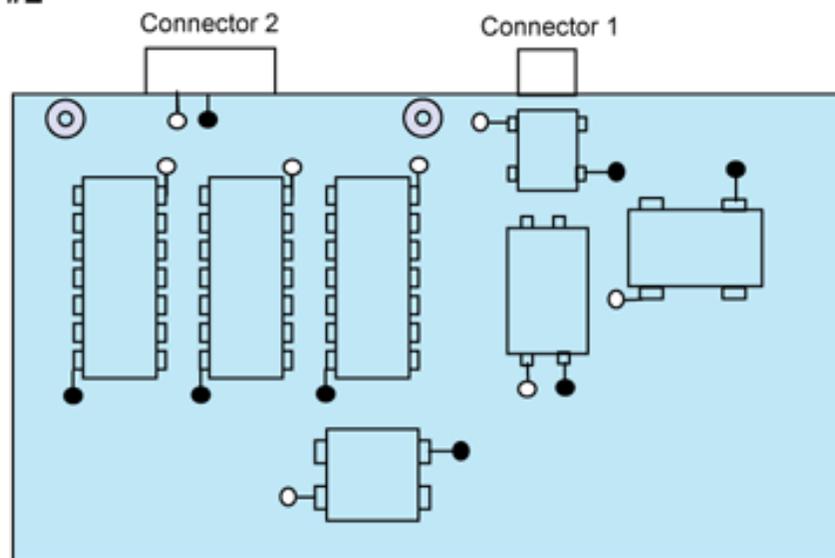
- Komponenta, ki nima povezav na priključek, naj ne bo preblizu priključkov.
 - Tipično naj bo oddaljena vsaj 2 cm, odvisno od primera. Na ta način omejimo motnje drugih elementov, da se ne sklapijajo na priključek.
- Postavite priključke skupaj na eno stran ali v en vogal TIV
 - Na ta način jih je lažje ohranjati na istem potencialu
 - Ne postavite hitrih vezij med priključke

Primer

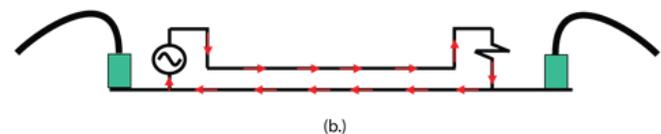
LAYOUT #1



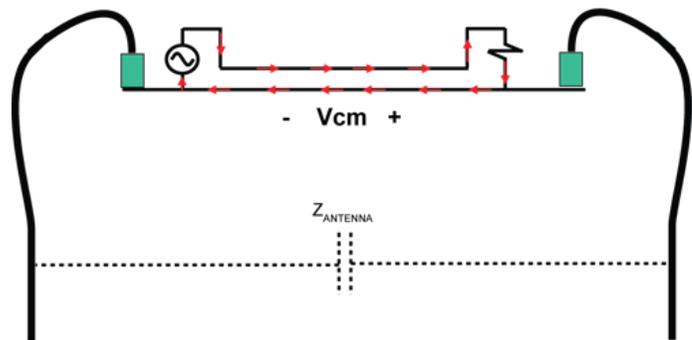
LAYOUT #2



(a.)



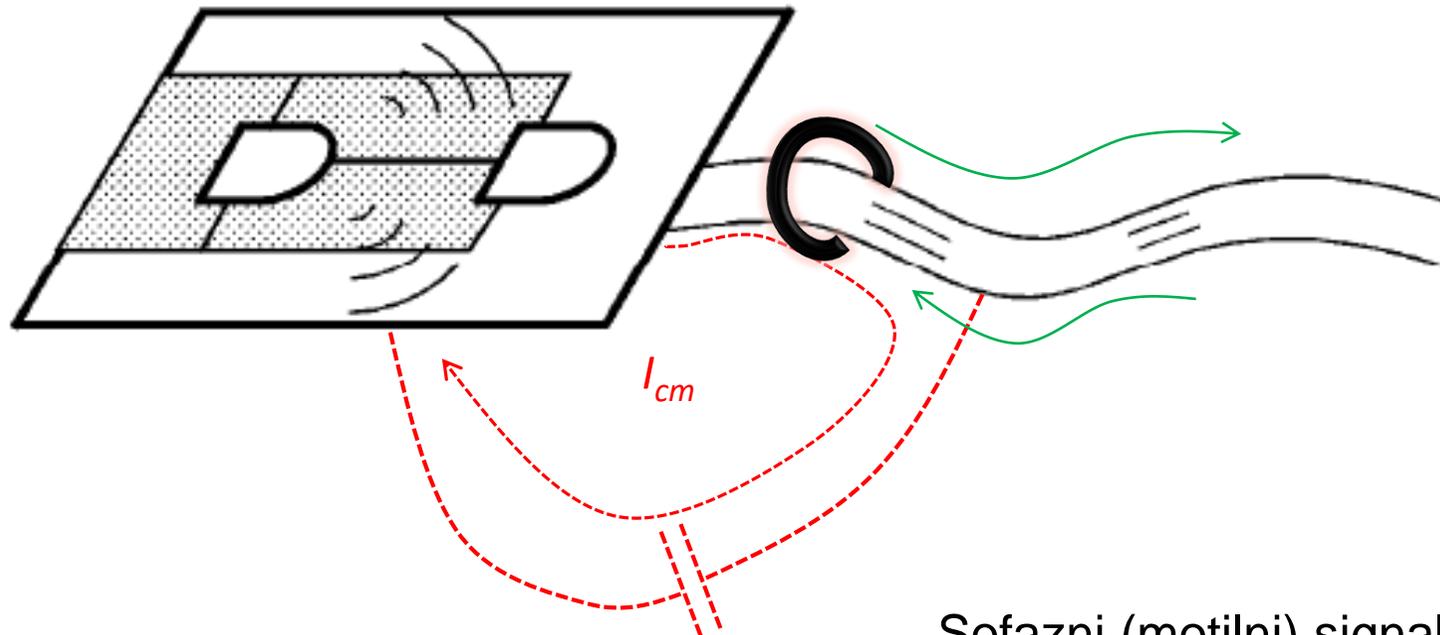
(b.)



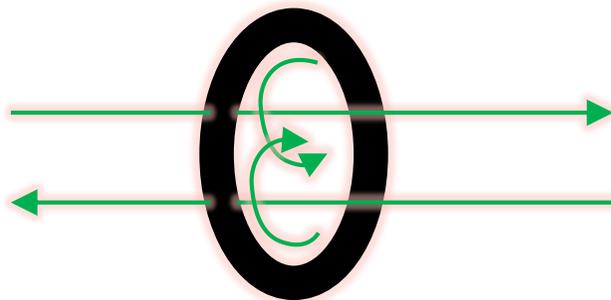
(c.)

http://www.learnemc.com/tutorials/PCB_Layout/PCB_Layout.html

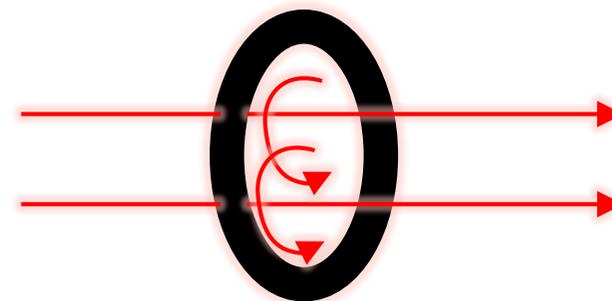
Feritni obroček



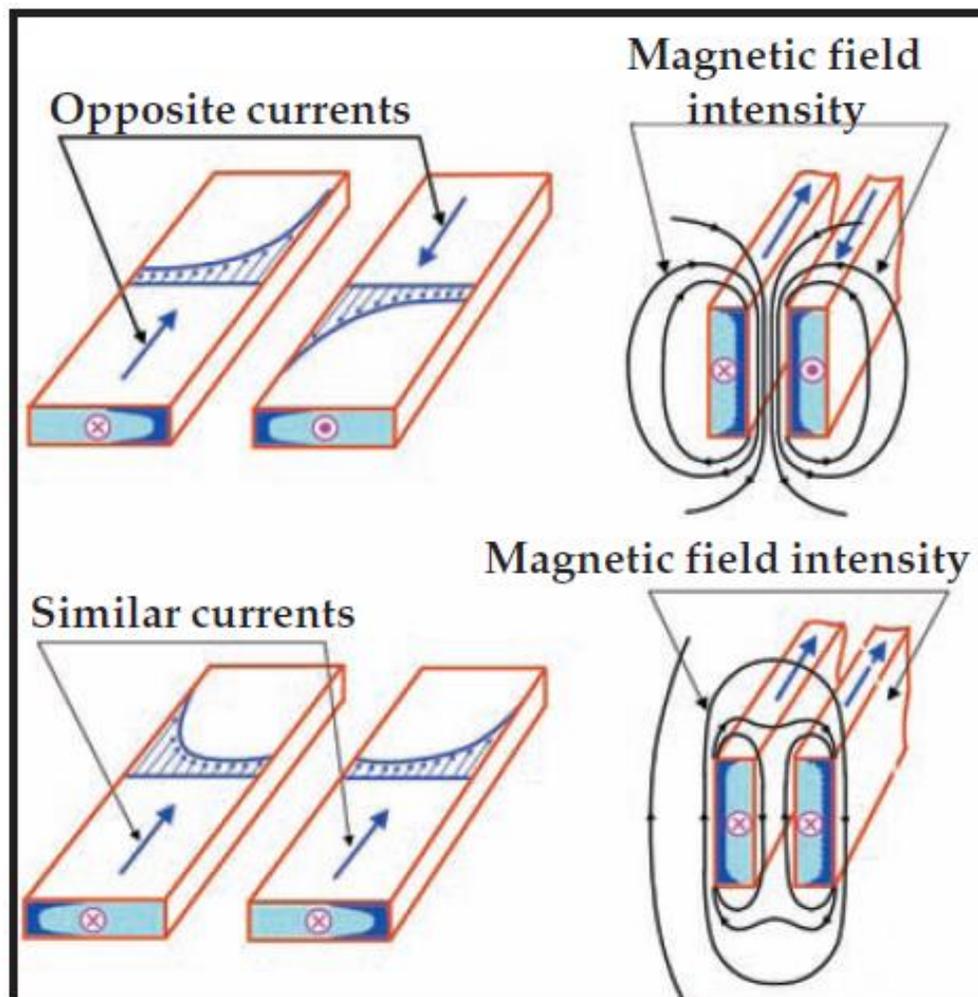
Diferencialni (koristni) signali



Sofazni (motilni) signali



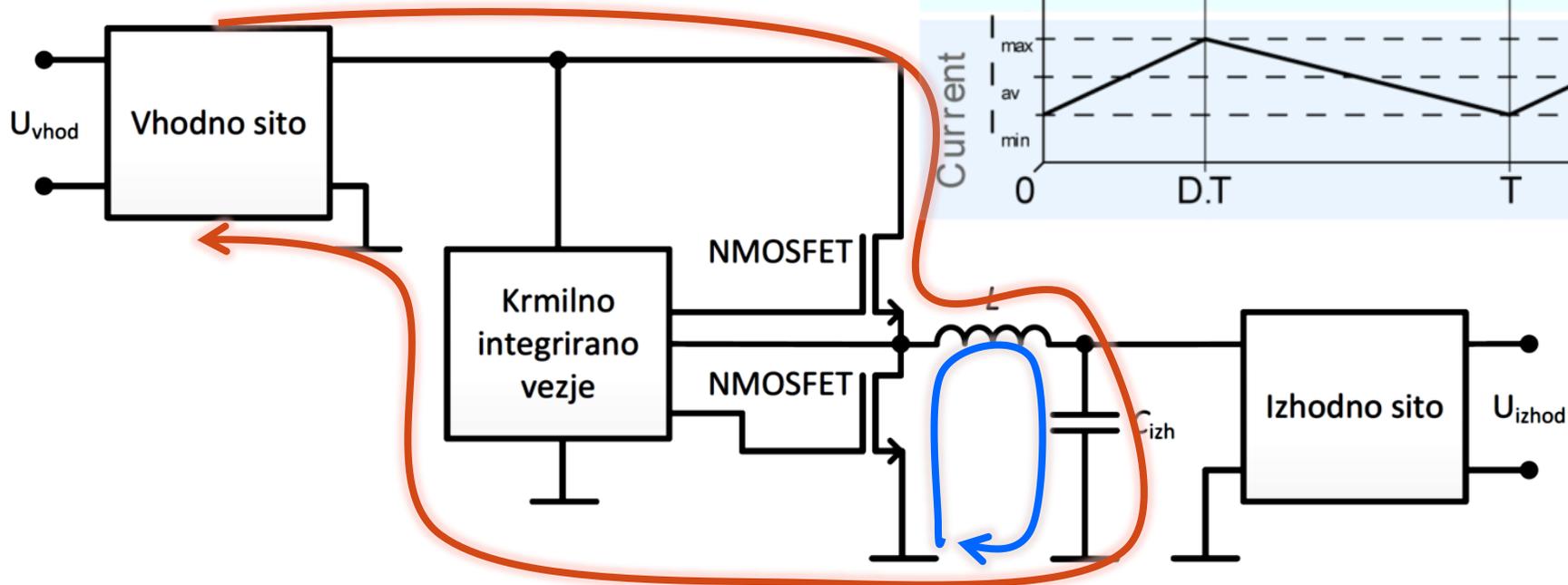
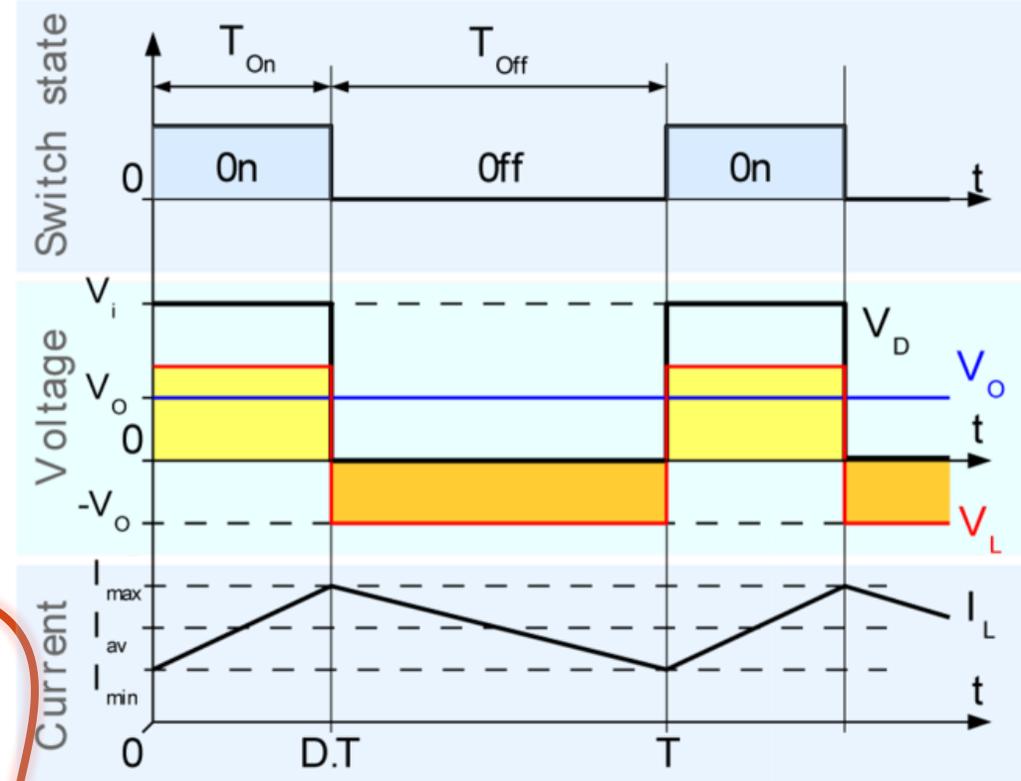
Tokovne zanke na tiskanem vezju



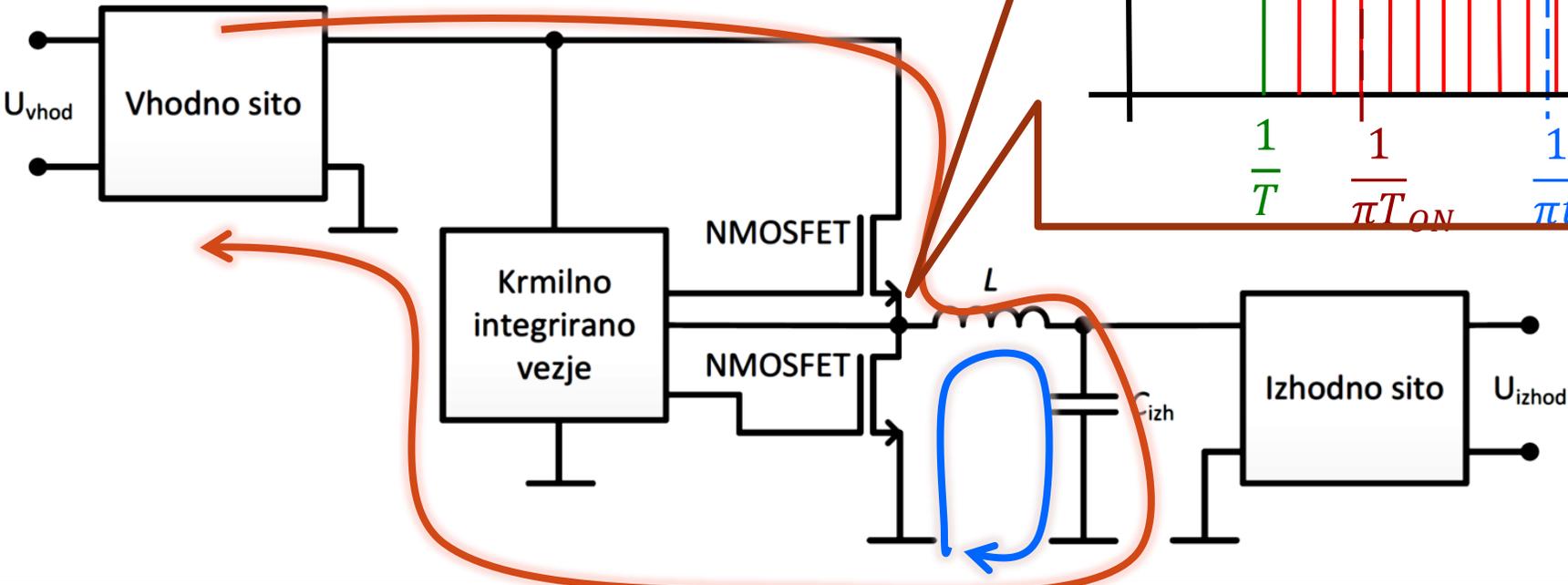
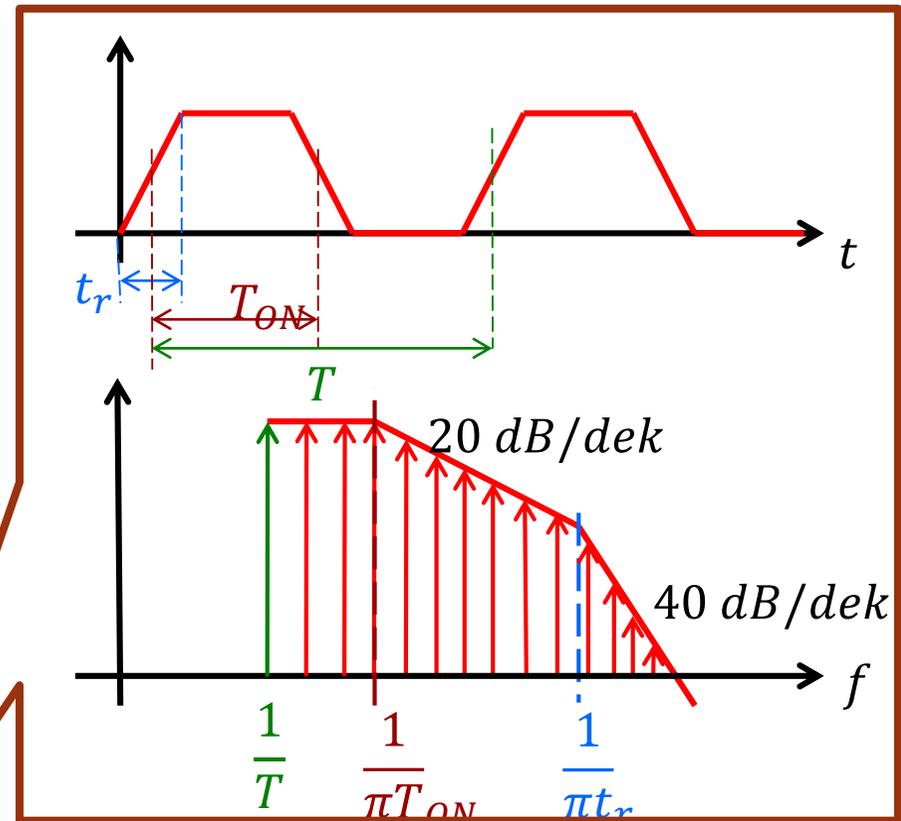
Izkustvena pravila

- Visokofrekvenčni tok bo vedno tekel blizu zunanjega roba vodnika
- Pri 35 μ m debeli bakreni liniji se kožni pojav pojavi že pri 3.5 MHz
- Kožni pojav zmanjšuje efektivno induktivnost
- Žica z manjšim premerom ali vije imajo večjo induktivnost
- Širše linije imajo nižjo induktivnost
- Diferencialni visokofrekvenčni tokovi tečejo po notranjem robu diferencialnega vodnika in tako znižujejo induktivnost
- Izsevana energija je sorazmerna površini zanke, po kateri teče tok
- Visokofrekvenčno magnetno polje bo vedno našlo poz iz naprave in sevalo v daljnem polju, zato pri načrtovanju skušamo vedno zmanjšati zanke, kolikor je mogoče.

Pretvornik navzdol



Pretvornik navzdol

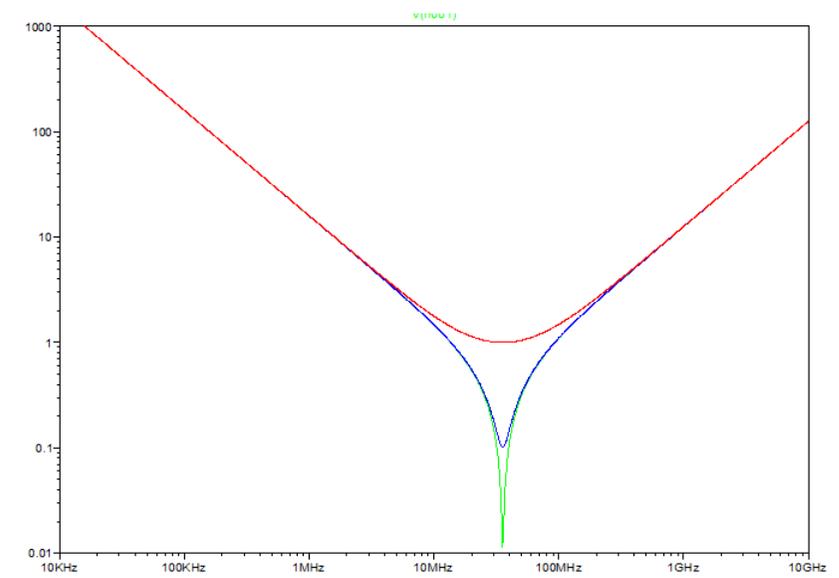
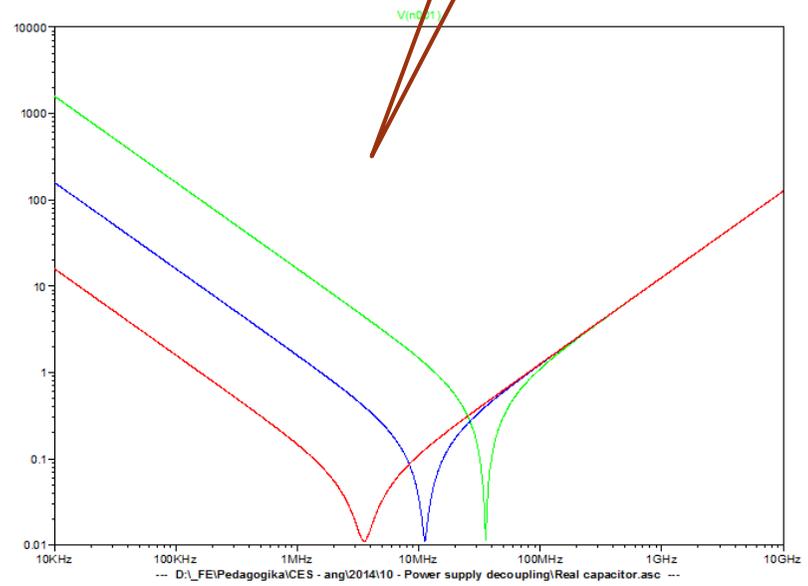
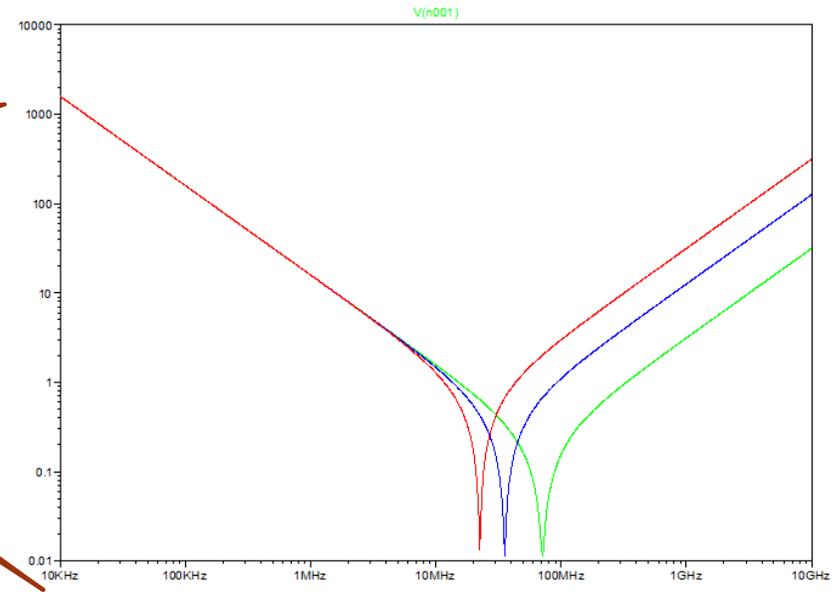
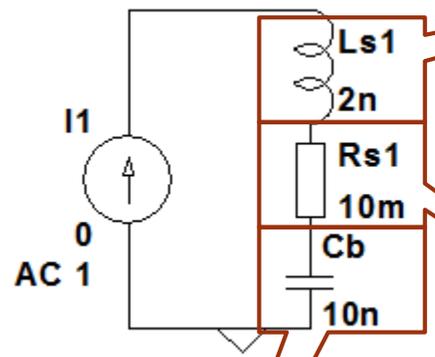


Blokiranje s kondenzatorji

- Vzpostavitev dodatne visokofrekvenčne nizkoimpedančne poti za spreminjajoče tokove s pomočjo kondenzatorja
 - Pot naj se čim manj sklaplja z glavnimi napajalnimi linijami
 - Pot naj ima čim nižjo impedanco
 - Čim krajše linije
 - Uporaba več vzporedno vezanih kondenzatorjev

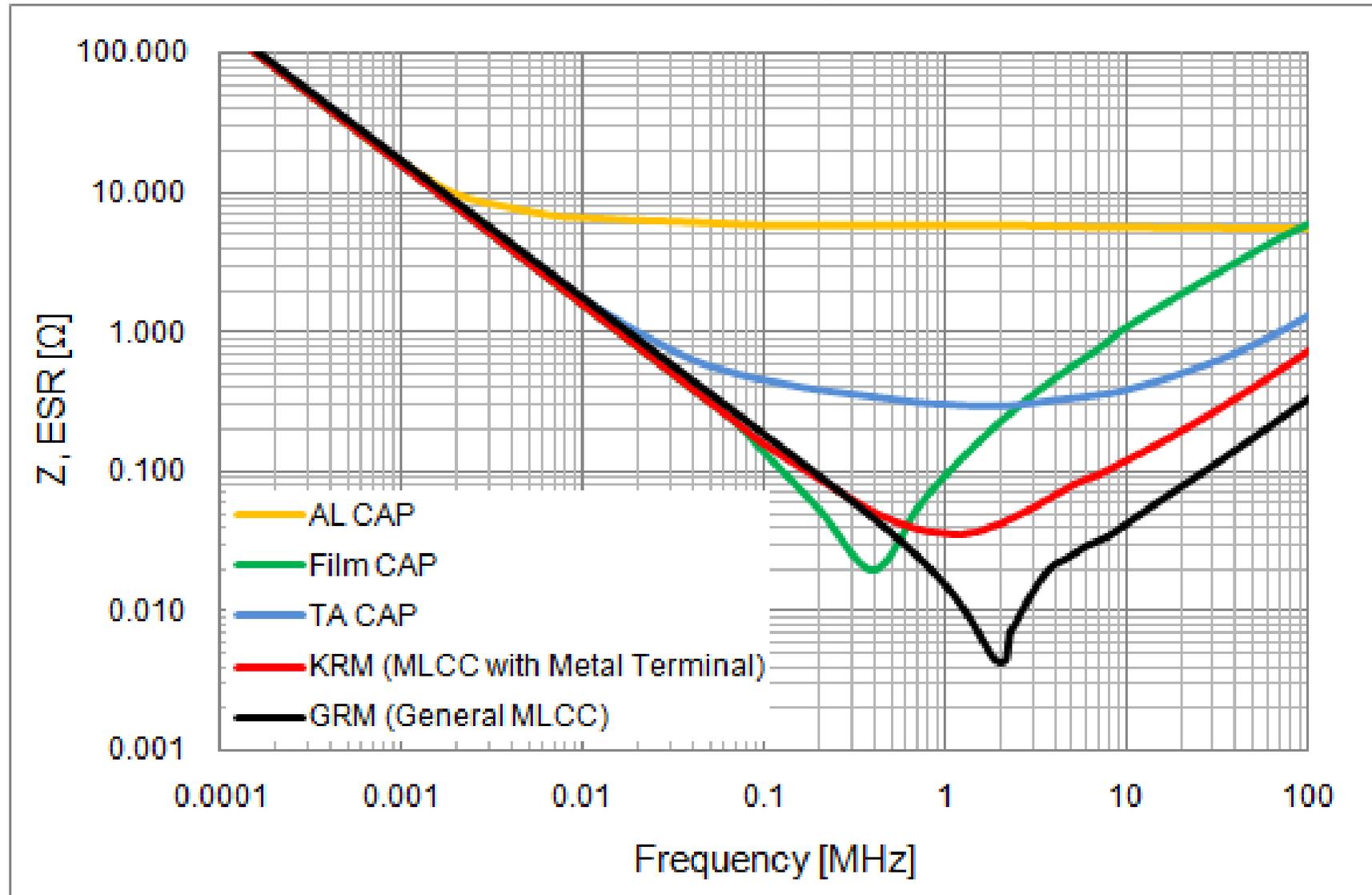


Realni kondenzator

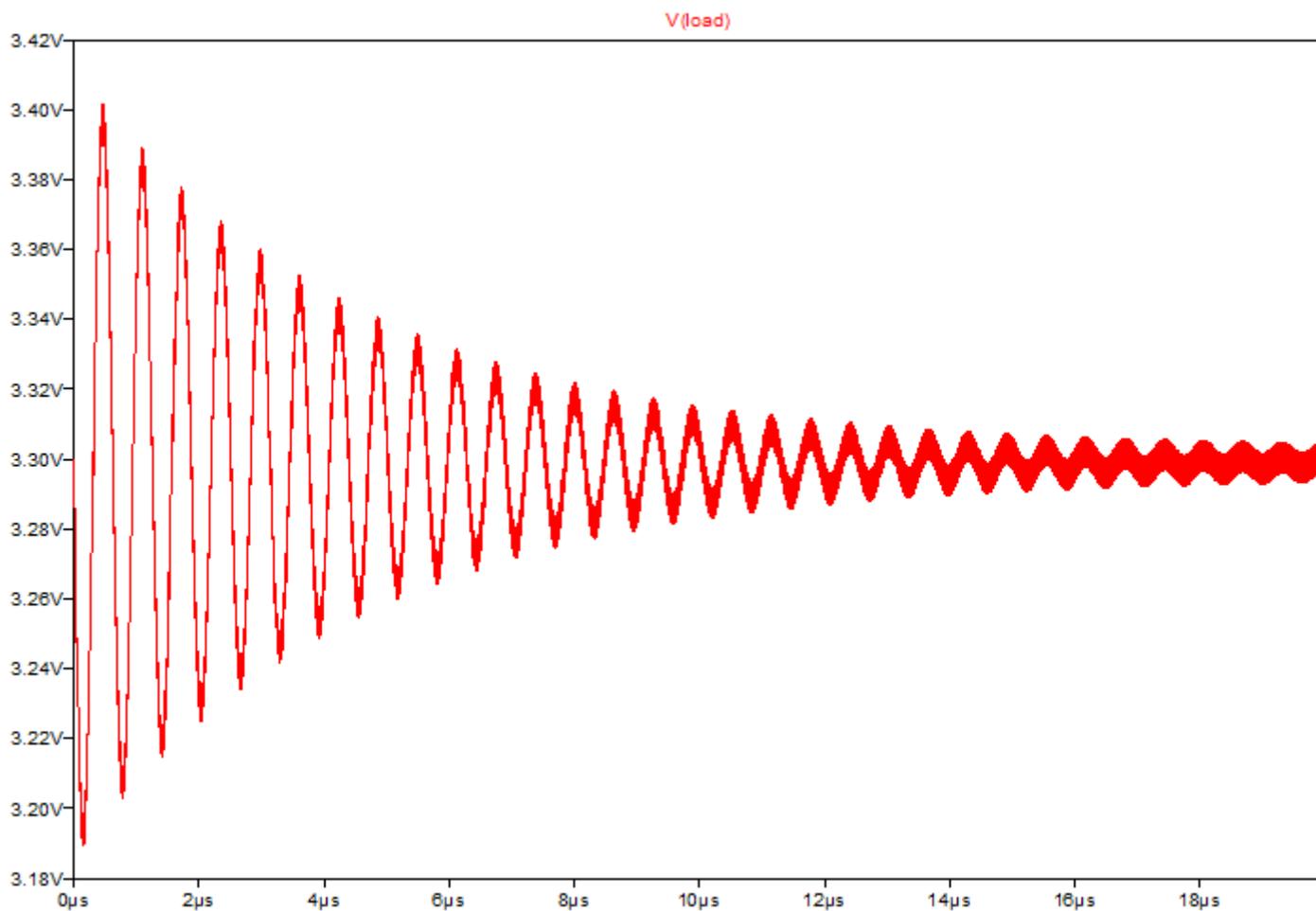
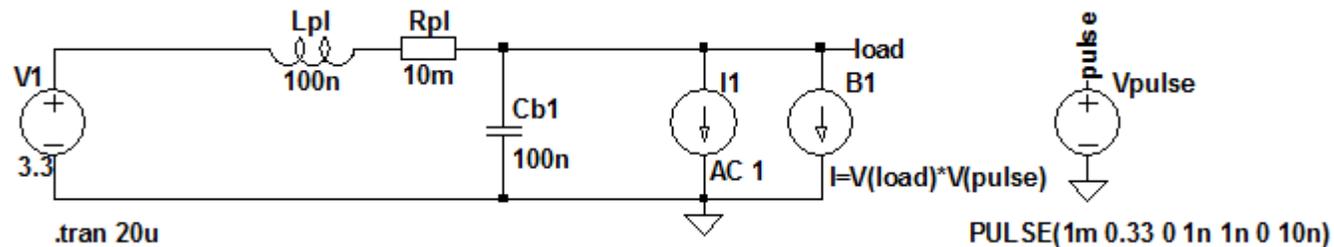


--- D:\FEI\Pedagogika\CES - ang\2014\10 - Power supply decoupling\Real capacitor.asc ---

Razlika med kondenzatorji

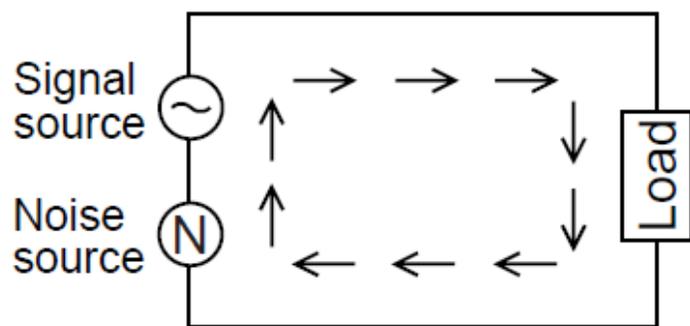


Učinek paralelne resonance

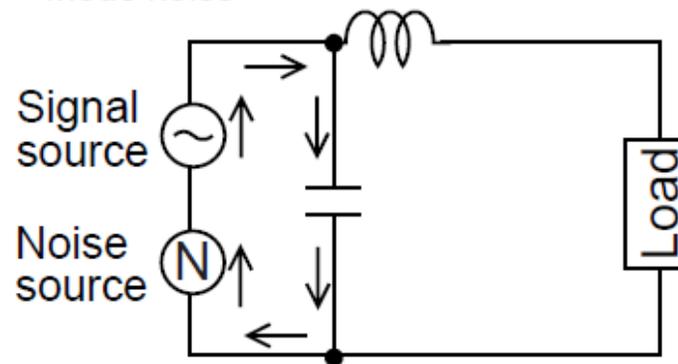


Filtriranje

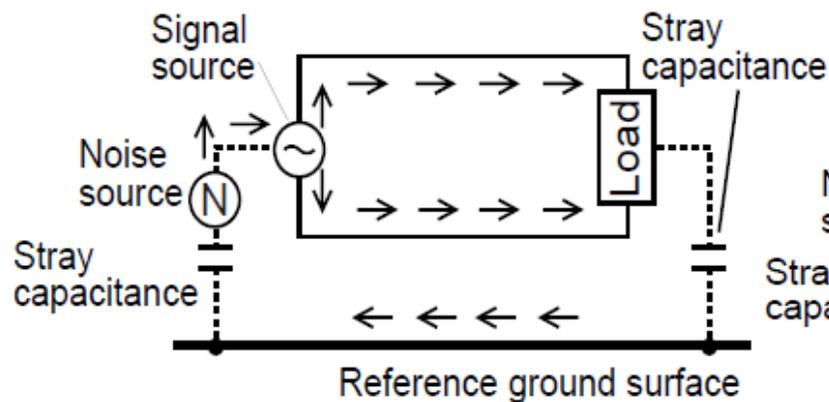
■ Differential mode noise



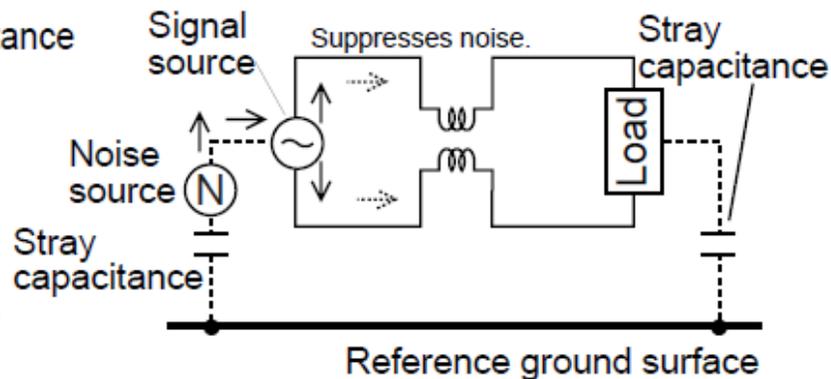
■ Suppression method of differential mode noise



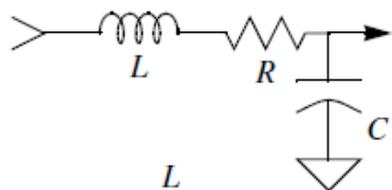
■ Common mode noise



■ Suppression method of common mode noise (1)

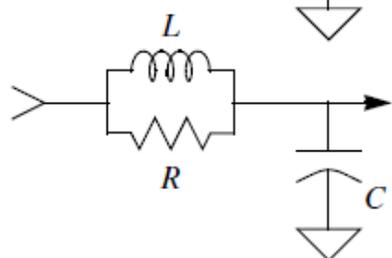


Dušenje resonanc filtrov



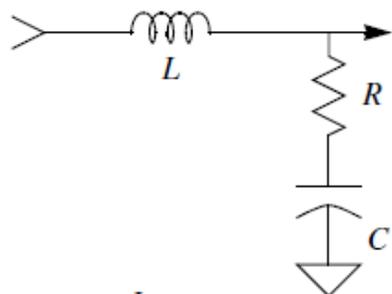
A. Reduced output voltage
Decreased supply regulation

$$R_{crit} = 2\sqrt{\frac{L}{C}}$$



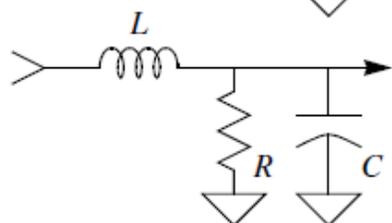
B. Poor decoupling

$$R_{crit} = \frac{1}{2}\sqrt{\frac{L}{C}}$$



C. Decreased bypass effectiveness

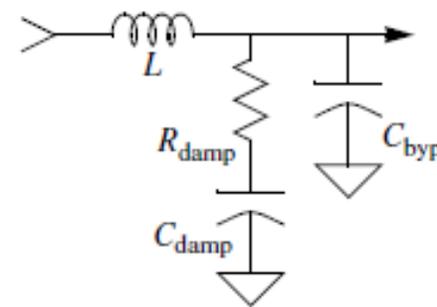
$$R_{crit} = 2\sqrt{\frac{L}{C}}$$



D. High power dissipation

$$R_{crit} = \frac{1}{2}\sqrt{\frac{L}{C}}$$

• Best option



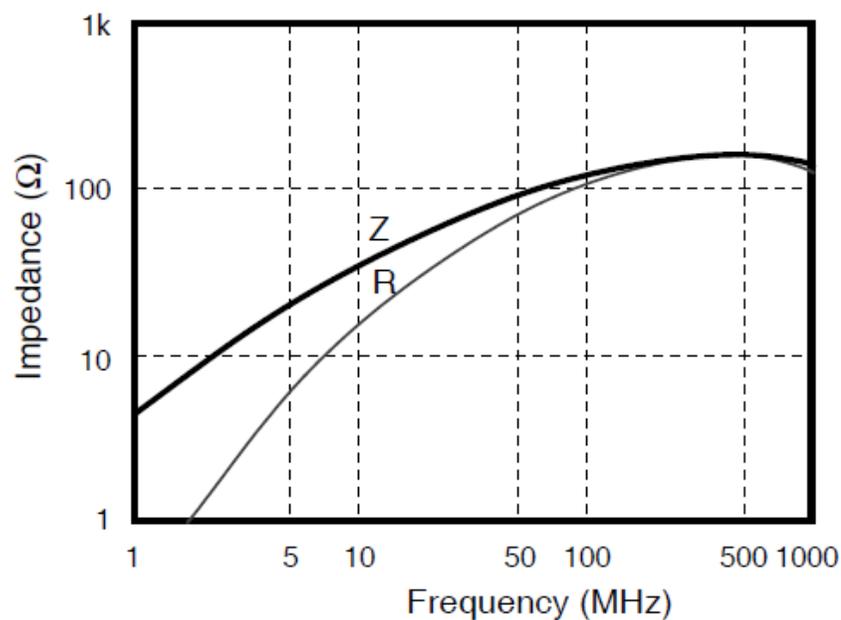
$$C_{damp} > 16C_{byp}$$

$$R_{damp} > 2\sqrt{\frac{L}{C_{damp}}}$$

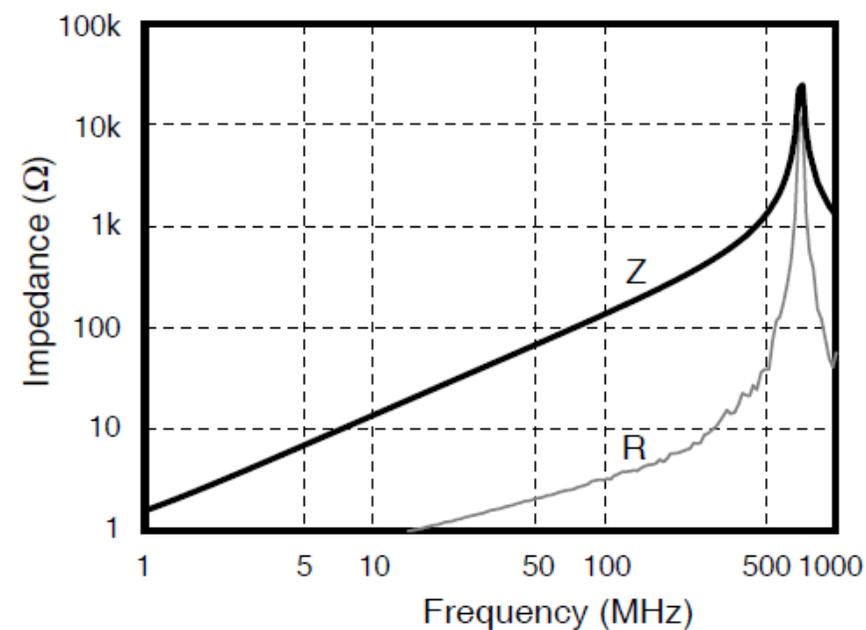
$$R_{damp} < \frac{1}{2}\sqrt{\frac{L}{C_{byp}}}$$

Feritna dušilka ali tuljava?

Feritna dušilka



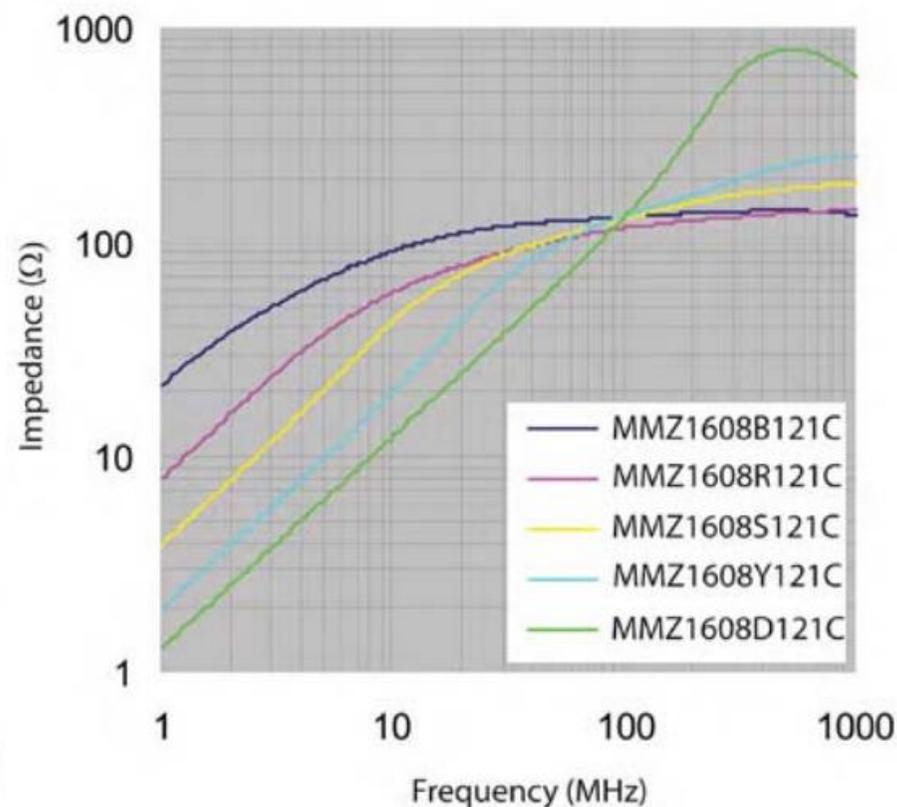
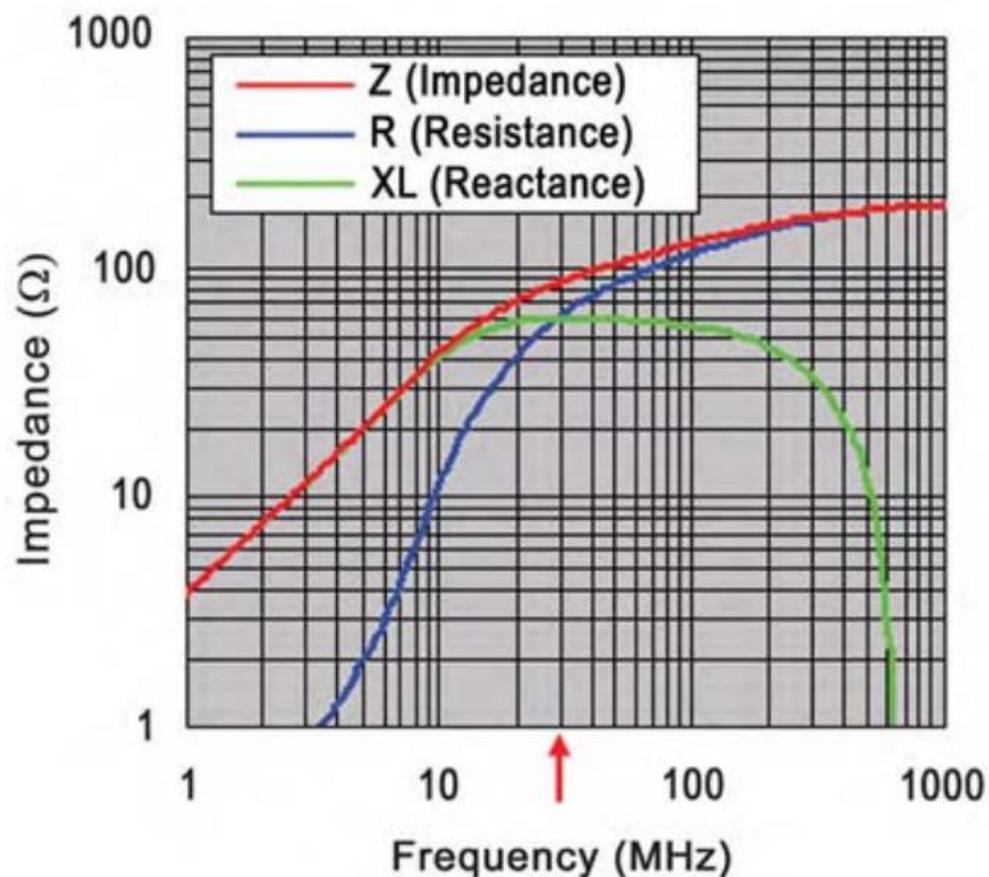
Tuljava



Podatki feritnih dušilk

Part No.	Impedance (Ω)[100MHz]*1	DC resistance (Ω)max.	Rated current*2 (A)max.	Thickness T(mm)
MPZ1608S300A	30 \pm 10 Ω	0.01	5	0.6
MPZ1608S600A	60 \pm 25%	0.02	3.5	0.6
MPZ1608S101A	100 \pm 25%	0.03	3	0.6
MPZ1608S221A	220 \pm 25%	0.05	2.2	0.8
MPZ1608R391A	390 \pm 25%	0.12	1.2	0.8
MPZ1608S471A	470 \pm 25%	0.15	1	0.8
MPZ1608S601A	600 \pm 25%	0.15	1	0.8
MPZ1608Y600B	60 \pm 25%	0.03	2.3	0.8
MPZ1608Y101B	100 \pm 25%	0.04	2	0.8
MPZ1608Y151B	150 \pm 25%	0.05	1.8	0.8
MPZ1608D300B	30 \pm 10 Ω	0.06	1.8	0.8
MPZ1608D600B	60 \pm 25%	0.1	1.2	0.8
MPZ1608D101B	100 \pm 25%	0.15	1	0.8

Razlike med feritnimi dušilkami z enakimi specifikacijami



Primer dizajna filtra

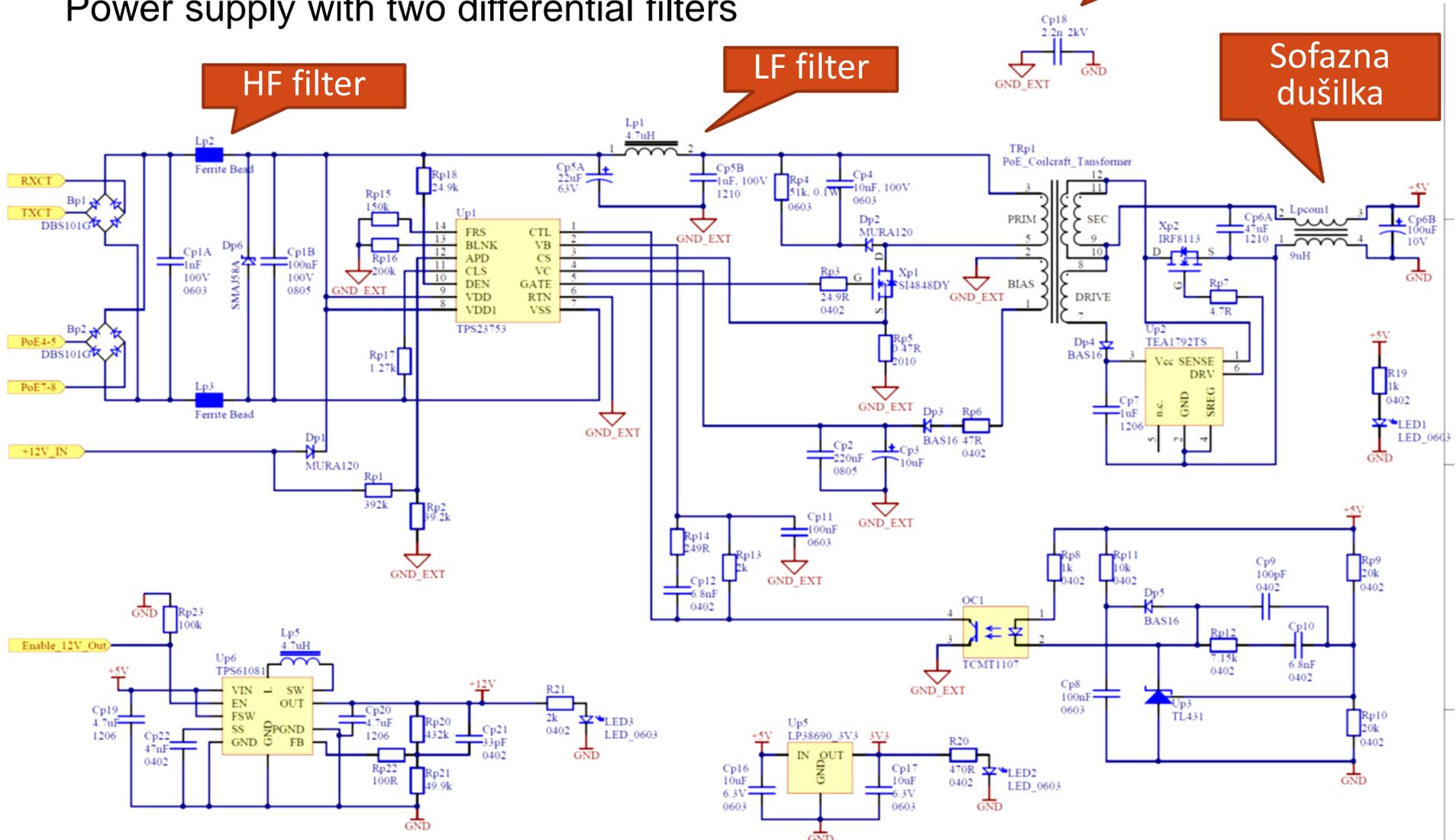
Power supply with two differential filters

I/O kondenzator

HF filter

LF filter

Sofazna dušilka



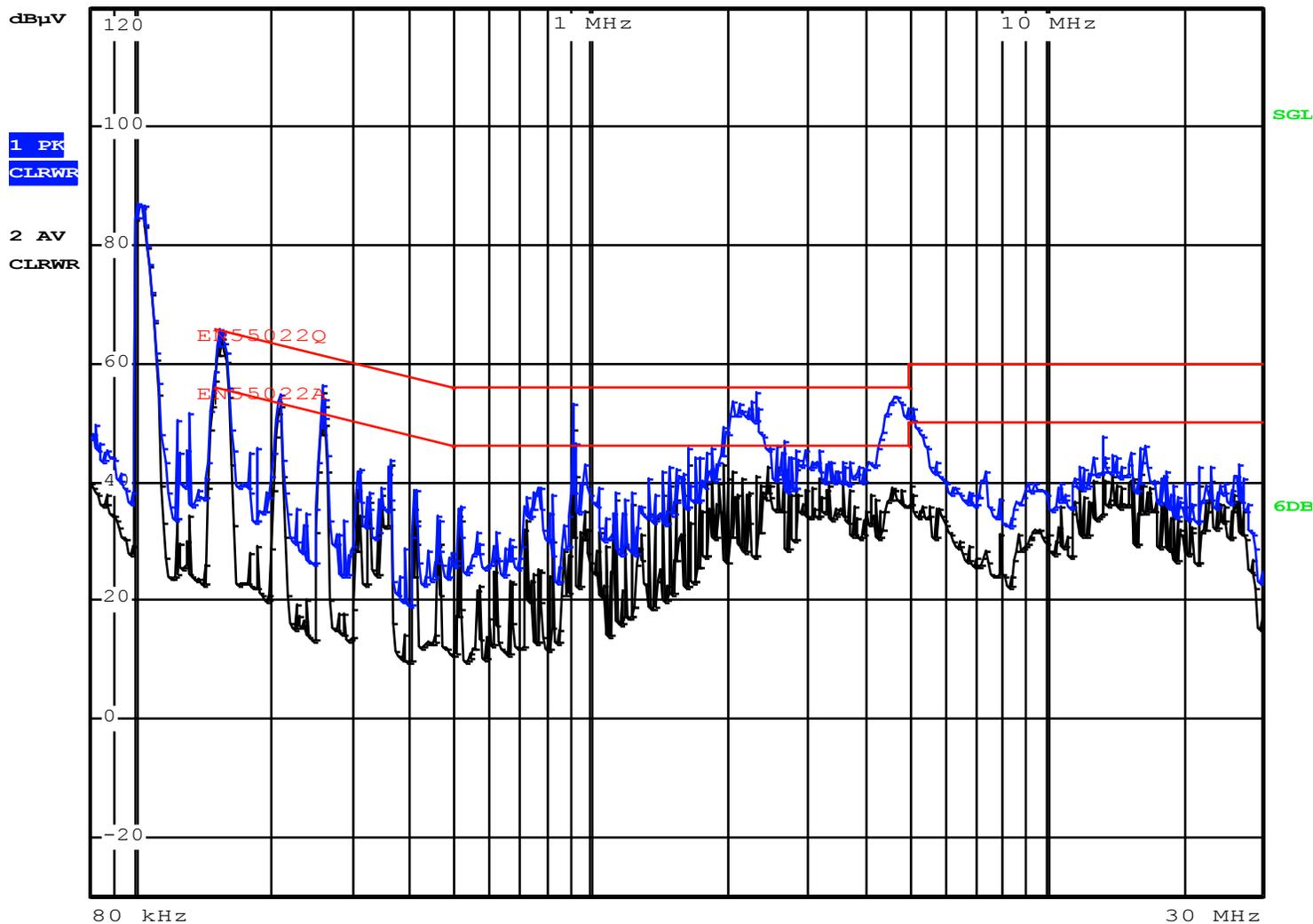
Konduktivne motnje na 12V napajalni liniji



RBW 9 kHz

MT 30 ms

Att 0 dB AUTO PREAMP ON



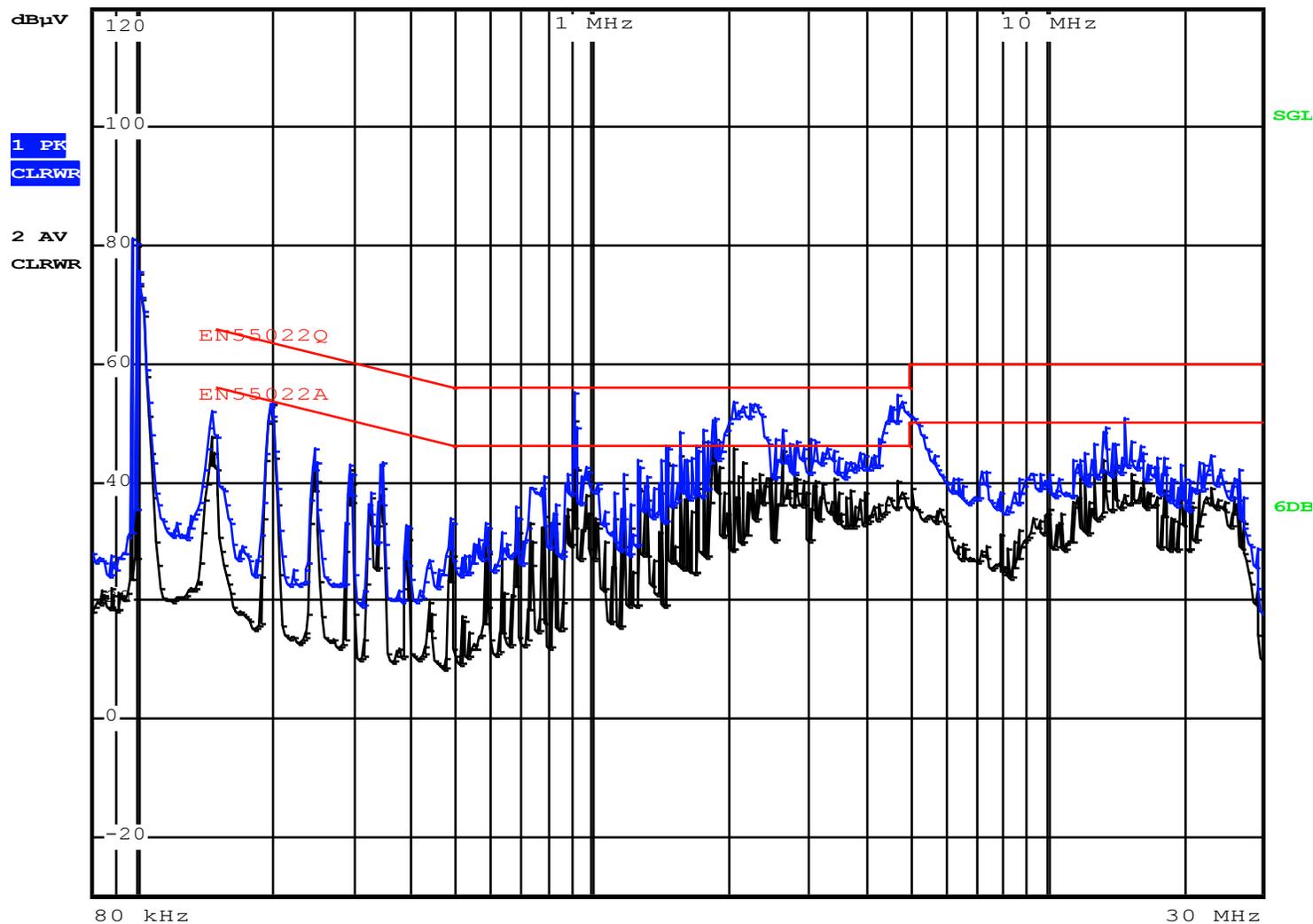
10 μ H tuljava v NF filtru



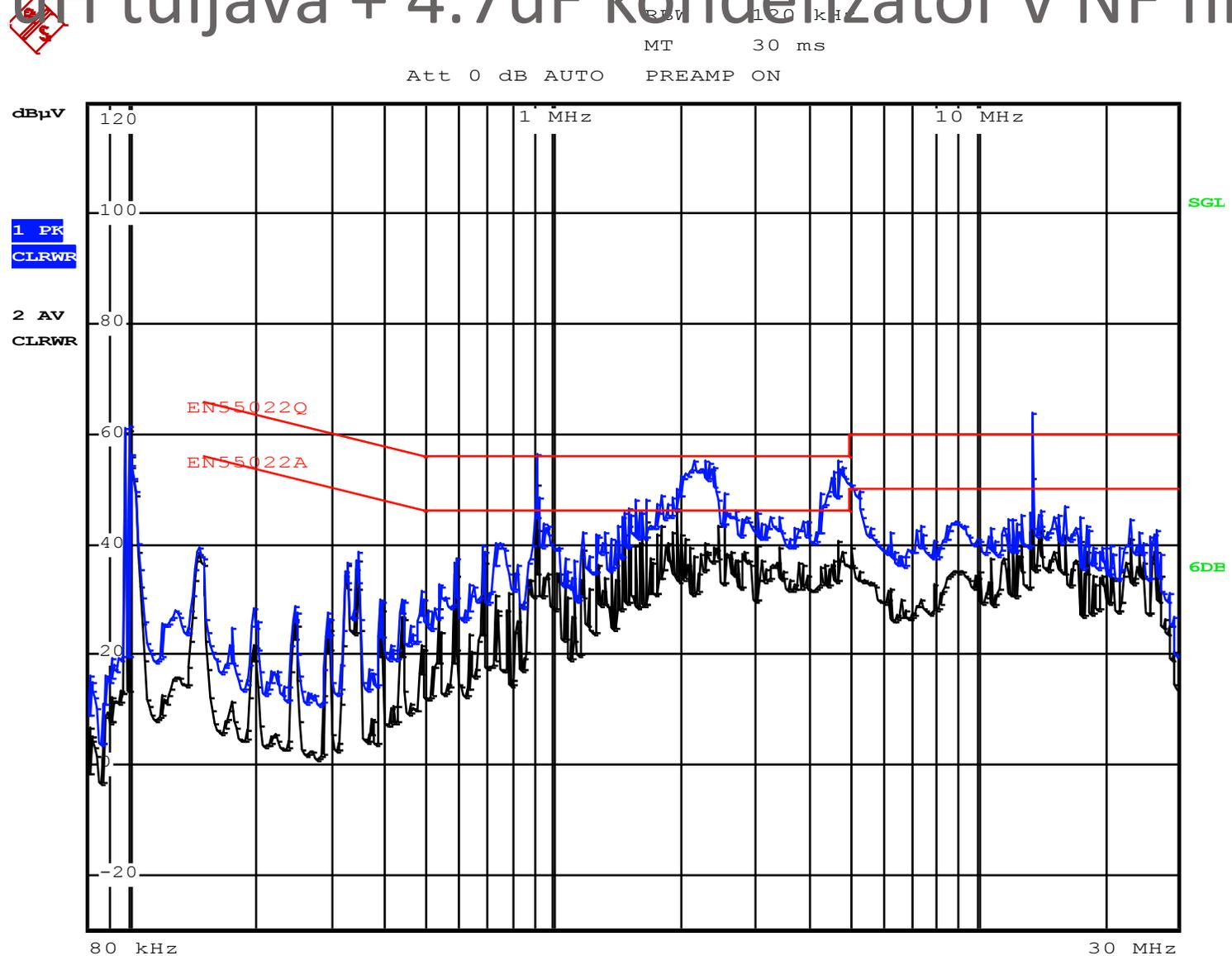
RBW 9 kHz

MT 30 ms

Att 0 dB AUTO PREAMP ON

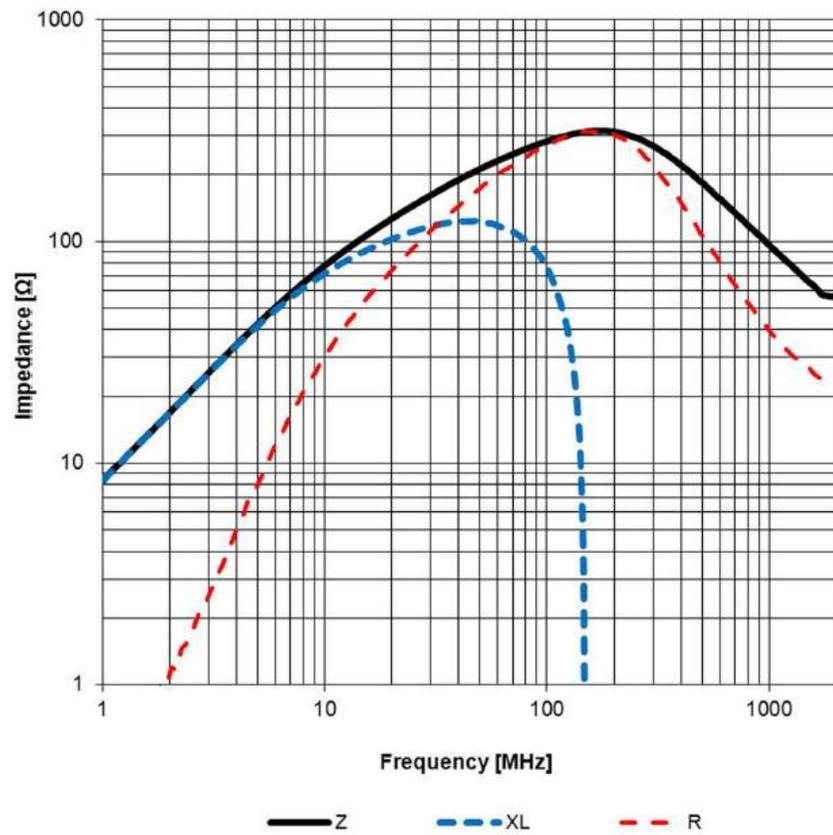


10 μ H tuljava + 4.7 μ F kondenzator v NF filtru

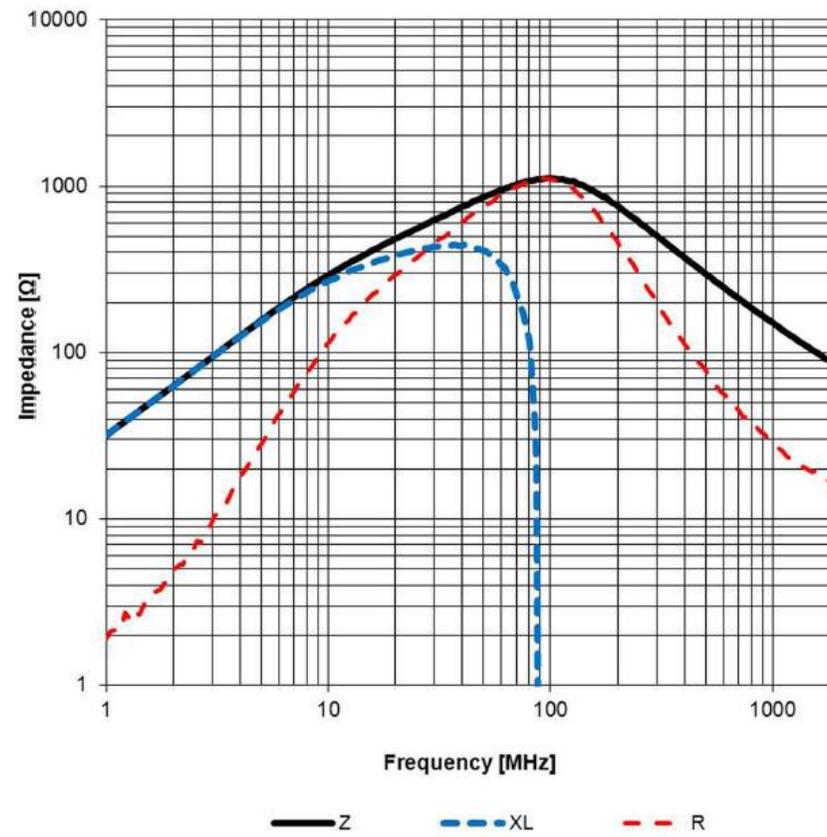


Različne feritne dušilke

FB1



FB2



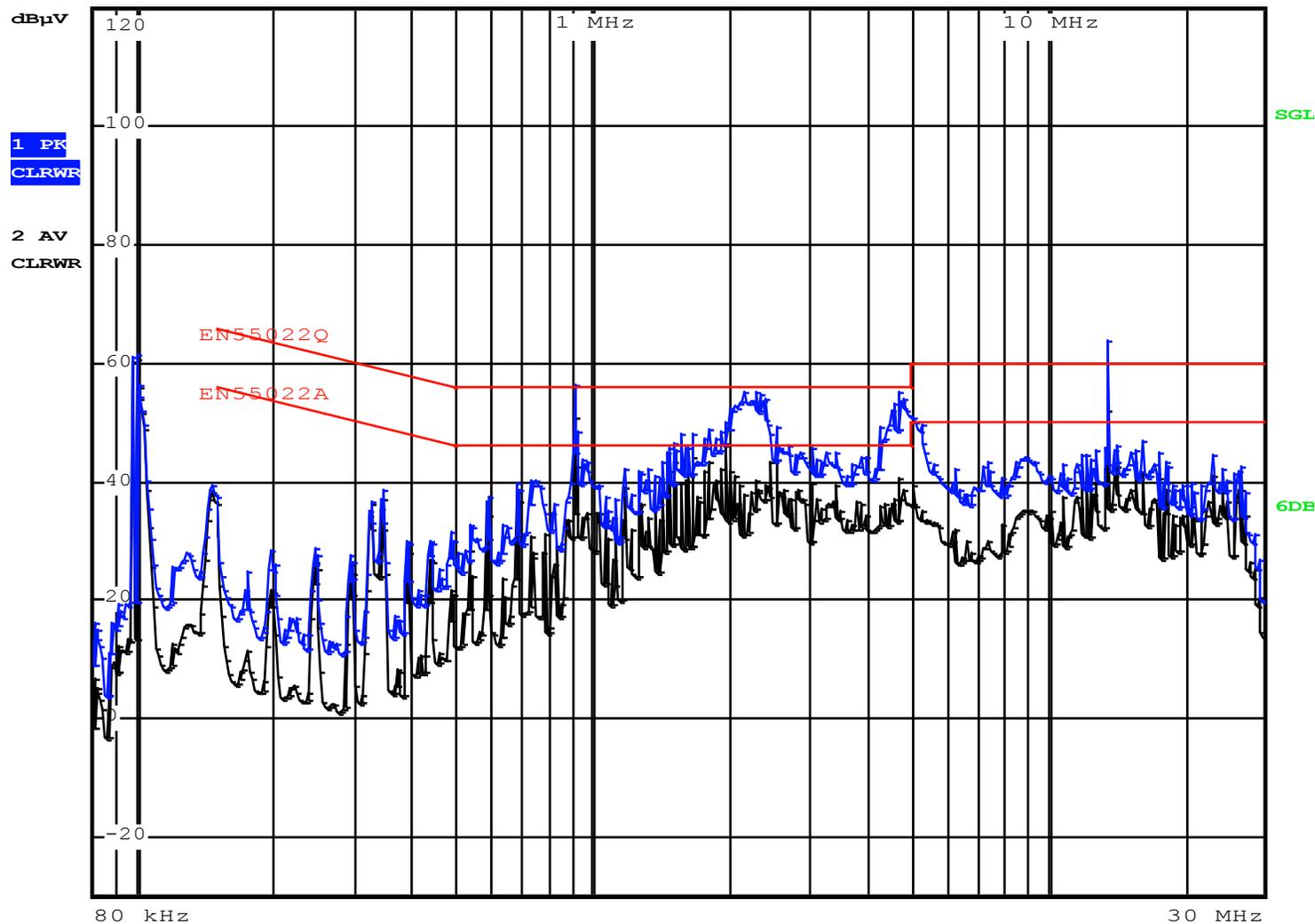
FB1



RBW 120 kHz

MT 30 ms

Att 0 dB AUTO PREAMP ON



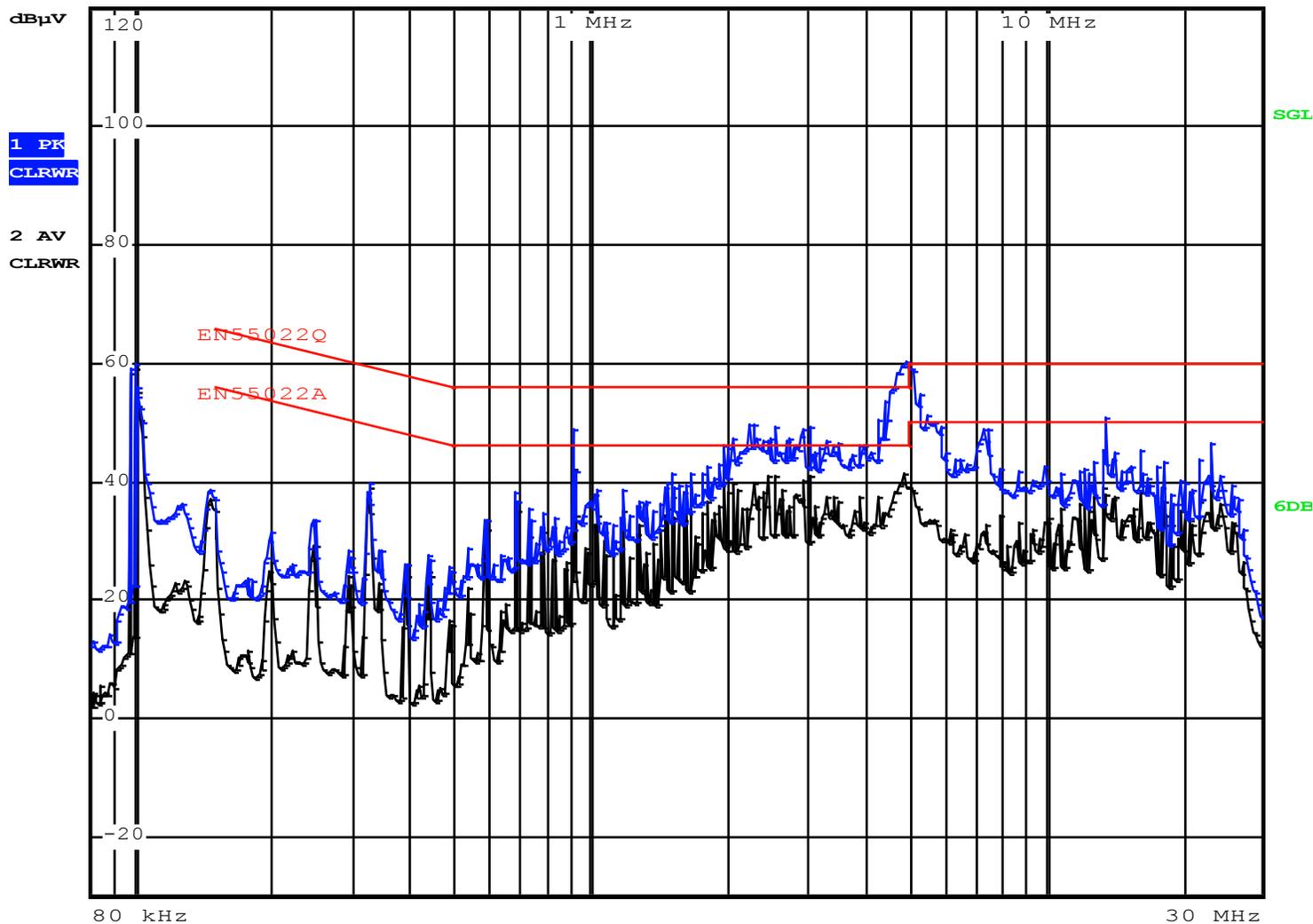
FB2



RBW 9 kHz

MT 30 ms

Att 0 dB AUTO PREAMP ON



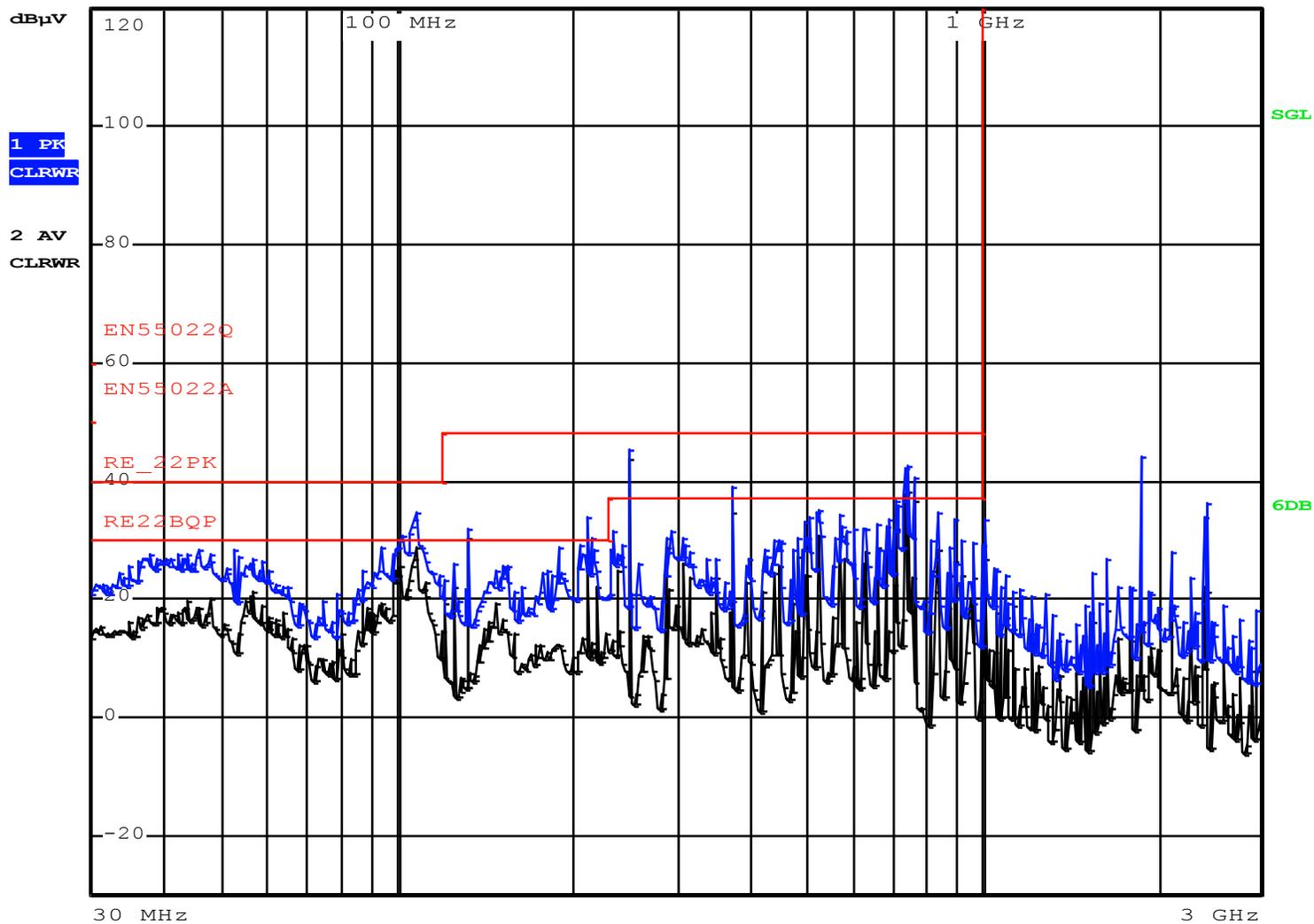
Z C₁₀



RBW 120 kHz

MT 2 ms

Att 0 dB AUTO PREAMP ON



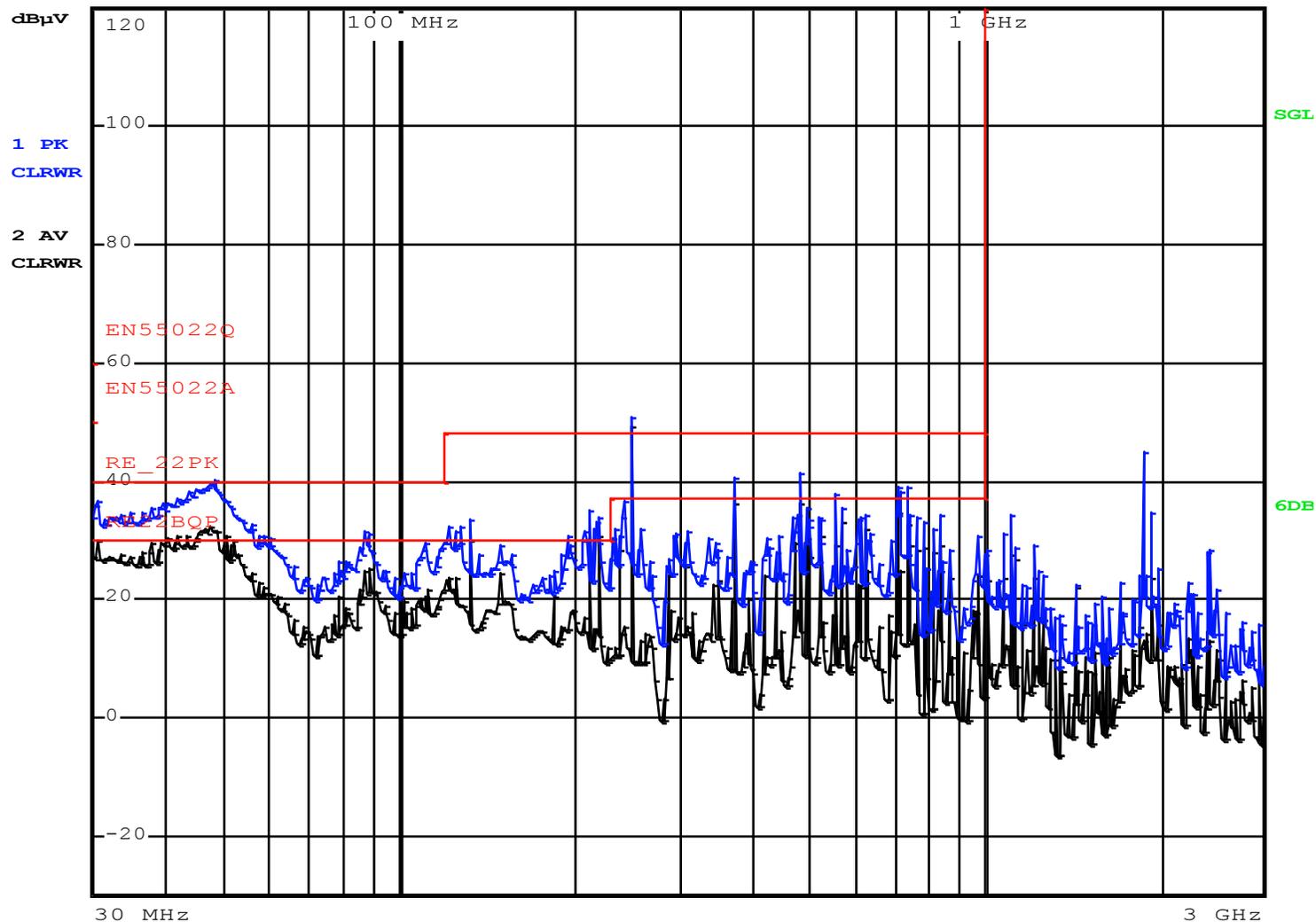
Brez C₁₀



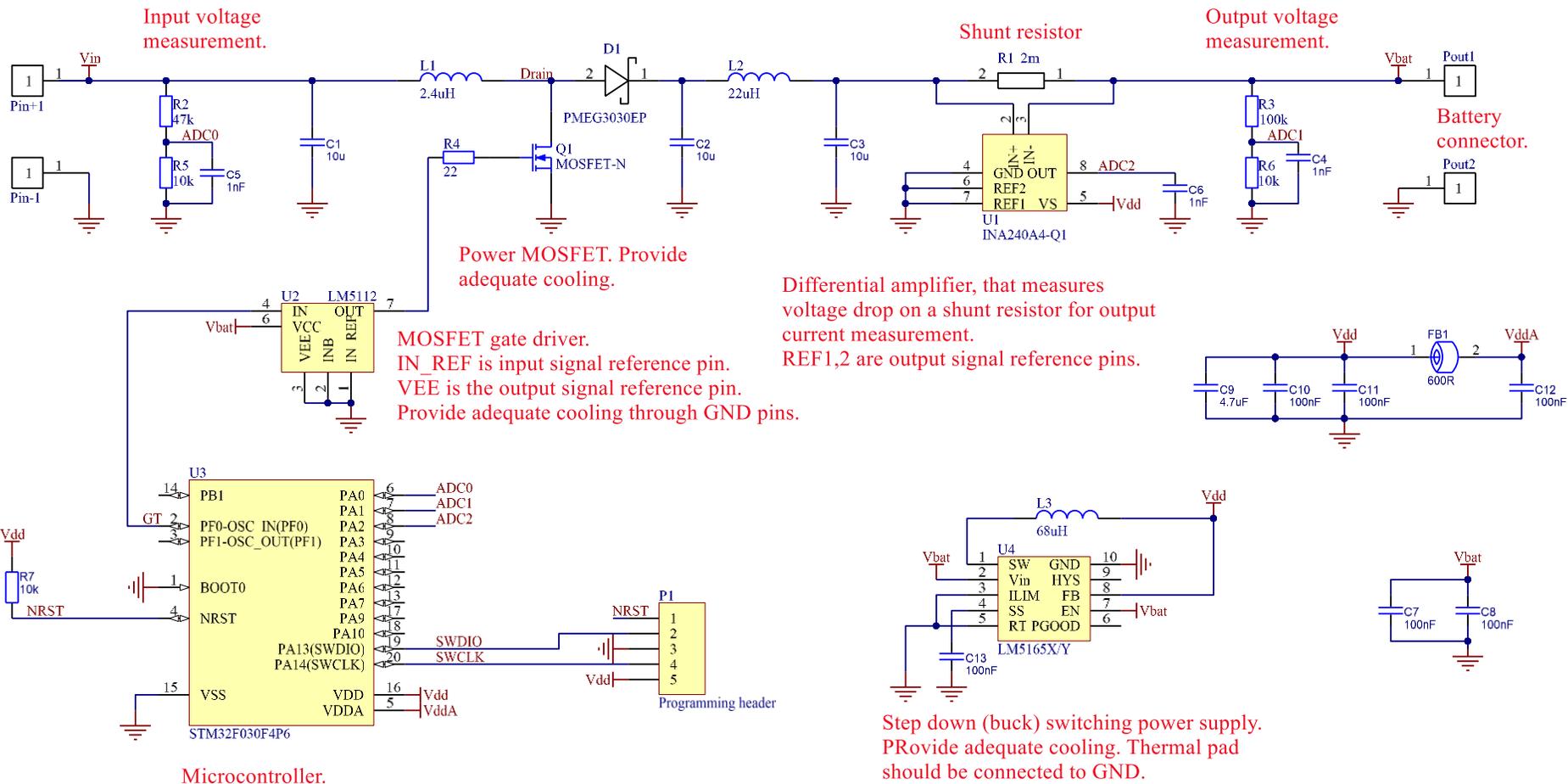
RBW 120 kHz

MT 2 ms

Att 0 dB AUTO PREAMP ON



Primer pretvornika navzgor



MPPT.PjPCB - Altium Designer (18.0.9)

File Edit View Project Place Design Tools Route Reports Window Help

MPPT.SchDoc * MPPT.PcbDoc MPPTsolution.PcbDoc AljazKovacic.PcbDoc LED driver solution.PcbDoc Main.SchDoc Analog.SchDoc Battery charger_Luka_Brodnik.PcbDoc Battery charger.SchDoc Strmec_Jernej.PcbDoc Battery charger.PcbDoc *

x: 57.600 dx: 4.800 mm
y: 65.000 dy: 12.100 mm
Top Layer
Snap: 0.1mm Hotspot Snap: 0.203mm

Inadequate cooling of Q1. -5
No four wire connection of P1 -5

LS Top Bottom Mech-1 Mech-13 Mech-15 T-Silk B-Silk T-Paste B-Paste T-Solder B-Solder D-Guide KeepOut D-Draw Multi

X:57.6mm Y:65mm Grid: 0.1mm (Hotspot Snap) Panels

MPPT.PjPCB - Altium Designer (18.0.9)

File Edit View Project Place Design Tools Route Reports Window Help

MPPT.SchDoc * MPPT.PcbDoc MPPTSolution.PcbDoc AljazKovacic.PcbDoc LED driver solution.PcbDoc Main.SchDoc Analog.SchDoc Battery charger_Luka_Brodnik.PcbDoc Battery charger.SchDoc Strmec_Jernej.PcbDoc Battery charger.PcbDoc *

Projects PCB PCB Filter

x: 58.400 dx: 1.600 mm
y: 68.800 dy: 3.700 mm
Bottom Layer
Snap: 0.1mm Hotspot Snap: 0.203mm

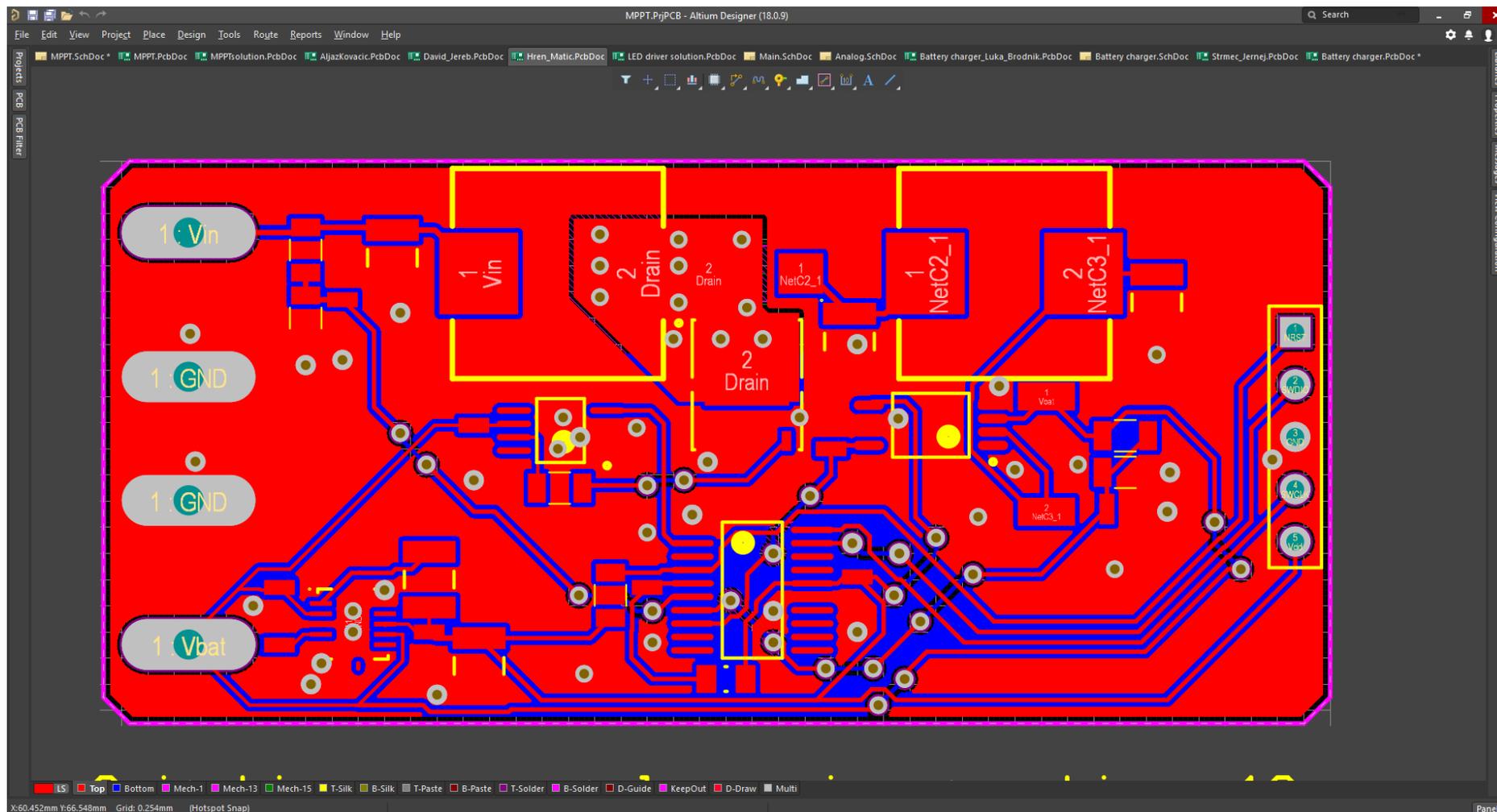
Inadequate cooling of Q1. -5
No four wire connection of P1 -5

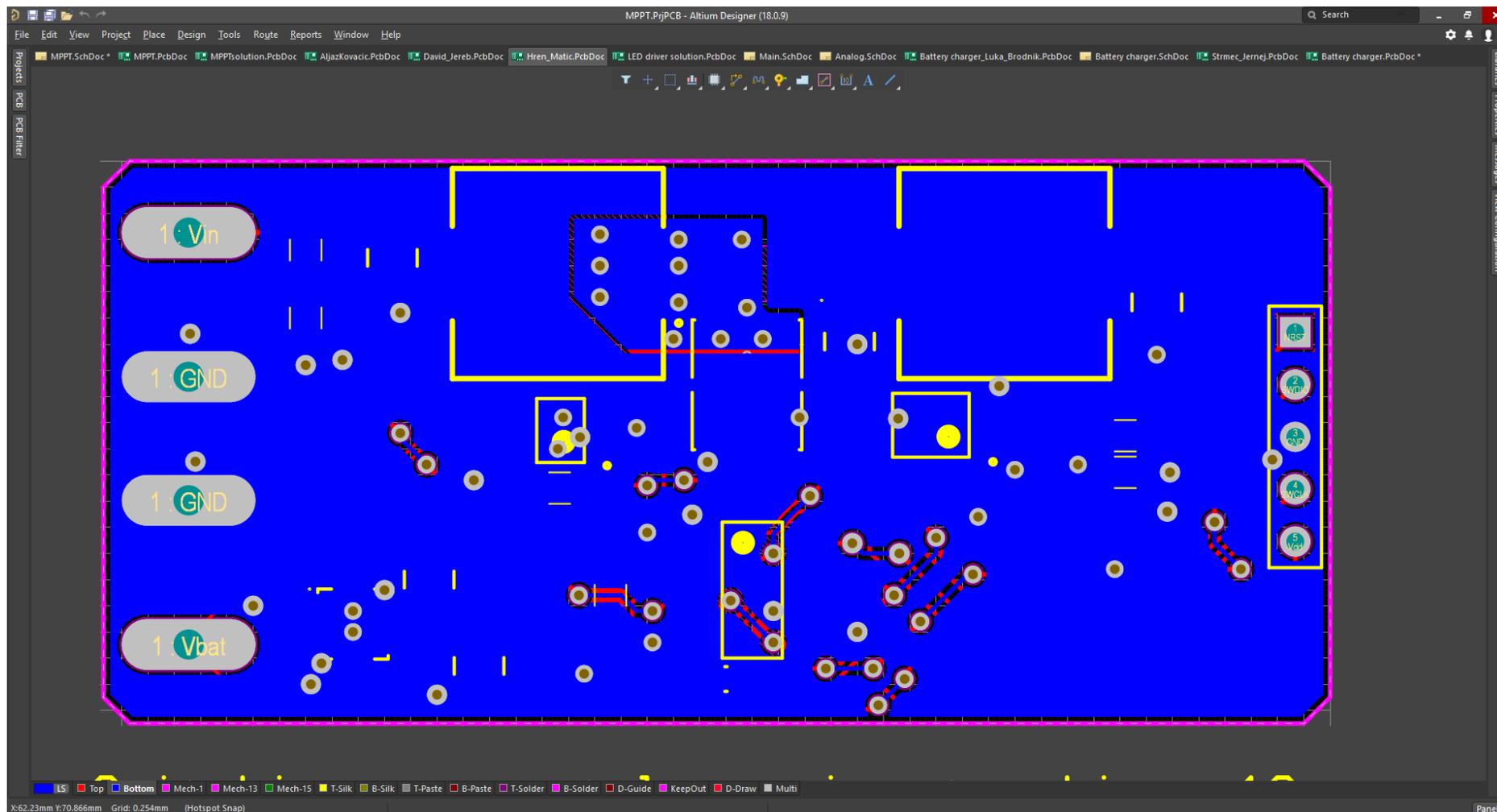
LS Top Bottom Mech-1 Mech-13 Mech-15 T-Silk B-Silk T-Paste B-Paste B-Solder D-Solder D-Guide KeepOut D-Draw Multi

X:58.4mm Y:68.8mm Grid: 0.1mm (Hotspot Snap)

Zakrajšek, Olga
Predlog komisije za oceno primernosti teme doktorske disertacije- Jošt Balent
Spoštovani, po nalogu predstojnika kz Outlook 2016

Libraries Properties Messages View Configuration Panels





MPPT.PjPCB - Altium Designer (18.0.9)

File Edit View Project Place Design Tools Route Reports Window Help

MPPT.SchDoc (1) JURE_LAKNER.PcbDoc Main.SchDoc Analog.SchDoc Battery charger.SchDoc

x: 59.800 dx: 65.700 mm
y: 62.000 dy: 5.600 mm
Top Overlay
Snap: 0.1mm Hotspot Snap: 0.203mm
GND 51.938 mm (33-Nodes)

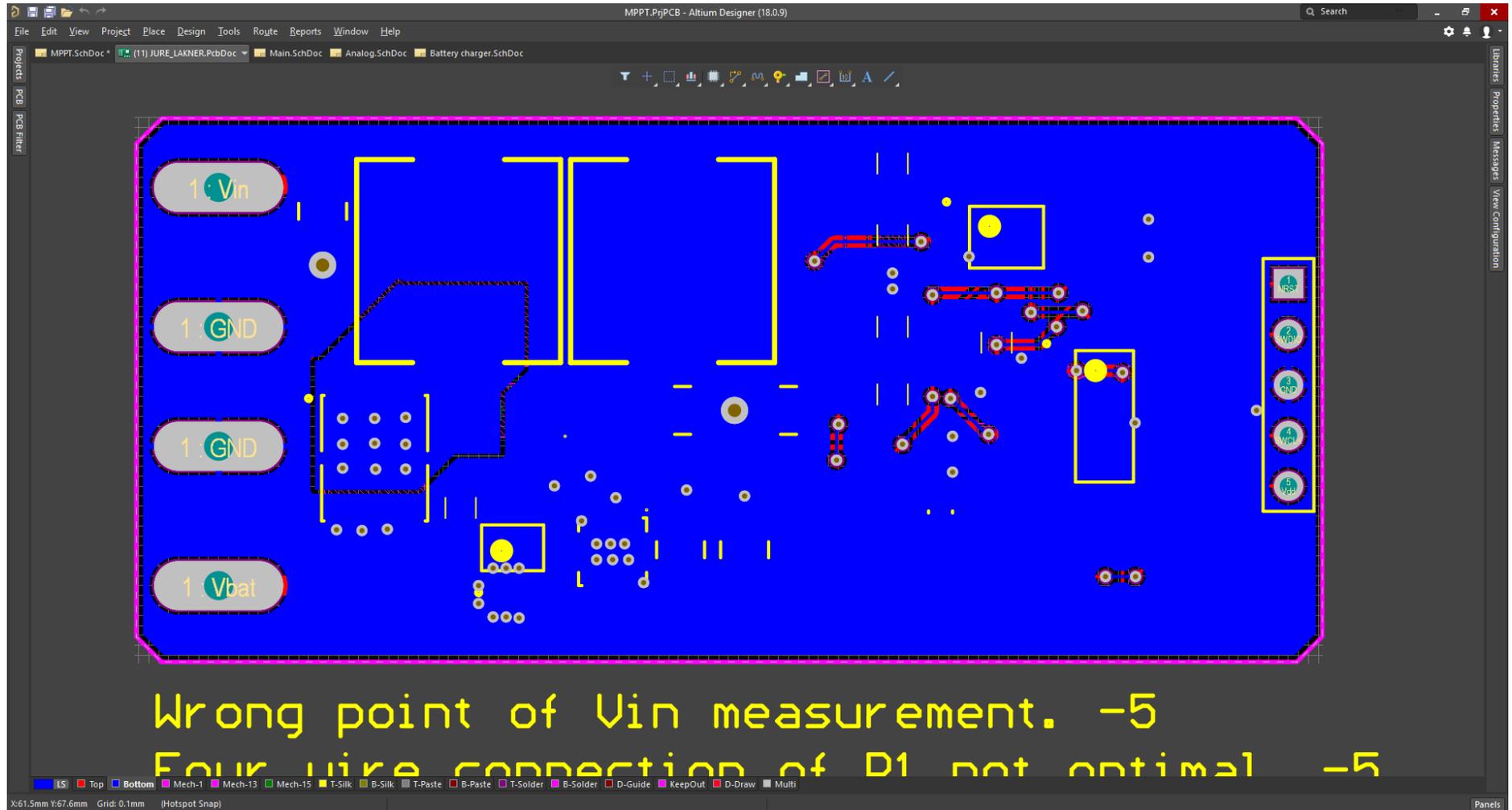
1 Vin
2 NetC3_1
1 Vin
2 Drain
1 NetC2_1
2 Drain
1 NetC2_1
2 Drain
1 Vbat
2 NetC3_1

1 Vbat
1 GND
1 GND
1 Vbat

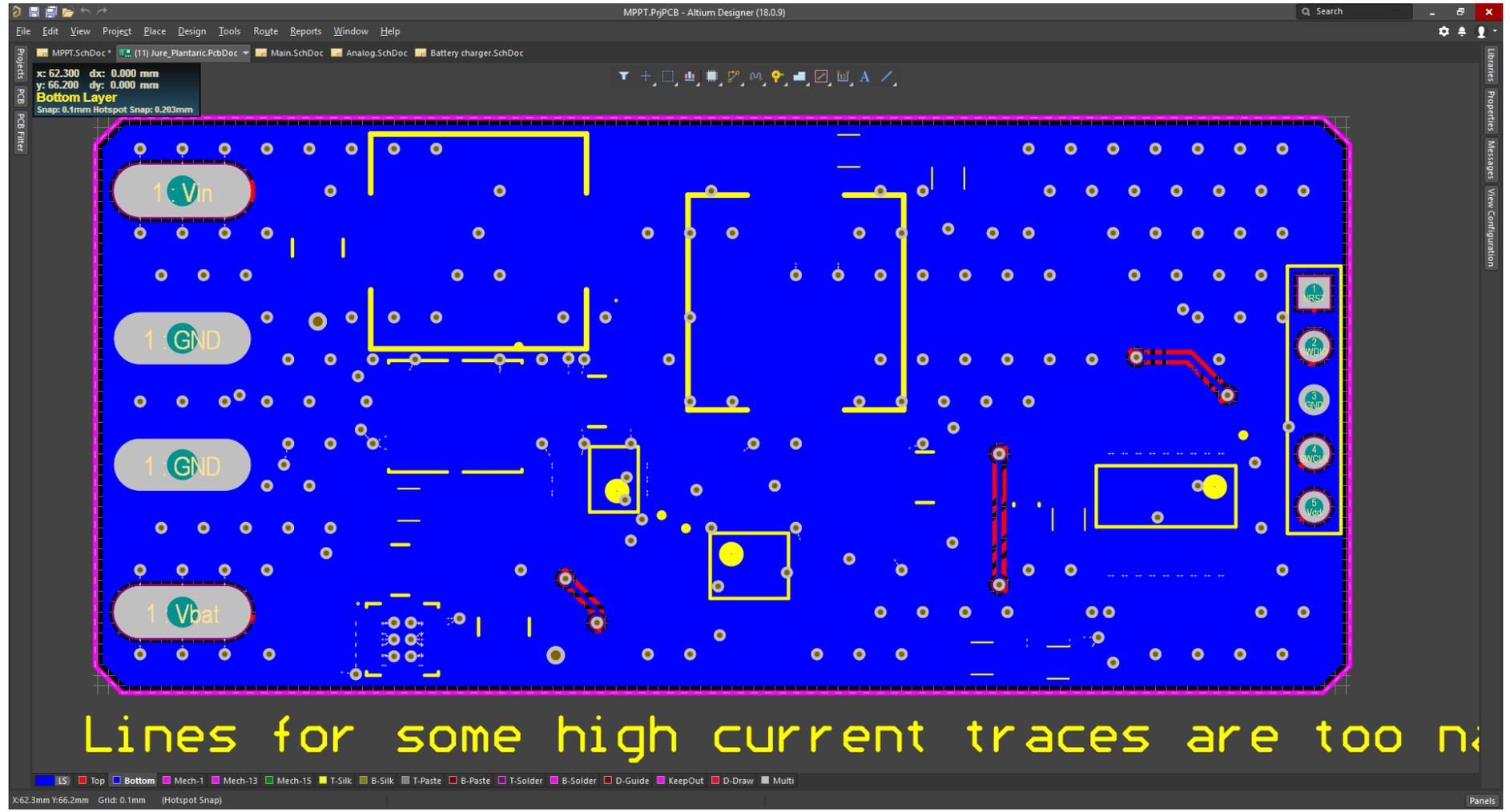
Wrong point of Vin measurement. -5
Four wire connection of D1 not optimal -5

LS Top Bottom Mech-1 Mech-13 Mech-15 T-Silk B-Silk T-Paste B-Paste T-Solder B-Solder D-Guide KeepOut D-Draw Multi

X:59.8mm Y:62mm Grid: 0.1mm (Hotspot Snap)



The image shows a screenshot of the Altium Designer PCB layout environment. The main workspace displays a PCB layout with a red background and blue traces. Several traces are highlighted in yellow, indicating they are too narrow. Labels on the board include '1: Vin', '2: Drain', '1: NetC2_1', '2: NetC3_1', and '1: Vbat'. On the right side, there is a vertical stack of five circular components labeled '1: VCC', '2: VDD', '3: SWP', '4: VCC', and '5: VDD'. The software interface includes a menu bar at the top (File, Edit, View, Project, Place, Design, Tools, Route, Reports, Window, Help), a toolbar, and a project browser on the left. A yellow text overlay at the bottom of the image reads 'Lines for some high current traces are too narrow'. At the very bottom, there is a legend for various PCB features and a status bar showing 'X:61mm Y:55.7mm Grid: 0.1mm (Hotspot Snap)'. The title bar of the window reads 'MPPT.Pcb - Altium Designer (18.0.9)'.



The screenshot displays the Altium Designer interface for a PCB layout. The main workspace shows a top-layer layout with a red background and blue traces. Key components and nets are highlighted with yellow boxes:

- 1 Vin**: Input power net, located on the left side.
- 1 GND**: Ground net, located on the left side.
- 1 Vbat**: Battery power net, located at the bottom left.
- 2 Drain**: Drain net, located in the upper middle section.
- 1 NetC2_1** and **2 NetC2_1**: Capacitor nets for component C2, located in the upper right section.
- 2 NetC3_1**: Capacitor net for component C3, located in the middle right section.
- 1 RST**, **2 WPI**, **3 SLP**, **4 VCI**, and **5 VPP**: A vertical stack of control and power nets on the far right edge.

At the bottom of the window, a legend identifies the colors used for different PCB layers and materials:

- LS (Light Blue)
- Top (Red)
- Bottom (Blue)
- Mech-1 (Pink)
- Mech-13 (Light Green)
- Mech-15 (Light Green)
- T-Silk (Dark Green)
- B-Silk (Light Green)
- T-Paste (Light Green)
- B-Paste (Light Green)
- T-Solder (Light Green)
- B-Solder (Light Green)
- D-Guide (Light Green)
- KeepOut (Light Green)
- D-Draw (Light Green)
- Multi (Light Green)

The status bar at the bottom left shows: X:60.2mm Y:61.8mm Grid:0.1mm (Hotspot Snap). The title bar indicates the file is MPPT.Pcb - Altium Designer (18.0.9).

Bad placement and connection of C2. -5

MPPT.PjPCB - Altium Designer (18.0.9)

File Edit View Project Place Design Tools Route Reports Window Help

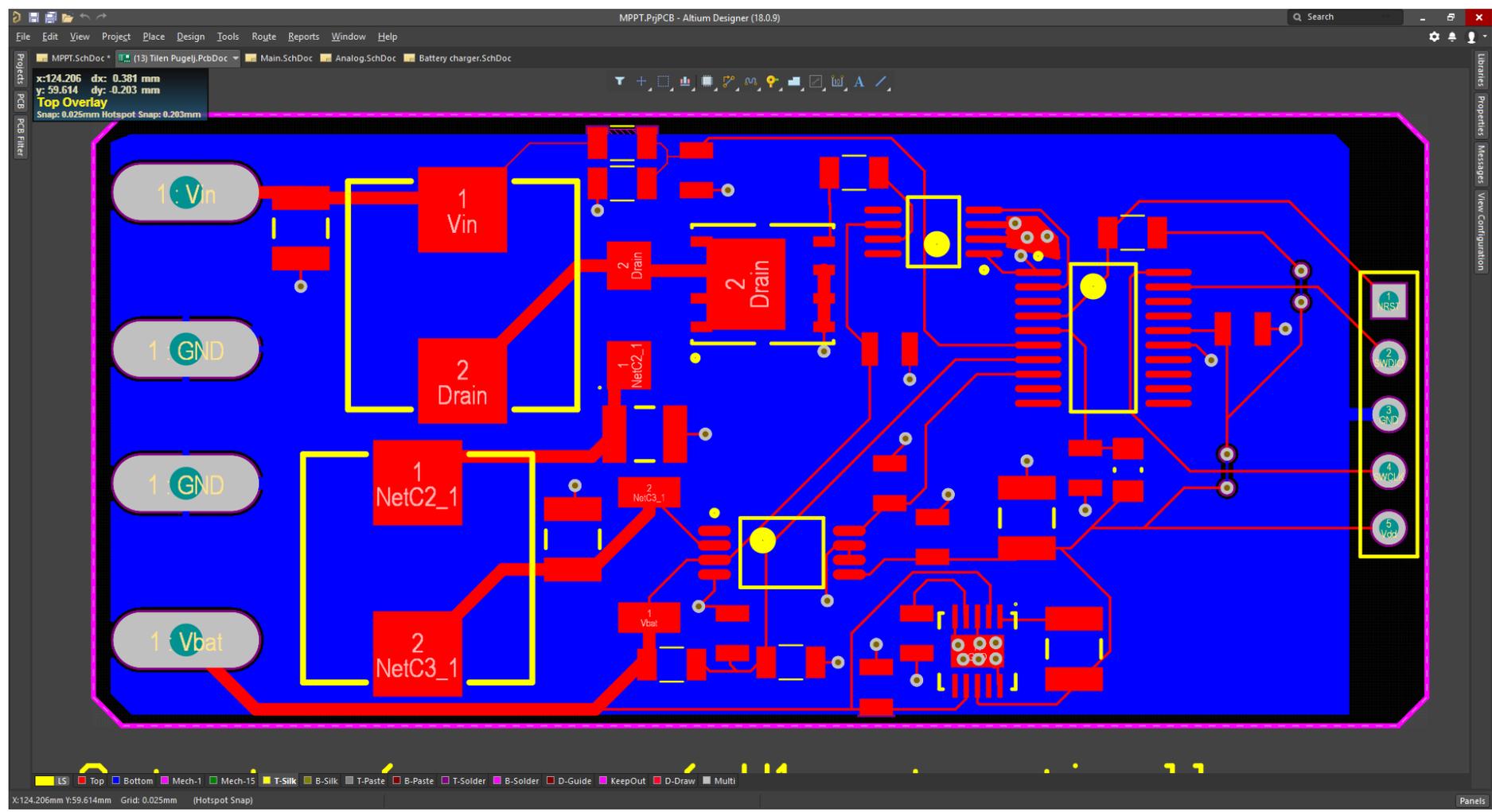
MPPT.SchDoc* (12) Rok Ratajec.PcbDoc Main.SchDoc Analog.SchDoc Battery charger.SchDoc

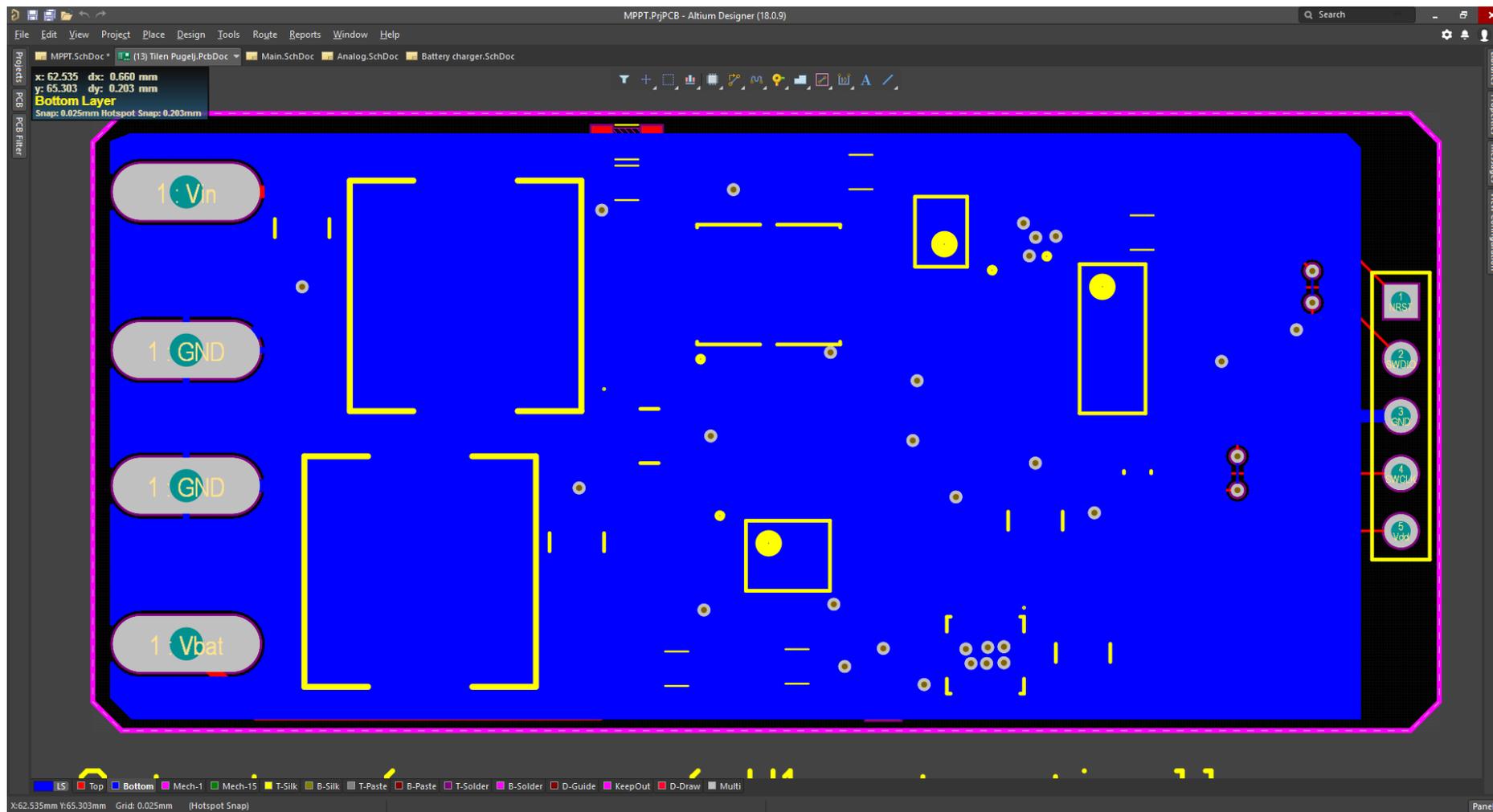
Bad placement and connection of C2. -5

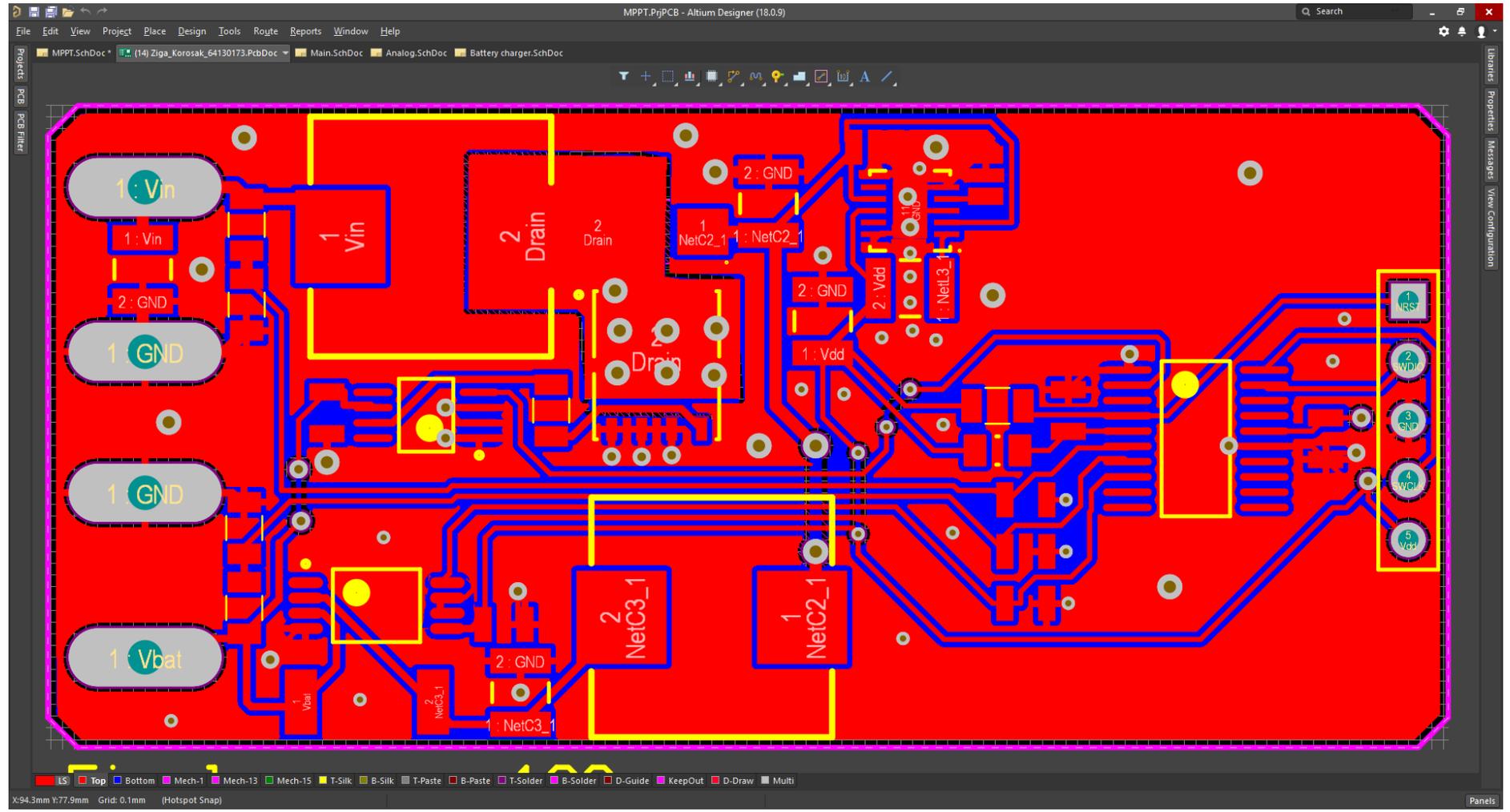
LS Top Bottom Mech-1 Mech-13 Mech-15 T-Silk B-Silk T-Paste B-Paste T-Solder B-Solder D-Guide KeepOut D-Draw Multi

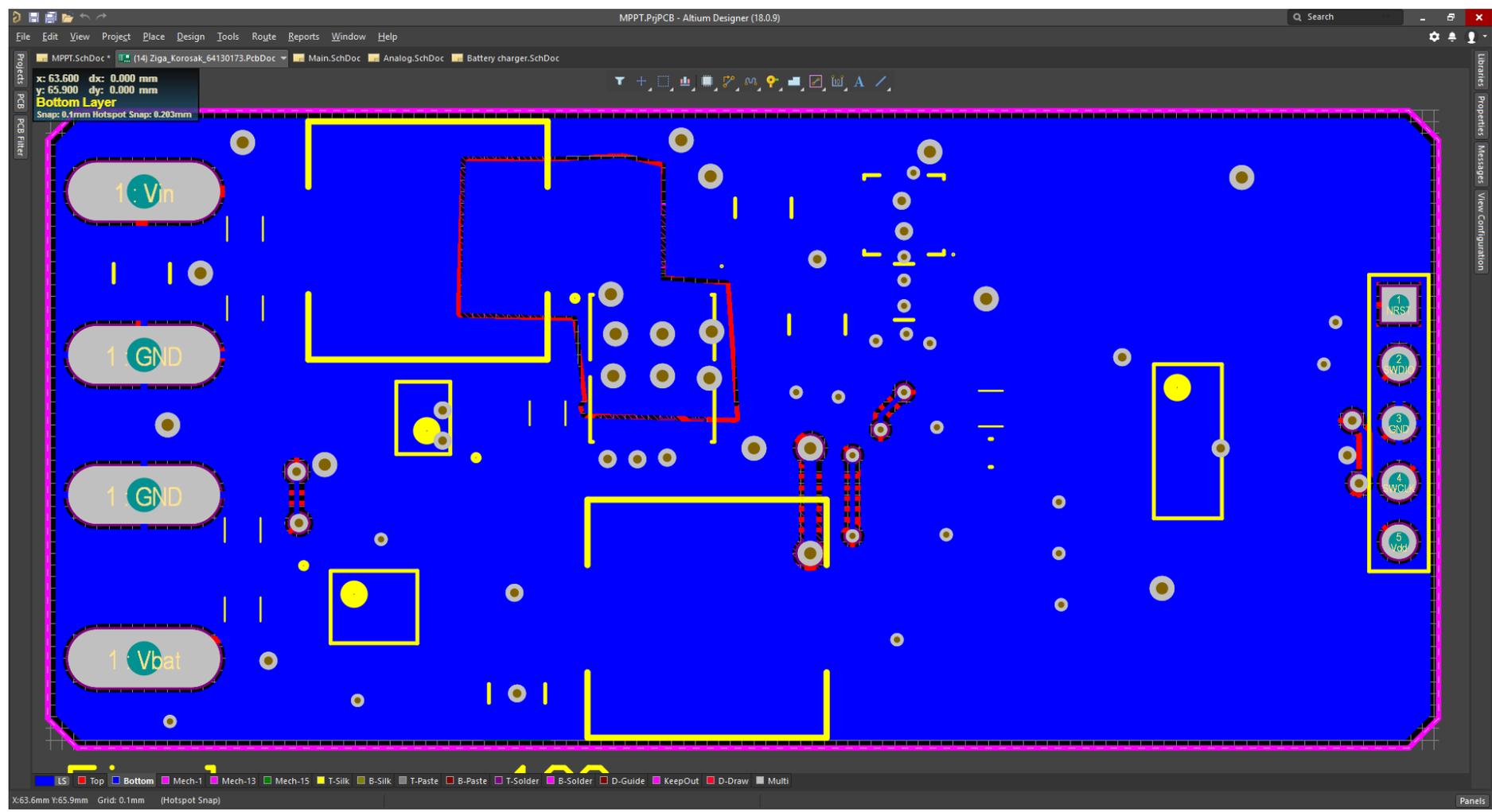
X:61.9mm Y:68.6mm Grid: 0.1mm (Hotspot Snap)

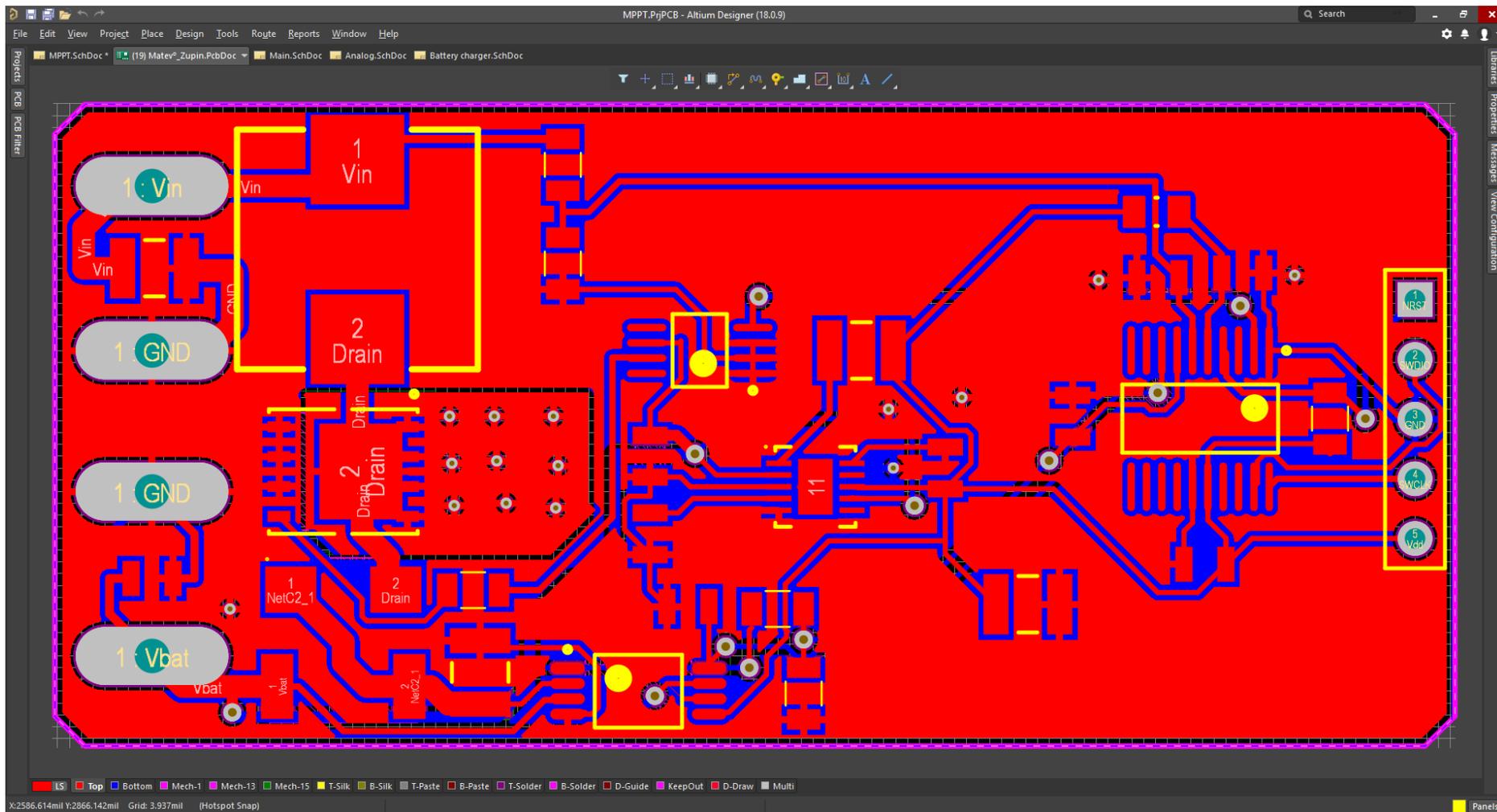
Libraries Properties Messages View Configuration

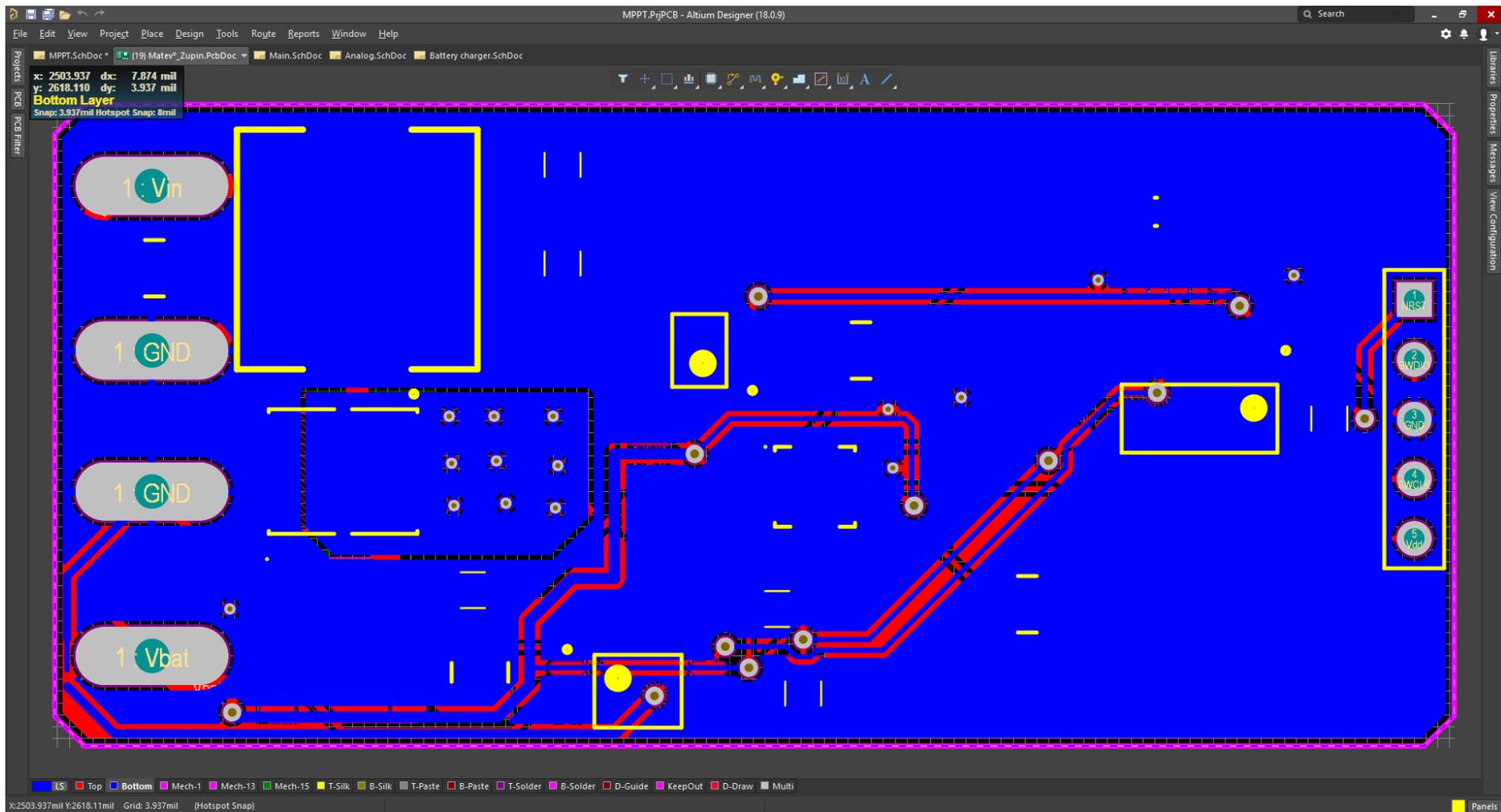


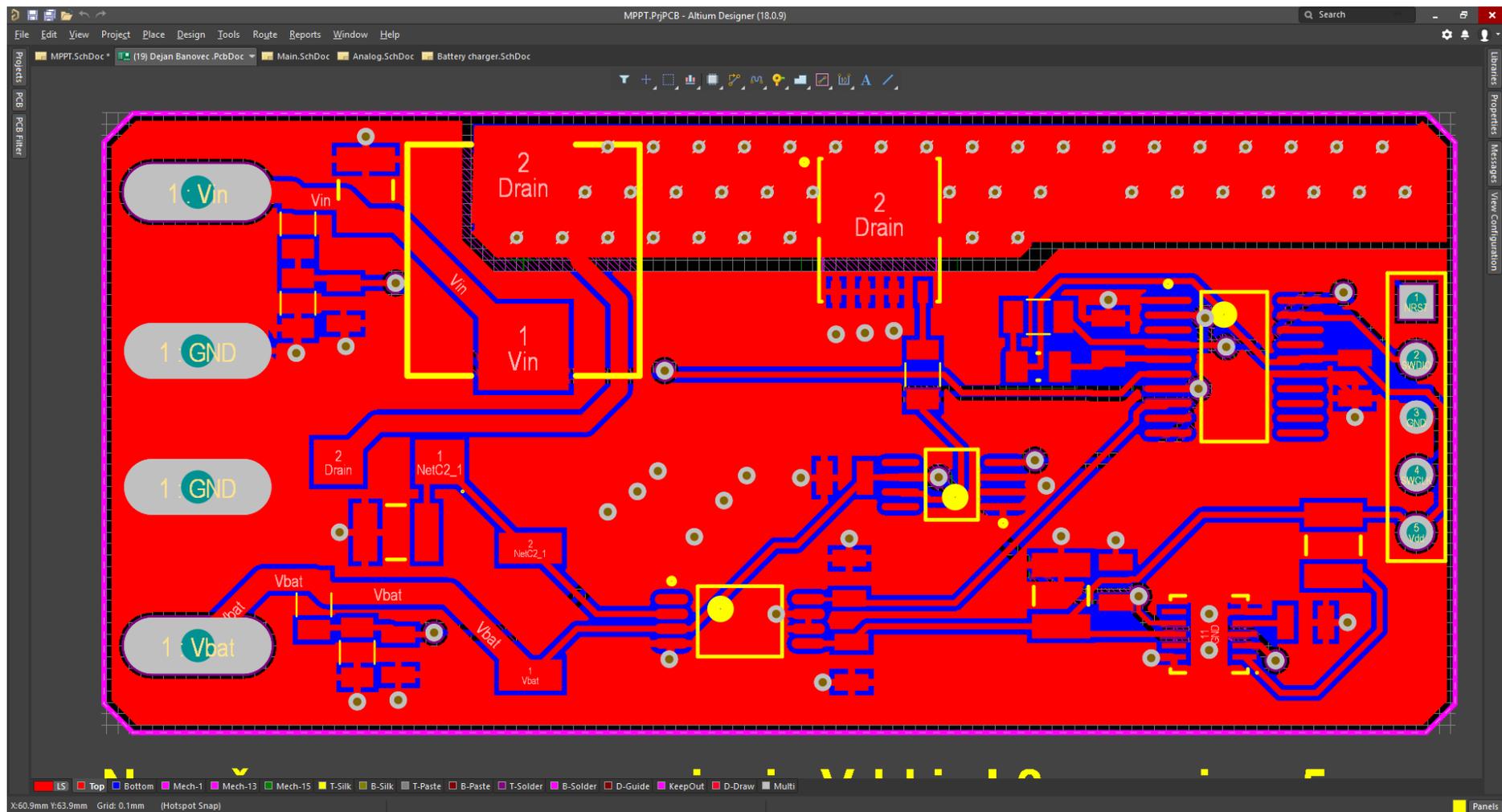


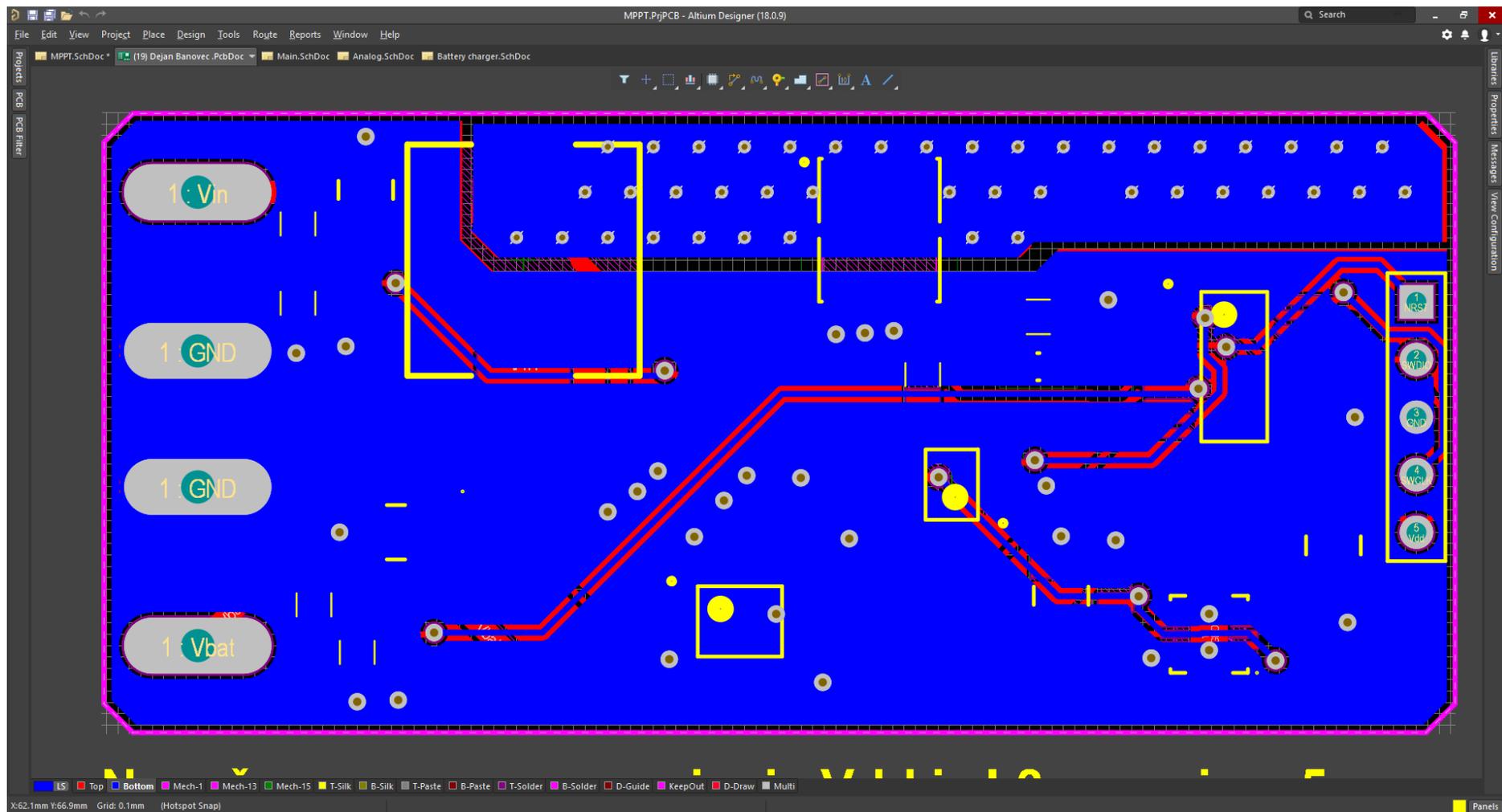


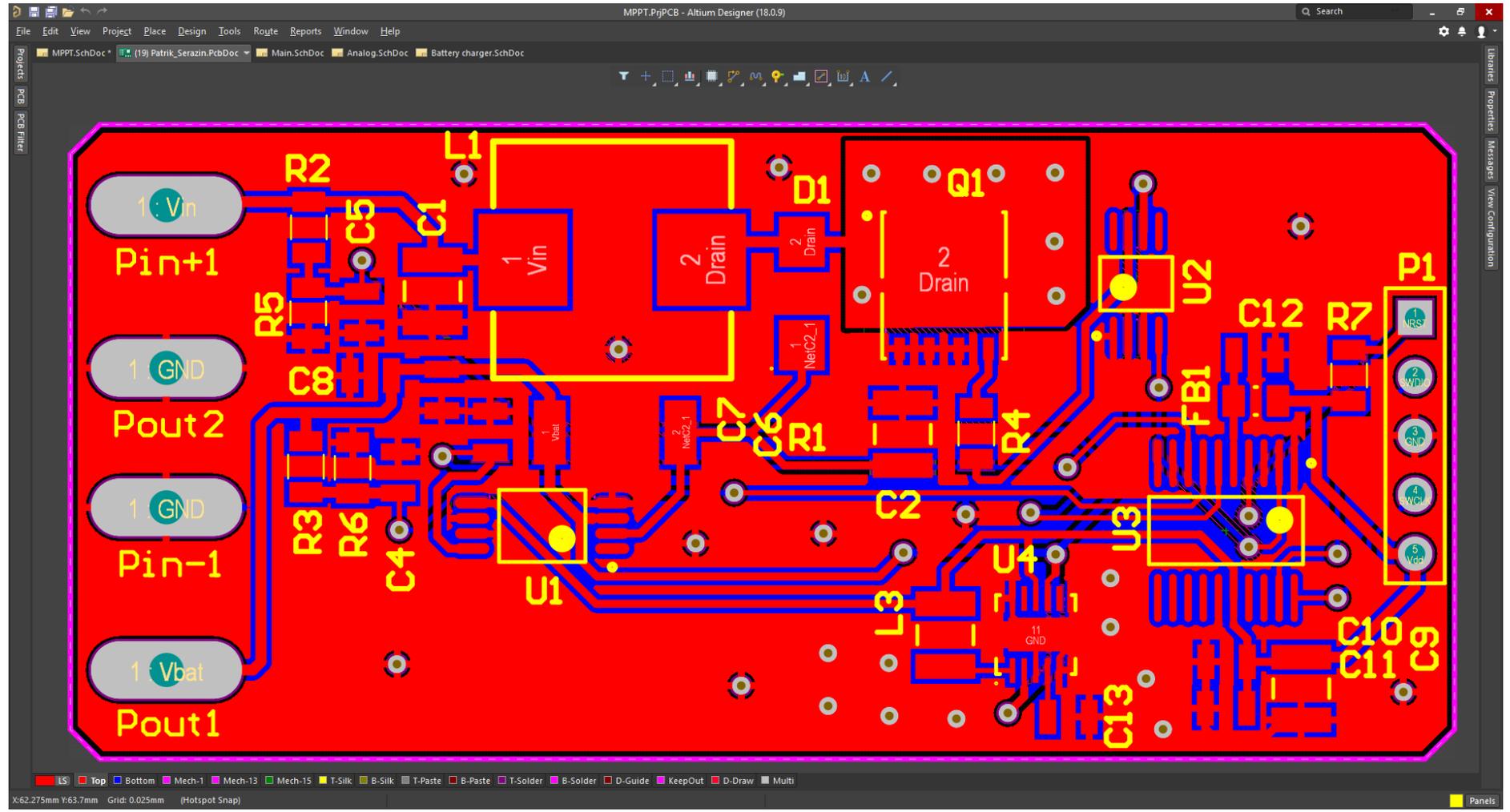


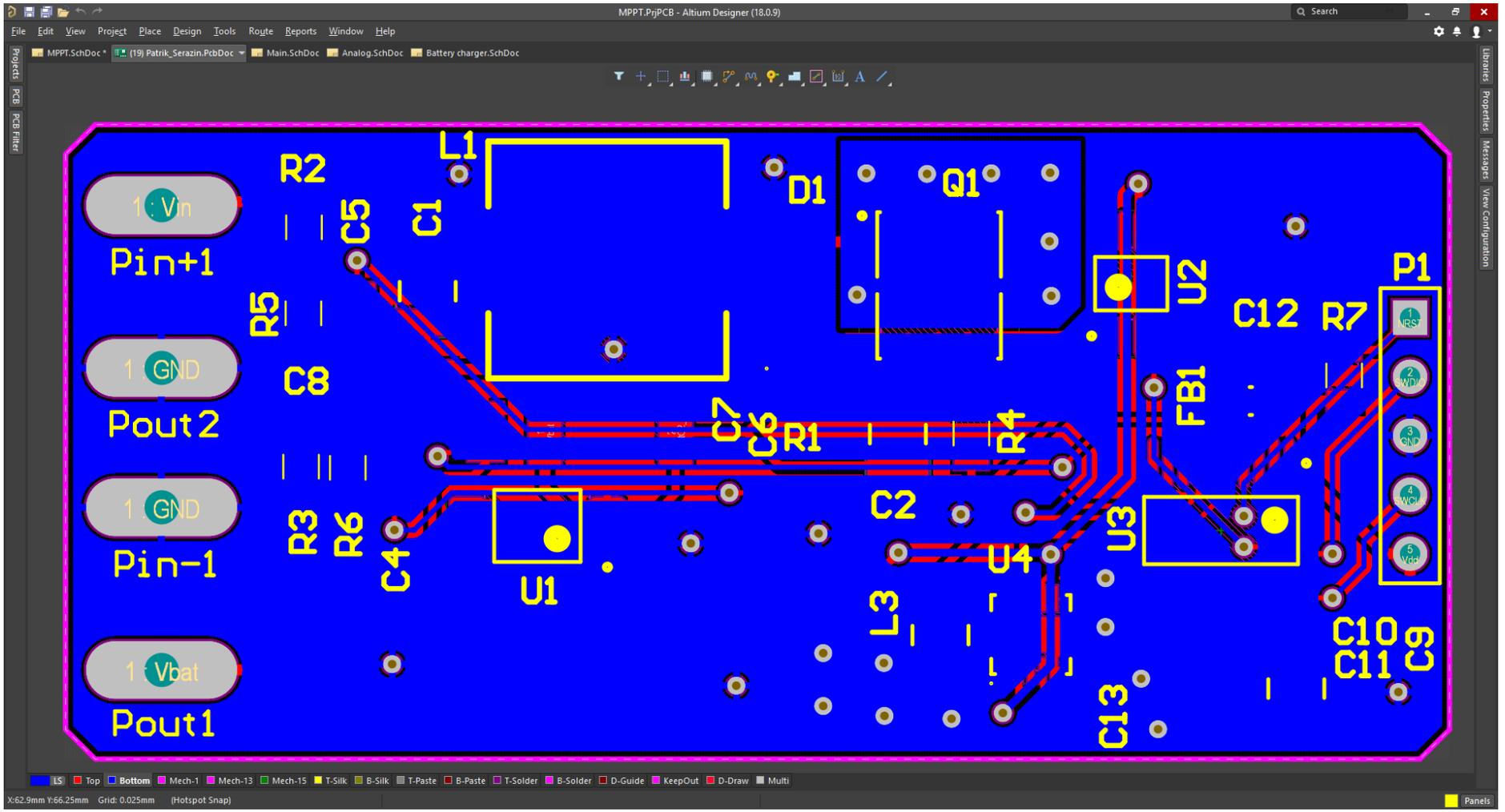


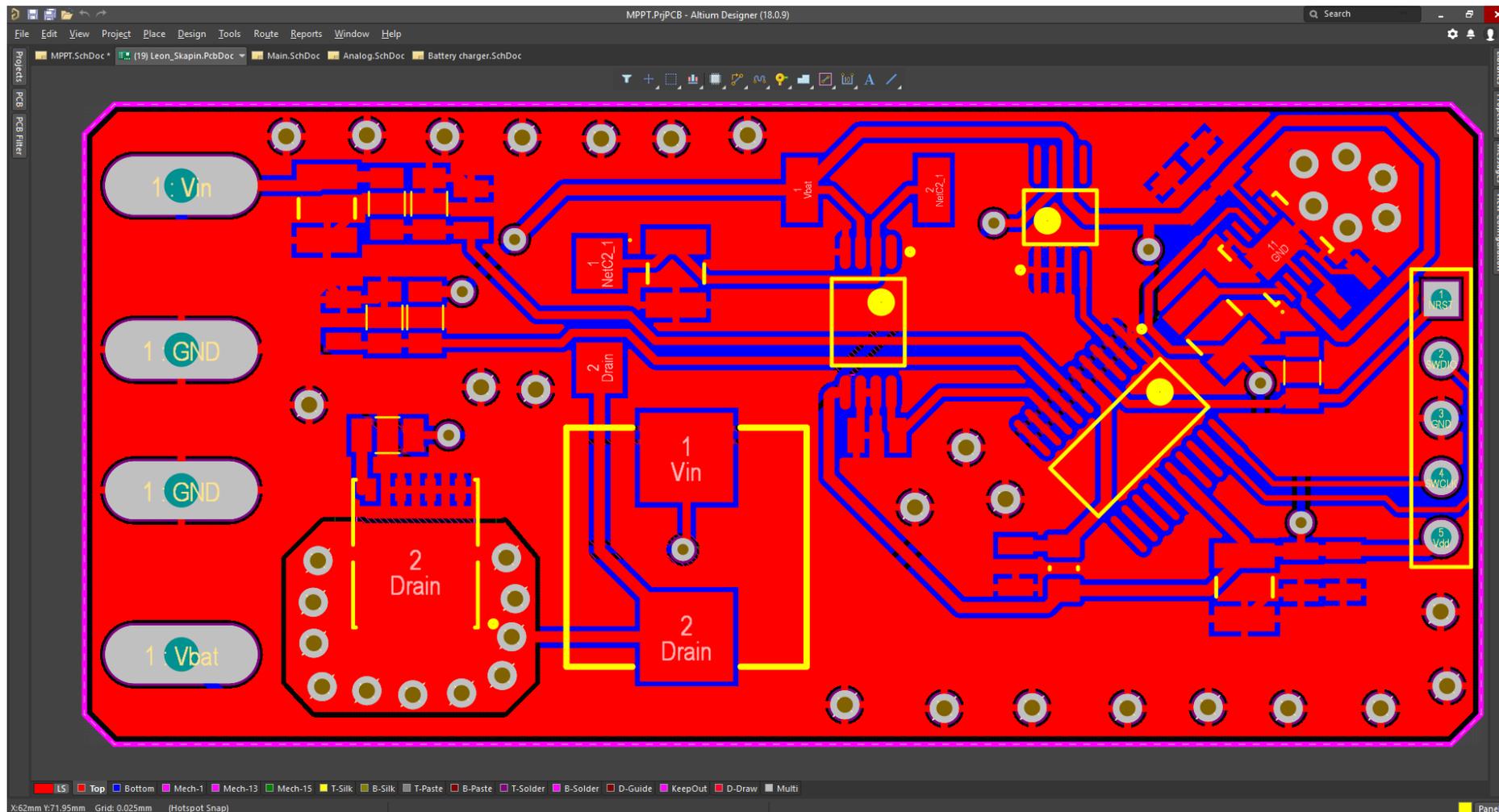












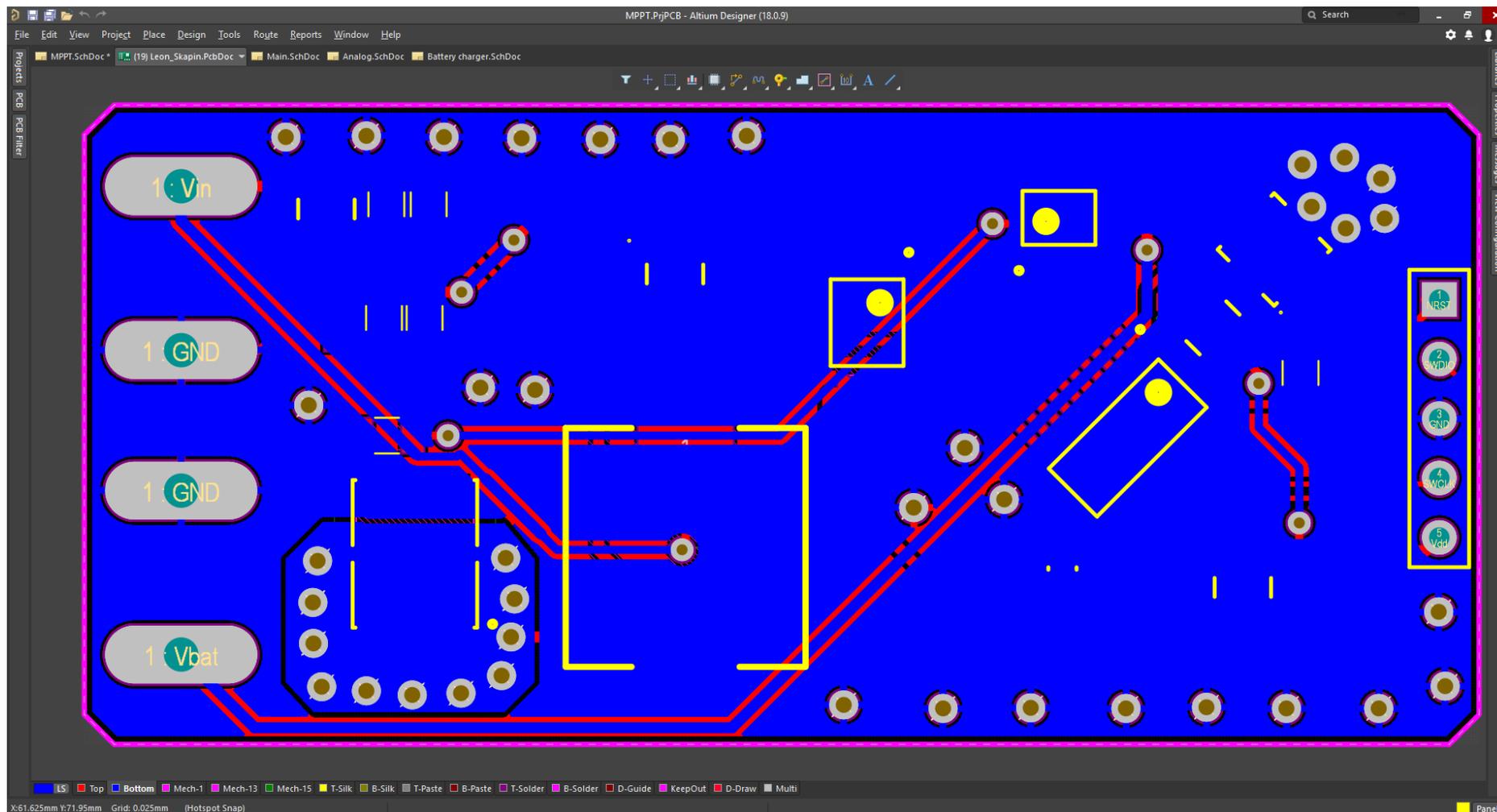
Libraries Properties Message View Configuration

- 1 VBAT
- 2 WDP
- 3 SUD
- 4 VDI
- 5 VCP

LS Top Bottom Mech-1 Mech-13 Mech-15 T-Silk B-Silk T-Paste B-Paste T-Solder B-Solder D-Guide KeepOut D-Draw Multi

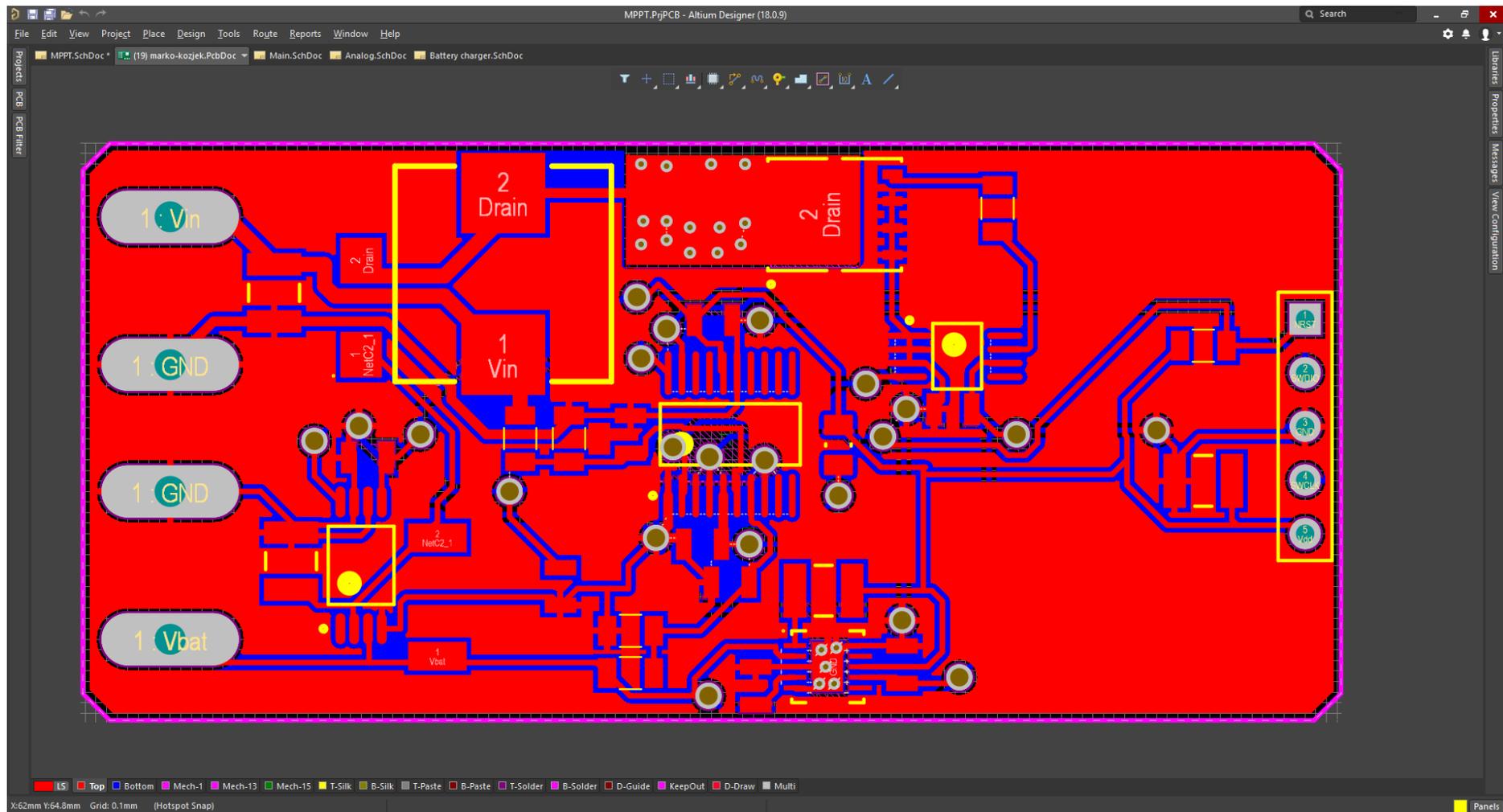
X:62mm Y:71.95mm Grid: 0.025mm (Hotspot Snap)

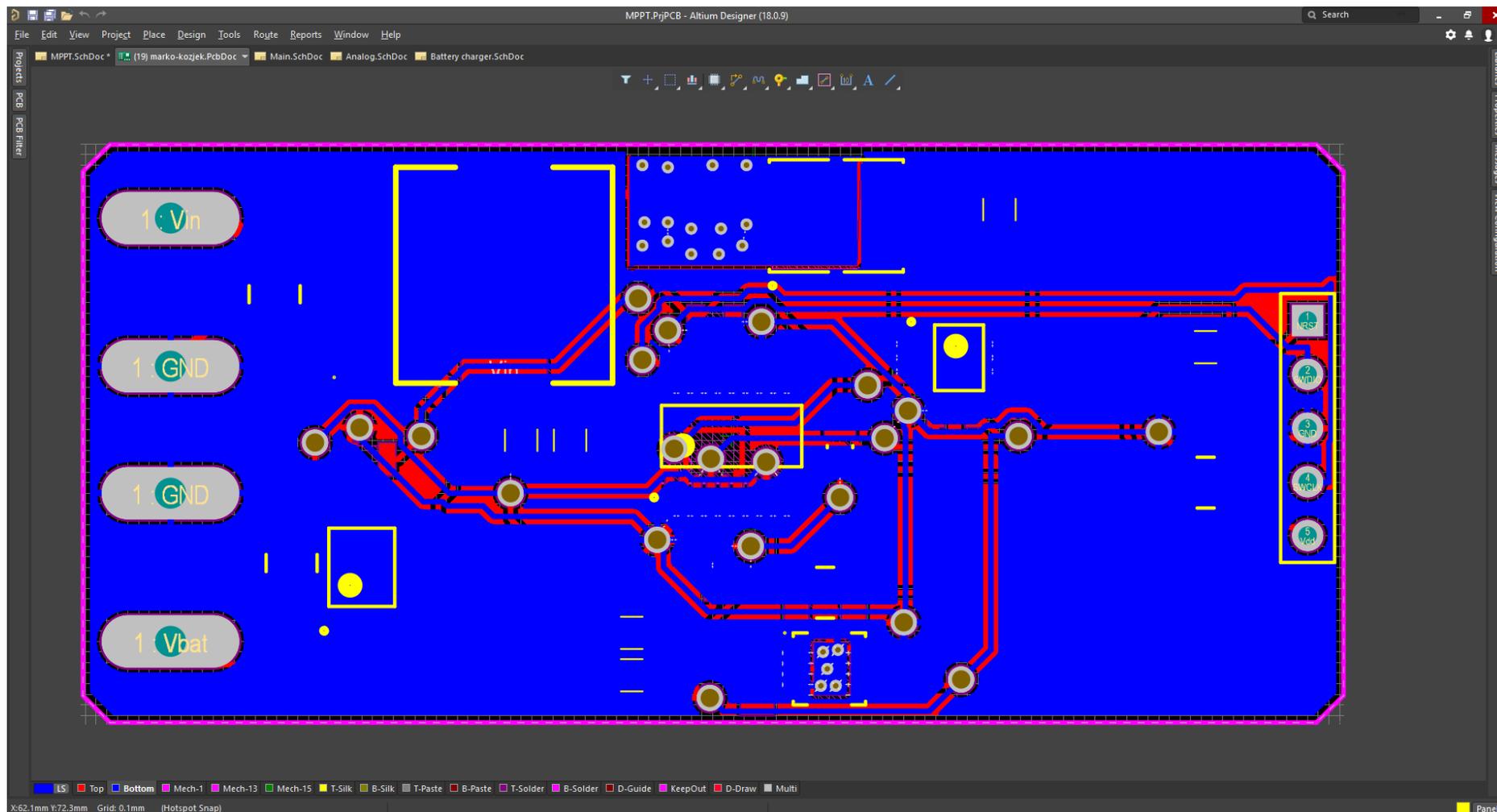
Panels



Libraries Properties Message View Configuration

Panel





Libraries Properties Messages View Configuration

Panels